

Kinetis K22F 128KB Flash

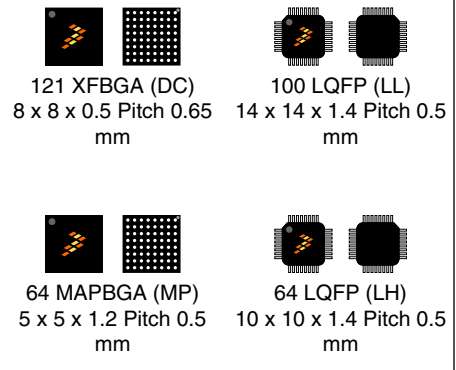
100 MHz ARM® Cortex®-M4 Based Microcontroller with FPU

The Kinetis K22 product family members are optimized for cost-sensitive applications requiring low-power, USB connectivity, high peripheral integration and processing efficiency with a floating-point unit. These devices share the comprehensive enablement and scalability of the Kinetis family.

This product offers:

- Run power consumption down to 120 μ A/MHz. Static power consumption down to 2.6 μ A with full state retention and 6 μ s wakeup. Lowest static mode down to 120 nA.
- USB LS/FS OTG 2.0 with embedded 3.3 V, USB FS device crystal-less functionality.

MK22FN128VDC10
MK22FN128VLL10
MK22FN128VMP10
MK22FN128VLH10



Performance

- 100 MHz ARM Cortex-M4 core with DSP instructions delivering 1.25 Dhrystone MIPS per MHz

Memories and memory interfaces

- 128 KB of embedded flash and 24 KB of RAM
- Serial programming interface (EzPort)
- Pre-programmed Kinetis flashloader for one-time, in-system factory programming

System peripherals

- Flexible low-power modes, multiple wakeup sources
- 4-channel DMA controller
- Independent External and Software Watchdog monitor

Clocks

- Two crystal oscillators: 32 kHz (RTC) and 32-40 kHz or 3-32 MHz
- Three internal oscillators: 32 kHz, 4 MHz, and 48 MHz
- Multi-purpose clock generator with FLL

Security and integrity modules

- Hardware CRC module
- 128-bit unique identification (ID) number per chip
- Flash access control to protect proprietary software

Human-machine interface

- Up to 67 general-purpose I/O (GPIO)

Analog modules

- Two 16-bit SAR ADCs (1.2 MS/s in 12bit mode)
- One 12-bit DAC
- Two analog comparators (CMP) with 6-bit DAC
- Accurate internal voltage reference

Communication interfaces

- USB LS/FS OTG 2.0 with on-chip transceiver
- USB full-speed device crystal-less operation
- Two SPI modules
- Three UART modules and one low-power UART
- Two I2C: Support for up to 1 Mbps operation
- I2S module

Timers

- One 8-channel general-purpose/PWM timer
- Two 2-channel general-purpose timers with quadrature decoder functionality
- Periodic interrupt timers
- 16-bit low-power timer
- Real-time clock with independent power domain
- Programmable delay block

Operating Characteristics

- Voltage range (including flash writes): 1.71 to 3.6 V
- Temperature range (ambient): -40 to 105°C

Ordering Information

| Part Number | Memory | | Number of GPIOs |
|----------------|------------|-----------|-----------------|
| | Flash (KB) | SRAM (KB) | |
| MK22FN128VDC10 | 128 | 24 | 67 |
| MK22FN128VLL10 | 128 | 24 | 66 |
| MK22FN128VMP10 | 128 | 24 | 40 |
| MK22FN128VLH10 | 128 | 24 | 40 |

Device Revision Number

| Device Mask Set Number | SIM_SDID[REVID] | JTAG ID Register[PRN] |
|------------------------|-----------------|-----------------------|
| 0N74K | 0000 | 0000 |

Related Resources

| Type | Description | Resource |
|------------------|--|---|
| Selector Guide | The NXP Solution Advisor is a web-based tool that features interactive application wizards and a dynamic product selector | KINETISKMCUSELGD |
| Product Brief | The Product Brief contains concise overview/summary information to enable quick evaluation of a device for design suitability. | K22FPB |
| Reference Manual | The Reference Manual contains a comprehensive description of the structure and function (operation) of a device. | K22P121M100SF9RM |
| Data Sheet | The Data Sheet is this document. It includes electrical characteristics and signal connections. | K22P121M100SF9 |
| Chip Errata | The chip mask set Errata provides additional or corrective information for a particular device mask set. | KINETIS_K_xN74K ¹ |
| Package drawing | Package dimensions are provided by part number: <ul style="list-style-type: none"> • MK22FN128VDC10 • MK22FN128VLL10 • MK22FN128VMP10 • MK22FN128VLH10 | Package drawing: <ul style="list-style-type: none"> • 98ASA00595D • 98ASS23308W • 98ASA00420D • 98ASS23234W |

1. To find the associated resource, go to [nxp.com](#) and perform a search using this term with the x replaced by the revision of the device you are using.

[Figure 1](#) shows the functional modules in the chip.

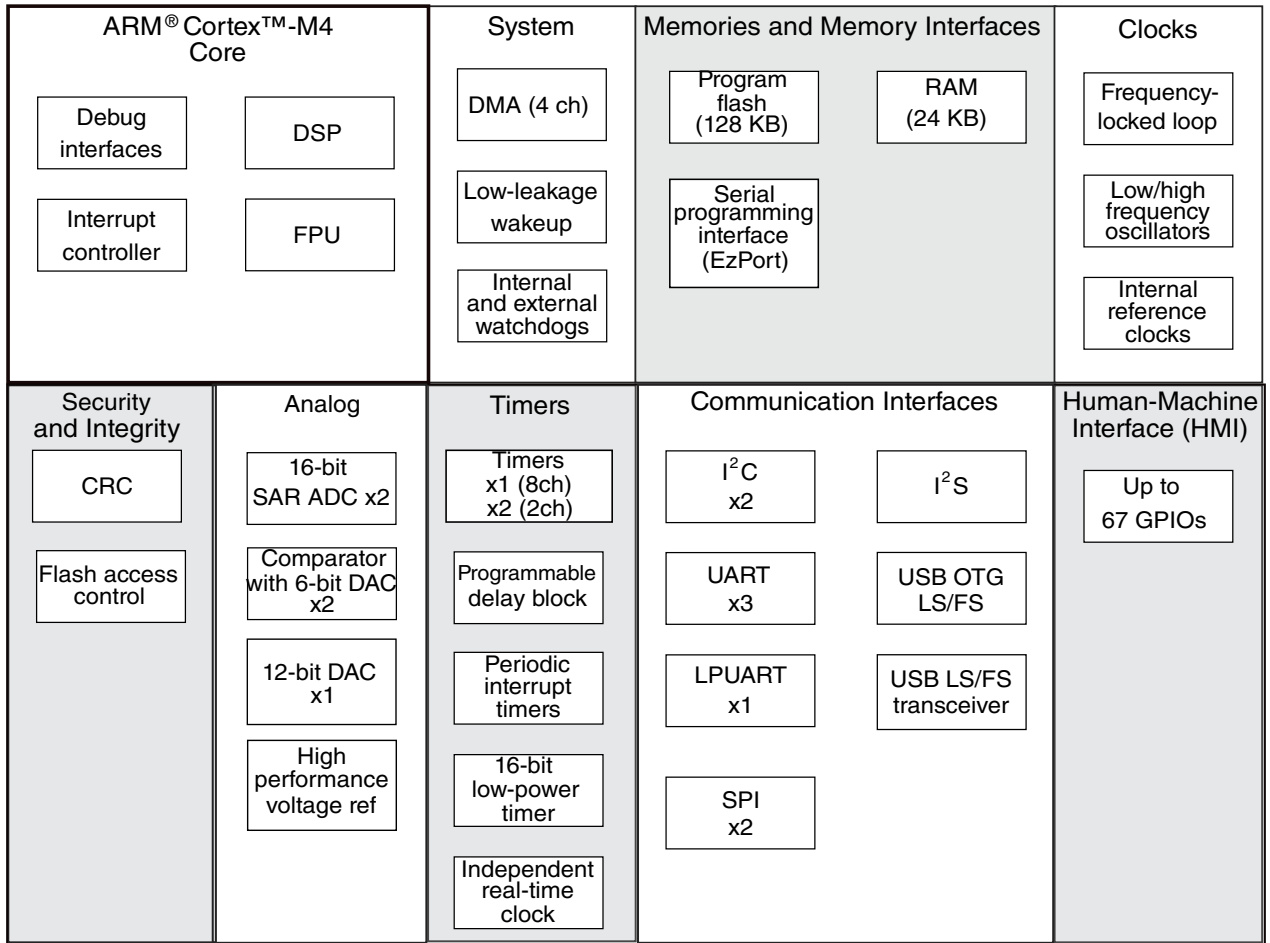


Figure 1. Functional block diagram

Table of Contents

| | | | | | |
|-------|--|----|-------|--|----|
| 1 | Ratings..... | 5 | 3.6.1 | ADC electrical specifications..... | 34 |
| 1.1 | Thermal handling ratings..... | 5 | 3.6.2 | CMP and 6-bit DAC electrical specifications..... | 38 |
| 1.2 | Moisture handling ratings..... | 5 | 3.6.3 | 12-bit DAC electrical characteristics..... | 40 |
| 1.3 | ESD handling ratings..... | 5 | 3.6.4 | Voltage reference electrical specifications..... | 43 |
| 1.4 | Voltage and current operating ratings..... | 5 | 3.7 | Timers..... | 44 |
| 2 | General..... | 6 | 3.8 | Communication interfaces..... | 44 |
| 2.1 | AC electrical characteristics..... | 6 | 3.8.1 | USB electrical specifications..... | 45 |
| 2.2 | Nonswitching electrical specifications..... | 6 | 3.8.2 | DSPI switching specifications (limited voltage range)..... | 45 |
| 2.2.1 | Voltage and current operating requirements..... | 6 | 3.8.3 | DSPI switching specifications (full voltage range)..... | 47 |
| 2.2.2 | LVD and POR operating requirements..... | 7 | 3.8.4 | Inter-Integrated Circuit Interface (I2C) timing..... | 48 |
| 2.2.3 | Voltage and current operating behaviors..... | 8 | 3.8.5 | UART switching specifications..... | 50 |
| 2.2.4 | Power mode transition operating behaviors..... | 9 | 3.8.6 | I2S/SAI switching specifications..... | 50 |
| 2.2.5 | Power consumption operating behaviors..... | 10 | 4 | Dimensions..... | 56 |
| 2.2.6 | EMC radiated emissions operating behaviors..... | 17 | 4.1 | Obtaining package dimensions..... | 56 |
| 2.2.7 | Designing with radiated emissions in mind..... | 18 | 5 | Pinout..... | 57 |
| 2.2.8 | Capacitance attributes..... | 18 | 5.1 | K22 Signal Multiplexing and Pin Assignments..... | 57 |
| 2.3 | Switching specifications..... | 18 | 5.2 | Recommended connection for unused analog and digital pins..... | 62 |
| 2.3.1 | Device clock specifications..... | 18 | 5.3 | K22 Pinouts..... | 63 |
| 2.3.2 | General switching specifications..... | 19 | 6 | Part identification..... | 67 |
| 2.4 | Thermal specifications..... | 20 | 6.1 | Description..... | 67 |
| 2.4.1 | Thermal operating requirements..... | 20 | 6.2 | Format..... | 67 |
| 2.4.2 | Thermal attributes..... | 20 | 6.3 | Fields..... | 68 |
| 3 | Peripheral operating requirements and behaviors..... | 21 | 6.4 | Example..... | 68 |
| 3.1 | Core modules..... | 21 | 6.5 | 121-pin XFBGA part marking..... | 69 |
| 3.1.1 | SWD electricals | 21 | 6.6 | 64-pin MAPBGA part marking..... | 69 |
| 3.1.2 | JTAG electricals..... | 22 | 7 | Terminology and guidelines..... | 69 |
| 3.2 | System modules..... | 25 | 7.1 | Definitions..... | 69 |
| 3.3 | Clock modules..... | 25 | 7.2 | Examples..... | 70 |
| 3.3.1 | MCG specifications..... | 25 | 7.3 | Typical-value conditions..... | 70 |
| 3.3.2 | IRC48M specifications..... | 27 | 7.4 | Relationship between ratings and operating requirements..... | 71 |
| 3.3.3 | Oscillator electrical specifications..... | 28 | 7.5 | Guidelines for ratings and operating requirements..... | 71 |
| 3.3.4 | 32 kHz oscillator electrical characteristics..... | 30 | 8 | Revision History..... | 71 |
| 3.4 | Memories and memory interfaces..... | 31 | | | |
| 3.4.1 | Flash electrical specifications..... | 31 | | | |
| 3.4.2 | EzPort switching specifications..... | 32 | | | |
| 3.5 | Security and integrity modules..... | 33 | | | |
| 3.6 | Analog..... | 33 | | | |

1 Ratings

1.1 Thermal handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|------------------|-------------------------------|------|------|------|-------|
| T _{STG} | Storage temperature | -55 | 150 | °C | 1 |
| T _{SDR} | Solder temperature, lead-free | — | 260 | °C | 2 |

1. Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
2. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

1.2 Moisture handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------|----------------------------|------|------|------|-------|
| MSL | Moisture sensitivity level | — | 3 | — | 1 |

1. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

1.3 ESD handling ratings

| Symbol | Description | Min. | Max. | Unit | Notes |
|------------------|---|-------|-------|------|-------|
| V _{HBM} | Electrostatic discharge voltage, human body model | -2000 | +2000 | V | 1 |
| V _{CDM} | Electrostatic discharge voltage, charged-device model | -500 | +500 | V | 2 |
| I _{LAT} | Latch-up current at ambient temperature of 105°C | -100 | +100 | mA | 3 |

1. Determined according to JEDEC Standard JESD22-A114, *Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)*.
2. Determined according to JEDEC Standard JESD22-C101, *Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components*.
3. Determined according to JEDEC Standard JESD78, *IC Latch-Up Test*.

1.4 Voltage and current operating ratings

General

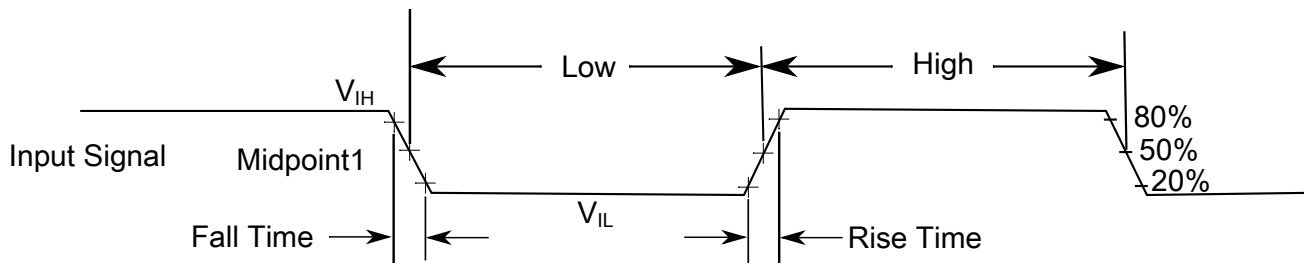
| Symbol | Description | Min. | Max. | Unit |
|----------------------|--|-----------------------|-----------------------|------|
| USBV _{DD} | USB Transceiver supply voltage | -0.3 | 3.8 | V |
| V _{DD} | Digital supply voltage | -0.3 | 3.8 | V |
| I _{DD} | Digital supply current | — | 145 | mA |
| V _{DIO} | Digital input voltage | -0.3 | V _{DD} + 0.3 | V |
| V _{AIO} | Analog ¹ | -0.3 | V _{DD} + 0.3 | V |
| I _D | Maximum current single pin limit (applies to all digital pins) | -25 | 25 | mA |
| V _{DDA} | Analog supply voltage | V _{DD} - 0.3 | V _{DD} + 0.3 | V |
| V _{USB0_DP} | USB0_DP input voltage | -0.3 | 3.63 | V |
| V _{USB0_DM} | USB0_DM input voltage | -0.3 | 3.63 | V |
| V _{BAT} | RTC battery supply voltage | -0.3 | 3.8 | V |

1. Analog pins are defined as pins that do not have an associated general purpose I/O port function.

2 General

2.1 AC electrical characteristics

Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured at the 20% and 80% points, as shown in the following figure.



The midpoint is $V_{IL} + (V_{IH} - V_{IL}) / 2$

Figure 2. Input signal measurement reference

2.2 Nonswitching electrical specifications

2.2.1 Voltage and current operating requirements

Table 1. Voltage and current operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|------------------------------------|--|---|---|--------|-------|
| V _{DD} | Supply voltage | 1.71 | 3.6 | V | |
| V _{DDA} | Analog supply voltage | 1.71 | 3.6 | V | |
| V _{DD} – V _{DDA} | V _{DD} -to-V _{DDA} differential voltage | –0.1 | 0.1 | V | |
| V _{SS} – V _{SSA} | V _{SS} -to-V _{SSA} differential voltage | –0.1 | 0.1 | V | |
| V _{BAT} | RTC battery supply voltage | 1.71 | 3.6 | V | |
| USBV _{DD} | USB Transceiver supply voltage | 3.0 | 3.6 | V | 1 |
| V _{IH} | Input high voltage <ul style="list-style-type: none"> • 2.7 V ≤ V_{DD} ≤ 3.6 V • 1.7 V ≤ V_{DD} ≤ 2.7 V | 0.7 × V _{DD} 0.75 × V _{DD} | — — | V V | |
| V _{IL} | Input low voltage <ul style="list-style-type: none"> • 2.7 V ≤ V_{DD} ≤ 3.6 V • 1.7 V ≤ V_{DD} ≤ 2.7 V | — — | 0.35 × V _{DD} 0.3 × V _{DD} | V V | |
| V _{HYS} | Input hysteresis | 0.06 × V _{DD} | — | V | |
| I _{ICIO} | Analog and I/O pin DC injection current — single pin <ul style="list-style-type: none"> • V_{IN} < V_{SS}-0.3V (Negative current injection) | -3 | — | mA | 2 |
| I _{ICcont} | Contiguous pin DC injection current — regional limit, includes sum of negative injection currents or sum of positive injection currents of 16 contiguous pins <ul style="list-style-type: none"> • Negative current injection | -25 | — | mA | |
| V _{ODPU} | Open drain pullup voltage level | V _{DD} | V _{DD} | V | 3 |
| V _{RAM} | V _{DD} voltage required to retain RAM | 1.2 | — | V | |
| V _{RFVBAT} | V _{BAT} voltage required to retain the VBAT register file | V _{POR_VBAT} | — | V | |

1. USB nominal operating voltage is 3.3 V.
2. All analog and I/O pins are internally clamped to V_{SS} through ESD protection diodes. If V_{IN} is less than V_{IO_MIN} or greater than V_{IO_MAX}, a current limiting resistor is required. The negative DC injection current limiting resistor is calculated as $R = (V_{IO_MIN} - V_{IN}) / |I_{ICIO}|$.
3. Open drain outputs must be pulled to V_{DD}.

2.2.2 LVD and POR operating requirements

Table 2. V_{DD} supply LVD and POR operating requirements

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-------------------|---|------|------|------|------|-------|
| V _{POR} | Falling V _{DD} POR detect voltage | 0.8 | 1.1 | 1.5 | V | |
| V _{LVDH} | Falling low-voltage detect threshold — high range (LVDV=01) | 2.48 | 2.56 | 2.64 | V | |

Table continues on the next page...

Table 2. V_{DD} supply LVD and POR operating requirements (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|--------------------|--|------|------|------|------|-------|
| V _{LVW1H} | Low-voltage warning thresholds — high range <ul style="list-style-type: none"> Level 1 falling (LVWV=00) Level 2 falling (LVWV=01) Level 3 falling (LVWV=10) Level 4 falling (LVWV=11) | 2.62 | 2.70 | 2.78 | V | 1 |
| V _{LVW2H} | | 2.72 | 2.80 | 2.88 | V | |
| V _{LVW3H} | | 2.82 | 2.90 | 2.98 | V | |
| V _{LVW4H} | | 2.92 | 3.00 | 3.08 | V | |
| V _{HYSH} | Low-voltage inhibit reset/recover hysteresis — high range | — | 80 | — | mV | |
| V _{LVDL} | Falling low-voltage detect threshold — low range (LVDV=00) | 1.54 | 1.60 | 1.66 | V | |
| V _{LVW1L} | Low-voltage warning thresholds — low range <ul style="list-style-type: none"> Level 1 falling (LVWV=00) Level 2 falling (LVWV=01) Level 3 falling (LVWV=10) Level 4 falling (LVWV=11) | 1.74 | 1.80 | 1.86 | V | 1 |
| V _{LVW2L} | | 1.84 | 1.90 | 1.96 | V | |
| V _{LVW3L} | | 1.94 | 2.00 | 2.06 | V | |
| V _{LVW4L} | | 2.04 | 2.10 | 2.16 | V | |
| V _{HYSL} | Low-voltage inhibit reset/recover hysteresis — low range | — | 60 | — | mV | |
| V _{BG} | Bandgap voltage reference | 0.97 | 1.00 | 1.03 | V | |
| t _{LPO} | Internal low power oscillator period — factory trimmed | 900 | 1000 | 1100 | μs | |

1. Rising threshold is the sum of falling threshold and hysteresis voltage

Table 3. VBAT power operating requirements

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------|--|------|------|------|------|-------|
| V _{POR_VBAT} | Falling VBAT supply POR detect voltage | 0.8 | 1.1 | 1.5 | V | |

2.2.3 Voltage and current operating behaviors

Table 4. Voltage and current operating behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------|---|-----------------------|------|------|------|-------|
| V _{OH} | Output high voltage — Normal drive pad except RESET_B 2.7 V ≤ V _{DD} ≤ 3.6 V, I _{OH} = -5 mA | V _{DD} - 0.5 | — | — | V | 1 |
| | | V _{DD} - 0.5 | — | — | V | |
| V _{OH} | Output high voltage — High drive pad except RESET_B 2.7 V ≤ V _{DD} ≤ 3.6 V, I _{OH} = -20 mA | V _{DD} - 0.5 | — | — | V | 1 |
| | | V _{DD} - 0.5 | — | — | V | |

Table continues on the next page...

Table 4. Voltage and current operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------|---|----------------|----------------|------------|--------------------------------|-------|
| | $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OH} = -10\text{ mA}$ | $V_{DD} - 0.5$ | — | — | V | |
| I_{OHT} | Output high current total for all ports | — | — | 100 | mA | |
| V_{OL} | Output low voltage — Normal drive pad except RESET_B $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 5\text{ mA}$ $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 2.5\text{ mA}$ | — — | — — | 0.5 0.5 | V V | 1 |
| V_{OL} | Output low voltage — High drive pad except RESET_B $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 20\text{ mA}$ $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 10\text{ mA}$ | — — | — — | 0.5 0.5 | V V | 1 |
| V_{OL} | Output low voltage — RESET_B $2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}$, $I_{OL} = 3\text{ mA}$ $1.71\text{ V} \leq V_{DD} \leq 2.7\text{ V}$, $I_{OL} = 1.5\text{ mA}$ | — — | — — | 0.5 0.5 | V V | |
| I_{OLT} | Output low current total for all ports | — | — | 100 | mA | |
| I_{IN} | Input leakage current (per pin) for full temperature range All pins other than high drive port pins High drive port pins | — — | 0.002 0.004 | 0.5 0.5 | μA μA | 1, 2 |
| I_{IN} | Input leakage current (total all pins) for full temperature range | — | — | 1.0 | μA | 2 |
| R_{PU} | Internal pullup resistors | 20 | — | 50 | $\text{k}\Omega$ | 3 |
| R_{PD} | Internal pulldown resistors | 20 | — | 50 | $\text{k}\Omega$ | 4 |

1. PTB0, PTB1, PTC3, PTC4, PTD4, PTD5, PTD6, and PTD7 I/O have both high drive and normal drive capability selected by the associated PTx_PCRn[DSE] control bit. All other GPIOs are normal drive only.
2. Measured at $V_{DD}=3.6\text{V}$
3. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{SS}$
4. Measured at V_{DD} supply voltage = V_{DD} min and $V_{input} = V_{DD}$

2.2.4 Power mode transition operating behaviors

All specifications except t_{POR} , and $VLLSx \rightarrow \text{RUN}$ recovery times in the following table assume this clock configuration:

- CPU and system clocks = 72 MHz
- Bus clock = 36 MHz
- Flash clock = 24 MHz
- MCG mode: FEI

Table 5. Power mode transition operating behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|------------------|---|------|------|------|------|-------|
| t _{POR} | After a POR event, amount of time from the point V _{DD} reaches 1.71 V to execution of the first instruction across the operating temperature range of the chip. | — | — | 300 | μs | 1 |
| | • VLLS0 → RUN | — | — | 135 | μs | |
| | • VLLS1 → RUN | — | — | 135 | μs | |
| | • VLLS2 → RUN | — | — | 75 | μs | |
| | • VLLS3 → RUN | — | — | 75 | μs | |
| | • LLS2 → RUN | — | — | 6 | μs | |
| | • LLS3 → RUN | — | — | 6 | μs | |
| | • VLPS → RUN | — | — | 5.7 | μs | |
| | • STOP → RUN | — | — | 5.7 | μs | |

1. Normal boot (FTFA_OPT[LPBOOT]=1)

2.2.5 Power consumption operating behaviors

The current parameters in the table below are derived from code executing a while(1) loop from flash, unless otherwise noted.

The IDD typical values represent the statistical mean at 25°C, and the IDD maximum values for RUN, WAIT, VLPR, and VLPW represent data collected at 125°C junction temperature unless otherwise noted. The maximum values represent characterized results equivalent to the mean plus three times the standard deviation (mean + 3 sigma).

Table 6. Power consumption operating behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------|--|------|------|----------|------|-------|
| I _{DDA} | Analog supply current | — | — | See note | mA | 1 |
| I _{DD_HSRUN} | High Speed Run mode current - all peripheral clocks disabled, CoreMark benchmark code executing from flash | | | | | |

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------|--|-----------------------|--------------------------------------|---|----------------------------|---------|
| | @ 1.8V @ 3.0V | — — | 19.51 19.51 | 20.24 20.24 | mA mA | 2, 3, 4 |
| I _{DD_HSRUN} | High Speed Run mode current - all peripheral clocks disabled, code executing from flash @ 1.8V @ 3.0V | — — | 16.9 17.0 | 17.63 17.73 | mA mA | 5 |
| I _{DD_HSRUN} | High Speed Run mode current — all peripheral clocks enabled, code executing from flash @ 1.8V @ 3.0V | — — | 22.8 22.9 | 23.53 23.63 | mA mA | 6 |
| I _{DD_RUN} | Run mode current in Compute operation — CoreMark benchmark code executing from flash @ 1.8V @ 3.0V | — — | 11.39 11.58 | 12.12 12.31 | mA mA | 2, 3, 7 |
| I _{DD_RUN} | Run mode current in Compute operation — code executing from flash @ 1.8V @ 3.0V | — — | 10.90 10.90 | 11.90 12.23 | mA mA | 7 |
| I _{DD_RUN} | Run mode current — all peripheral clocks disabled, code executing from flash @ 1.8V @ 3.0V | — — | 11.8 11.9 | 12.53 12.63 | mA mA | 8 |
| I _{DD_RUN} | Run mode current — all peripheral clocks enabled, code executing from flash @ 1.8V @ 3.0V • @ 25°C • @ 70°C • @ 85°C • @ 105°C | — — — — — | 15.5 15.6 15.6 15.6 16.3 | 16.23 16.33 16.33 16.33 17.03 | mA mA mA mA mA | 9 |
| I _{DD_RUN} | Run mode current — Compute operation, code executing from flash @ 1.8V @ 3.0V • @ 25°C • @ 70°C • @ 85°C • @ 105°C | — — — — — | 10.9 10.9 10.9 10.9 11.5 | 11.63 11.63 11.63 11.63 12.23 | mA mA mA mA mA | 10 |

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------|---|------|------|-------|------|----------|
| I _{DD_WAIT} | Wait mode high frequency current at 3.0 V — all peripheral clocks disabled | — | 6.5 | 7.23 | mA | 8 |
| I _{DD_WAIT} | Wait mode reduced frequency current at 3.0 V — all peripheral clocks disabled | — | 3.9 | 4.63 | mA | 11 |
| I _{DD_VLPR} | Very-low-power run mode current in Compute operation — CoreMark benchmark code executing from flash @ 1.8V @ 3.0V | — | 0.60 | 0.88 | mA | 2, 3, 12 |
| | | — | 0.61 | 0.89 | mA | |
| I _{DD_VLPR} | Very-low-power run mode current in Compute operation, code executing from flash @ 1.8V @ 3.0V | — | 0.48 | 0.76 | mA | 12 |
| | | — | 0.48 | 0.76 | mA | |
| I _{DD_VLPR} | Very-low-power run mode current at 3.0 V — all peripheral clocks disabled | — | 0.54 | 0.82 | mA | 13 |
| I _{DD_VLPR} | Very-low-power run mode current at 3.0 V — all peripheral clocks enabled | — | 0.79 | 1.07 | mA | 14 |
| I _{DD_VLPW} | Very-low-power wait mode current at 3.0 V — all peripheral clocks disabled | — | 0.30 | 0.59 | mA | 15 |
| I _{DD_STOP} | Stop mode current at 3.0 V @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — | 0.27 | 0.33 | mA | |
| | | — | 0.31 | 0.36 | mA | |
| | | — | 0.31 | 0.36 | mA | |
| | | — | 0.43 | 0.66 | mA | |
| I _{DD_VLPS} | Very-low-power stop mode current at 3.0 V @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — | 4.2 | 9.00 | μA | |
| | | — | 15.8 | 31.90 | μA | |
| | | — | 26.9 | 50.95 | μA | |
| | | — | 43.0 | 89.00 | μA | |
| I _{DD_LLS3} | Low leakage stop mode 3 current at 3.0 V @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — | 2.6 | 3.30 | μA | |
| | | — | 6.2 | 8.60 | μA | |
| | | — | 9.6 | 12.30 | μA | |
| | | — | 15.0 | 26.00 | μA | |
| I _{DD_LLS2} | Low leakage stop mode 2 current at 3.0 V @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — | 2.4 | 3.00 | μA | |
| | | — | 5.2 | 6.85 | μA | |
| | | — | 7.9 | 9.95 | μA | |
| | | — | 12.0 | 20.00 | μA | |
| I _{DD_VLLS3} | Very low-leakage stop mode 3 current at 3.0 V @ -40°C to 25°C | — | 1.8 | 2.10 | μA | |

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------|--|------------------|------------------------------|-------------------------------|----------------------|-------|
| | @ 70°C @ 85°C @ 105°C | — — — | 4.3 6.6 10.0 | 5.70 8.10 17.00 | μA μA μA | |
| I _{DD_VLLS2} | Very low-leakage stop mode 2 current at 3.0 V @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — — — — | 1.6 3.1 4.7 6.8 | 1.80 3.90 7.00 10.90 | μA μA μA μA | |
| I _{DD_VLLS1} | Very low-leakage stop mode 1 current at 3.0 V @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — — — — | 0.70 1.78 2.8 4.0 | 0.90 2.09 3.25 6.15 | μA μA μA μA | |
| I _{DD_VLLS0} | Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit enabled @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — — — — | 0.40 1.38 2.40 3.6 | 0.49 1.49 2.70 5.65 | μA μA μA μA | |
| I _{DD_VLLS0} | Very low-leakage stop mode 0 current at 3.0 V with POR detect circuit disabled @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — — — — | 0.12 1.05 2.1 3.3 | 0.19 1.13 2.45 5.35 | μA μA μA μA | |
| I _{DD_VBAT} | Average current with RTC and 32kHz disabled at 3.0 V @ -40°C to 25°C @ 70°C @ 85°C @ 105°C | — — — — | 0.18 0.66 1.52 2.92 | 0.21 0.86 2.24 4.30 | μA μA μA μA | |
| I _{DD_VBAT} | Average current when CPU is not accessing RTC registers @ 1.8V • @ -40°C to 25°C • @ 70°C • @ 85°C • @ 105°C @ 3.0V | — — — — | 0.57 0.90 0.90 2.4 | 0.67 1.2 1.2 3.5 | μA μA μA μA | 16 |

Table continues on the next page...

Table 6. Power consumption operating behaviors (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|--------|-------------------|------|------|------|------|-------|
| | • @ -40°C to 25°C | — | 0.67 | 0.94 | μA | |
| | • @ 70°C | — | 1.0 | 1.4 | μA | |
| | • @ 85°C | — | 1.0 | 1.4 | μA | |
| | • @ 105°C | — | 2.7 | 3.9 | μA | |

- The analog supply current is the sum of the active or disabled current for each of the analog modules on the device. See each module's specification for its supply current.
- Cache on and prefetch on, low compiler optimization.
- Coremark benchmark compiled using IAR 7.2 with optimization level low.
- 100 MHz core and system clock, 50 MHz bus clock, and 25 MHz flash clock. MCG configured for FEE mode. All peripheral clocks disabled.
- 100MHz core and system clock, 50MHz bus clock, and 25MHz flash clock. MCG configured for FEI mode. All peripheral clocks disabled.
- 100MHz core and system clock, 50MHz bus clock, and 25MHz flash clock. MCG configured for FEI mode. All peripheral clocks enabled.
- 72 MHz core and system clock, 36 MHz bus clock, and 24 MHz flash clock. MCG configured for FEE mode. All peripheral clocks disabled. Compute operation.
- 72MHz core and system clock, 36MHz bus clock, and 24MHz flash clock. MCG configured for FEI mode. All peripheral clocks disabled.
- 72MHz core and system clock, 36MHz bus clock, and 24MHz flash clock. MCG configured for FEI mode. All peripheral clocks enabled.
- 72MHz core and system clock, 36MHz bus clock, and 24MHz flash clock. MCG configured for FEI mode. Compute Operation.
- 25MHz core and system clock, 25MHz bus clock, and 25MHz flash clock. MCG configured for FEI mode.
- 4 MHz core, system, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. Compute Operation. Code executing from flash.
- 4 MHz core, system, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled. Code executing from flash.
- 4 MHz core, system, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks enabled but peripherals are not in active operation. Code executing from flash.
- 4 MHz core, system, and bus clock and 1MHz flash clock. MCG configured for BLPE mode. All peripheral clocks disabled.
- Includes 32kHz oscillator current and RTC operation.

Table 7. Low power mode peripheral adders—typical value

| Symbol | Description | Temperature (°C) | | | | | | Unit |
|----------------------------|--|------------------|-----|-----|-----|-----|-----|------|
| | | -40 | 25 | 50 | 70 | 85 | 105 | |
| I _{IREFSTEN4MHZ} | 4 MHz internal reference clock (IRC) adder. Measured by entering STOP or VLPS mode with 4 MHz IRC enabled. | 56 | 56 | 56 | 56 | 56 | 56 | μA |
| I _{IREFSTEN32KHZ} | 32 kHz internal reference clock (IRC) adder. Measured by entering STOP mode with the 32 kHz IRC enabled. | 52 | 52 | 52 | 52 | 52 | 52 | μA |
| I _{EREFSTEN4MHZ} | External 4 MHz crystal clock adder. Measured by entering STOP or VLPS mode with the crystal enabled. | 206 | 228 | 237 | 245 | 251 | 258 | uA |

Table continues on the next page...

Table 7. Low power mode peripheral adders—typical value (continued)

| Symbol | Description | Temperature (°C) | | | | | | Unit |
|----------------------------|--|------------------|-----|-----|-----|-----|-----|------|
| | | -40 | 25 | 50 | 70 | 85 | 105 | |
| I _{EREFSTEN32KHZ} | External 32 kHz crystal clock adder by means of the OSC0_CR[EREFSTEN and EREFSTEN] bits. Measured by entering all modes with the crystal enabled. | | | | | | | |
| | VLLS1 | 440 | 490 | 540 | 560 | 570 | 580 | nA |
| | VLLS3 | 440 | 490 | 540 | 560 | 570 | 580 | |
| | LLS | 490 | 490 | 540 | 560 | 570 | 680 | |
| | VLPS | 510 | 560 | 560 | 560 | 610 | 680 | |
| | STOP | 510 | 560 | 560 | 560 | 610 | 680 | |
| I _{48MIRC} | 48 Mhz internal reference clock | 350 | 350 | 350 | 350 | 350 | 350 | μA |
| I _{CMP} | CMP peripheral adder measured by placing the device in VLLS1 mode with CMP enabled using the 6-bit DAC and a single external input for compare. Includes 6-bit DAC power consumption. | 22 | 22 | 22 | 22 | 22 | 22 | μA |
| I _{RTC} | RTC peripheral adder measured by placing the device in VLLS1 mode with external 32 kHz crystal enabled by means of the RTC_CR[OSCE] bit and the RTC ALARM set for 1 minute. Includes ERCLK32K (32 kHz external crystal) power consumption. | 432 | 357 | 388 | 475 | 532 | 810 | nA |
| I _{UART} | UART peripheral adder measured by placing the device in STOP or VLPS mode with selected clock source waiting for RX data at 115200 baud rate. Includes selected clock source power consumption. | | | | | | | |
| | MCGIRCLK (4 MHz internal reference clock) | 66 | 66 | 66 | 66 | 66 | 66 | μA |
| | >OSCERCLK (4 MHz external crystal) | 214 | 237 | 246 | 254 | 260 | 268 | |
| I _{BG} | Bandgap adder when BGEN bit is set and device is placed in VLPx, LLS, or VLLSx mode. | 45 | 45 | 45 | 45 | 45 | 45 | μA |
| I _{ADC} | ADC peripheral adder combining the measured values at V _{DD} and V _{DDA} by placing the device in STOP or VLPS mode. ADC is configured for low power mode using the internal clock and continuous conversions. | 42 | 42 | 42 | 42 | 42 | 42 | μA |

2.2.5.1 Diagram: Typical IDD_RUN operating behavior

The following data was measured under these conditions:

- MCG in FBE mode for 50 MHz and lower frequencies. MCG in FEE mode at frequencies between 50 MHz and 100MHz.
- No GPIOs toggled
- Code execution from flash with cache enabled
- For the ALLOFF curve, all peripheral clocks are disabled except FTFA

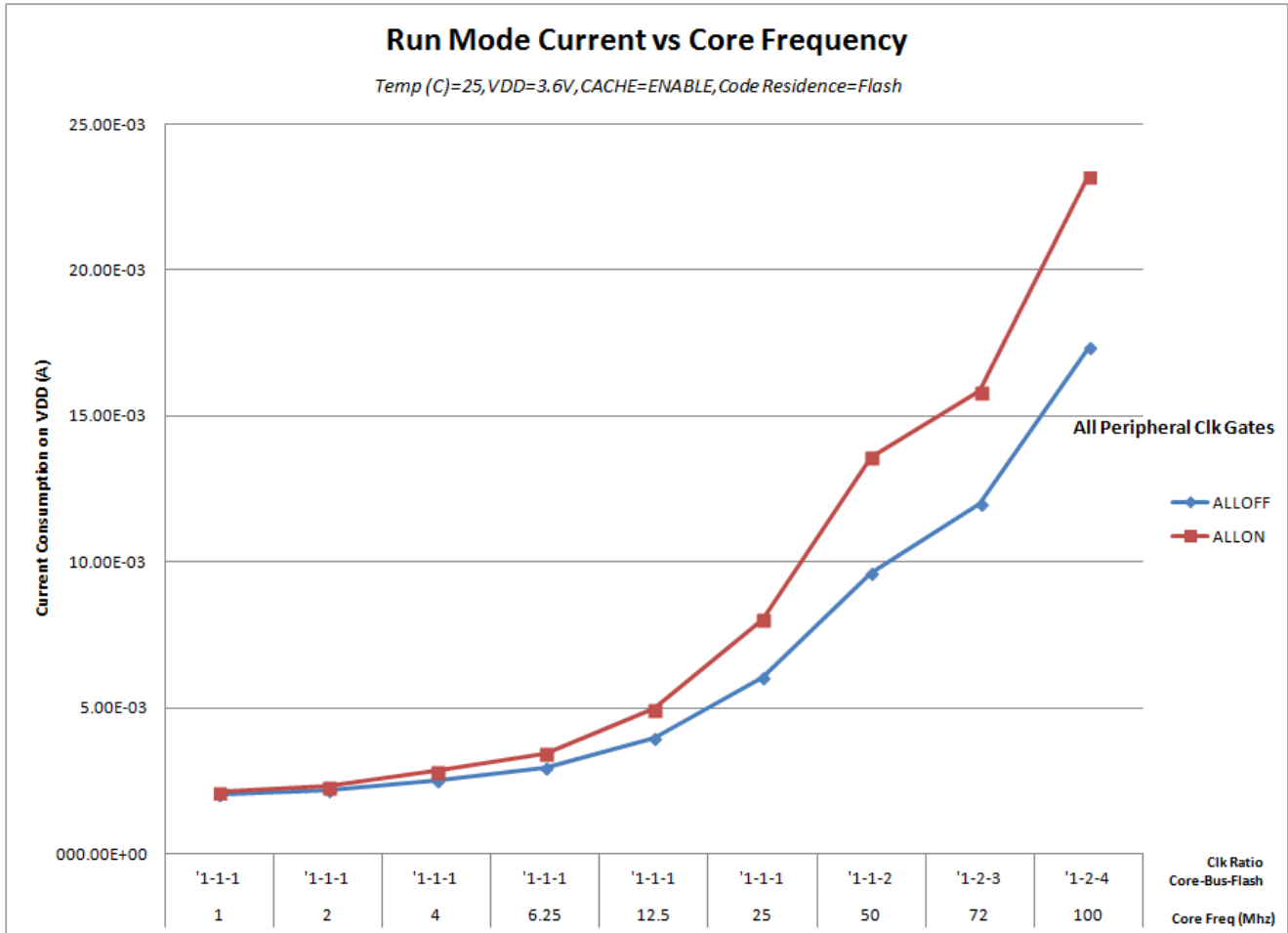


Figure 3. Run mode supply current vs. core frequency

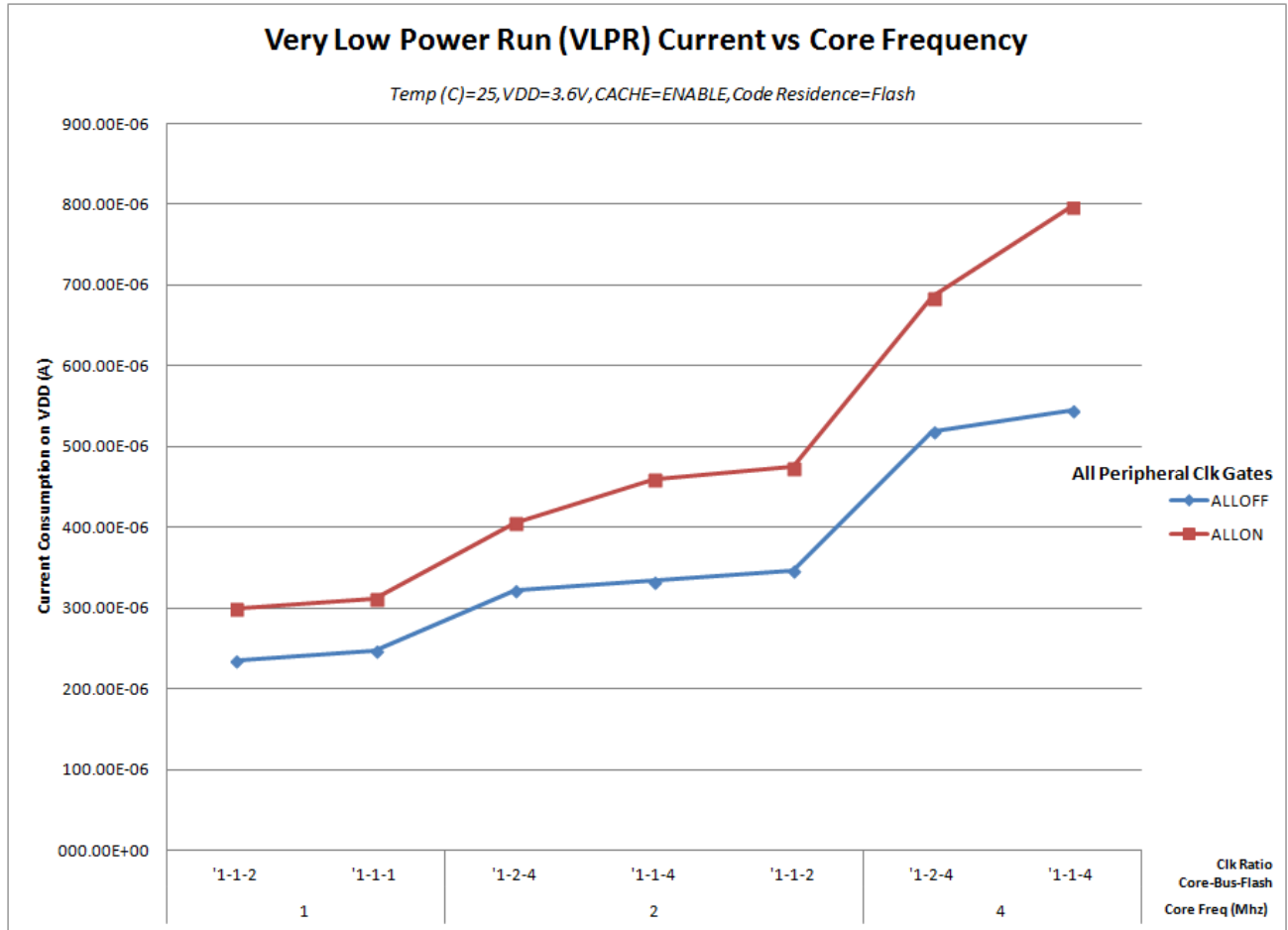


Figure 4. VLPR mode supply current vs. core frequency

2.2.6 EMC radiated emissions operating behaviors

Table 8. EMC radiated emissions operating behaviors for 64 LQFP package

| Parameter | Conditions | Clocks | Frequency range | Level (Typ.) | Unit | Notes |
|------------------|---|--|------------------|--------------|------|---------|
| V _{EME} | Device configuration, test conditions and EM testing per standard IEC 61967-2. Supply voltages: Temp = 25°C | FSYS = 100 MHz FBUS = 50 MHz External crystal = 10 MHz | 150 kHz–50 MHz | 13 | dBuV | 1, 2, 3 |
| | | | 50 MHz–150 MHz | 24 | | |
| | | | 150 MHz–500 MHz | 23 | | |
| | | | 500 MHz–1000 MHz | 7 | | |
| | | | IEC level | L | | 4 |

1. Measurements were made per IEC 61967-2 while the device was running typical application code.
2. Measurements were performed on the 64LQFP device, MK22FN128VLH10 .
3. The reported emission level is the value of the maximum measured emission, rounded up to the next whole number, from among the measured orientations in each frequency range.
4. IEC Level Maximums: M ≤ 18dBmV, L ≤ 24dBmV, K ≤ 30dBmV, I ≤ 36dBmV, H ≤ 42dBmV .

2.2.7 Designing with radiated emissions in mind

To find application notes that provide guidance on designing your system to minimize interference from radiated emissions:

- Go to nxp.com
- Perform a keyword search for “EMC design.”

2.2.8 Capacitance attributes

Table 9. Capacitance attributes

| Symbol | Description | Min. | Max. | Unit |
|-------------------|---------------------------------|------|------|------|
| C _{IN_A} | Input capacitance: analog pins | — | 7 | pF |
| C _{IN_D} | Input capacitance: digital pins | — | 7 | pF |

2.3 Switching specifications

2.3.1 Device clock specifications

Table 10. Device clock specifications

| Symbol | Description | Min. | Max. | Unit | Notes |
|--|--|------|------|------|-------|
| High Speed run mode | | | | | |
| f _{sys} | System and core clock | — | 100 | MHz | |
| f _{bus} | Bus clock | — | 50 | MHz | |
| Normal run mode (and High Speed run mode unless otherwise specified above) | | | | | |
| f _{sys} | System and core clock | — | 72 | MHz | |
| f _{sys_usb} | System and core clock when Full Speed USB in operation | 20 | — | MHz | |
| f _{bus} | Bus clock | — | 50 | MHz | |
| f _{flash} | Flash clock | — | 25 | MHz | |
| f _{lptmr} | LPTMR clock | — | 25 | MHz | |
| VLPR mode ¹ | | | | | |
| f _{sys} | System and core clock | — | 4 | MHz | |
| f _{bus} | Bus clock | — | 4 | MHz | |
| f _{flash} | Flash clock | — | 1 | MHz | |
| f _{erclk} | External reference clock | — | 16 | MHz | |

Table continues on the next page...

Table 10. Device clock specifications (continued)

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------------------|--------------------------------|------|------|------|-------|
| f_{LPTMR_pin} | LPTMR clock | — | 25 | MHz | |
| f_{LPTMR_ERCLK} | LPTMR external reference clock | — | 16 | MHz | |
| f_{I2S_MCLK} | I2S master clock | — | 12.5 | MHz | |
| f_{I2S_BCLK} | I2S bit clock | — | 4 | MHz | |

1. The frequency limitations in VLPR mode here override any frequency specification listed in the timing specification for any other module.

2.3.2 General switching specifications

These general purpose specifications apply to all signals configured for GPIO, UART, and timers.

Table 11. General switching specifications

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------|---|------------------|---------------------|----------------------|-------|
| | GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path | 1.5 | — | Bus clock cycles | 1, 2 |
| | External RESET and NMI pin interrupt pulse width — Asynchronous path | 100 | — | ns | 3 |
| | GPIO pin interrupt pulse width (digital glitch filter disabled, passive filter disabled) — Asynchronous path | 50 | — | ns | 4 |
| | Mode select (EZP_CS) hold time after reset deassertion | 2 | — | Bus clock cycles | |
| | Port rise and fall time <ul style="list-style-type: none"> • Slew disabled <ul style="list-style-type: none"> • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$ • Slew enabled <ul style="list-style-type: none"> • $1.71 \leq V_{DD} \leq 2.7V$ • $2.7 \leq V_{DD} \leq 3.6V$ | — — — — | 10 5 30 16 | ns ns ns ns | 5 |

1. This is the minimum pulse width that is guaranteed to pass through the pin synchronization circuitry. Shorter pulses may or may not be recognized. In Stop, VLPS, LLS, and VLLSx modes, the synchronizer is bypassed so shorter pulses can be recognized in that case.
2. The greater of synchronous and asynchronous timing must be met.
3. These pins have a passive filter enabled on the inputs. This is the shortest pulse width that is guaranteed to be recognized.
4. These pins do not have a passive filter on the inputs. This is the shortest pulse width that is guaranteed to be recognized.
5. 25 pF load

2.4 Thermal specifications

2.4.1 Thermal operating requirements

Table 12. Thermal operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------|--------------------------|------|------|------|-------|
| T_J | Die junction temperature | -40 | 125 | °C | |
| T_A | Ambient temperature | -40 | 105 | °C | 1 |

1. Maximum T_A can be exceeded only if the user ensures that T_J does not exceed maximum T_J . The simplest method to determine T_J is: $T_J = T_A + R_{\theta JA} \times \text{chip power dissipation}$.

2.4.2 Thermal attributes

| Board type | Symbol | Description | 121 XFBGA | 100 LQFP | 64 LQFP | 64 MAPBGA | Unit | Notes |
|-------------------|------------------|--|-----------|----------|---------|-----------|------|-------|
| Single-layer (1s) | $R_{\theta JA}$ | Thermal resistance, junction to ambient (natural convection) | 46.6 | 63 | 69 | 53.8 | °C/W | 1 |
| Four-layer (2s2p) | $R_{\theta JA}$ | Thermal resistance, junction to ambient (natural convection) | 39.3 | 50 | 51 | 46.0 | °C/W | 2 |
| Single-layer (1s) | $R_{\theta JMA}$ | Thermal resistance, junction to ambient (200 ft./min. air speed) | 39.0 | 53 | 57 | 45.8 | °C/W | 3 |
| Four-layer (2s2p) | $R_{\theta JMA}$ | Thermal resistance, junction to ambient (200 ft./min. air speed) | 35.3 | 44 | 44 | 41.0 | °C/W | 3 |
| — | $R_{\theta JB}$ | Thermal resistance, junction to board | 36.7 | 36 | 33 | 43.4 | °C/W | 4 |

Table continues on the next page...

| Board type | Symbol | Description | 121 XFBGA | 100 LQFP | 64 LQFP | 64 MAPBGA | Unit | Notes |
|------------|-----------------|---|-----------|----------|---------|-----------|------|-------|
| — | $R_{\theta JC}$ | Thermal resistance, junction to case | 11.5 | 18 | 18 | 25.7 | °C/W | 5 |
| — | Ψ_{JT} | Thermal characterization parameter, junction to package top outside center (natural convection) | 0.9 | 3 | 3 | 0.4 | °C/W | 6 |

1. Determined according to JEDEC Standard JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions—Natural Convection (Still Air)* with the single layer board horizontal. Board meets JESD51-9 specification.
2. Determined according to JEDEC Standard JESD51-2, *Integrated Circuits Thermal Test Method Environmental Conditions—Natural Convection (Still Air)*.
3. Determined according to JEDEC Standard JESD51-6, *Integrated Circuits Thermal Test Method Environmental Conditions—Forced Convection (Moving Air)* with the board horizontal.
4. Determined according to JEDEC Standard JESD51-8, *Integrated Circuit Thermal Test Method Environmental Conditions—Junction-to-Board*.
5. Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).
6. Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2.

3 Peripheral operating requirements and behaviors

3.1 Core modules

3.1.1 SWD electricals

Table 13. SWD full voltage range electricals

| Symbol | Description | Min. | Max. | Unit |
|--------|--|------|------|------|
| | Operating voltage | 1.71 | 3.6 | V |
| S1 | SWD_CLK frequency of operation <ul style="list-style-type: none"> • Serial wire debug | 0 | 33 | MHz |
| S2 | SWD_CLK cycle period | 1/S1 | — | ns |
| S3 | SWD_CLK clock pulse width <ul style="list-style-type: none"> • Serial wire debug | 15 | — | ns |

Table continues on the next page...

Table 13. SWD full voltage range electricals (continued)

| Symbol | Description | Min. | Max. | Unit |
|--------|---|------|------|------|
| S4 | SWD_CLK rise and fall times | — | 3 | ns |
| S9 | SWD_DIO input data setup time to SWD_CLK rise | 8 | — | ns |
| S10 | SWD_DIO input data hold time after SWD_CLK rise | 1.4 | — | ns |
| S11 | SWD_CLK high to SWD_DIO data valid | — | 25 | ns |
| S12 | SWD_CLK high to SWD_DIO high-Z | 5 | — | ns |

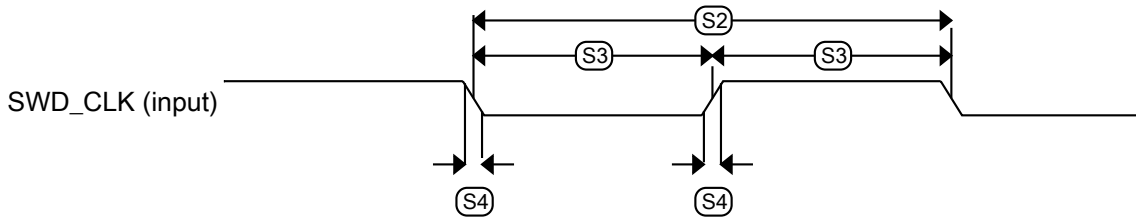


Figure 5. Serial wire clock input timing

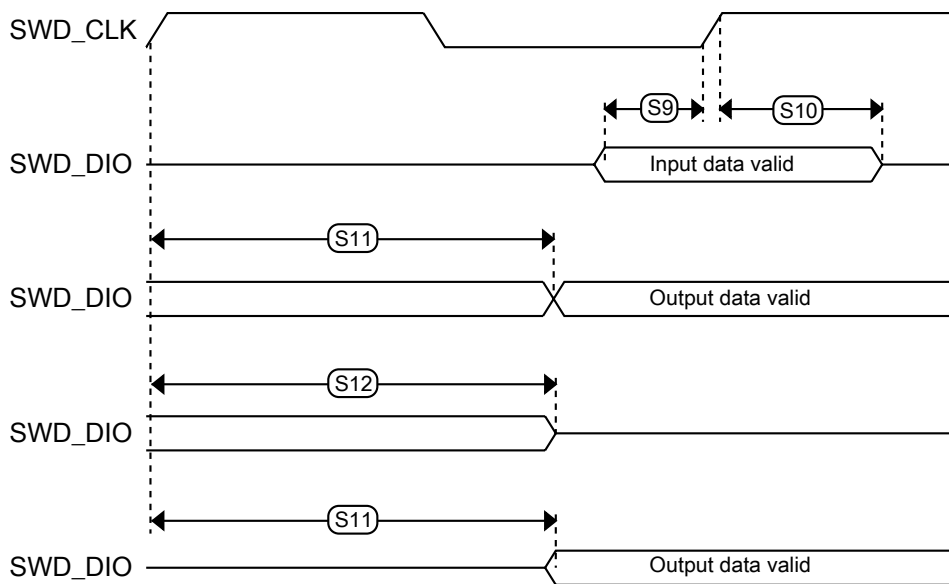


Figure 6. Serial wire data timing

3.1.2 JTAG electricals

Table 14. JTAG limited voltage range electricals

| Symbol | Description | Min. | Max. | Unit |
|--------|---|----------|----------|----------|
| | Operating voltage | 2.7 | 3.6 | V |
| J1 | TCLK frequency of operation <ul style="list-style-type: none"> • Boundary Scan • JTAG and CJTAG | 0 0 | 10 20 | MHz |
| J2 | TCLK cycle period | 1/J1 | — | ns |
| J3 | TCLK clock pulse width <ul style="list-style-type: none"> • Boundary Scan • JTAG and CJTAG | 50 25 | — — | ns ns |
| J4 | TCLK rise and fall times | — | 3 | ns |
| J5 | Boundary scan input data setup time to TCLK rise | 20 | — | ns |
| J6 | Boundary scan input data hold time after TCLK rise | 1 | — | ns |
| J7 | TCLK low to boundary scan output data valid | — | 25 | ns |
| J8 | TCLK low to boundary scan output high-Z | — | 25 | ns |
| J9 | TMS, TDI input data setup time to TCLK rise | 8 | — | ns |
| J10 | TMS, TDI input data hold time after TCLK rise | 1 | — | ns |
| J11 | TCLK low to TDO data valid | — | 19 | ns |
| J12 | TCLK low to TDO high-Z | — | 19 | ns |
| J13 | $\overline{\text{TRST}}$ assert time | 100 | — | ns |
| J14 | $\overline{\text{TRST}}$ setup time (negation) to TCLK high | 8 | — | ns |

Table 15. JTAG full voltage range electricals

| Symbol | Description | Min. | Max. | Unit |
|--------|---|----------|----------|----------|
| | Operating voltage | 1.71 | 3.6 | V |
| J1 | TCLK frequency of operation <ul style="list-style-type: none"> • Boundary Scan • JTAG and CJTAG | 0 0 | 10 15 | MHz |
| J2 | TCLK cycle period | 1/J1 | — | ns |
| J3 | TCLK clock pulse width <ul style="list-style-type: none"> • Boundary Scan • JTAG and CJTAG | 50 33 | — — | ns ns |
| J4 | TCLK rise and fall times | — | 3 | ns |
| J5 | Boundary scan input data setup time to TCLK rise | 20 | — | ns |
| J6 | Boundary scan input data hold time after TCLK rise | 1.4 | — | ns |
| J7 | TCLK low to boundary scan output data valid | — | 27 | ns |

Table continues on the next page...

Table 15. JTAG full voltage range electricals (continued)

| Symbol | Description | Min. | Max. | Unit |
|--------|---|------|------|------|
| J8 | TCLK low to boundary scan output high-Z | — | 27 | ns |
| J9 | TMS, TDI input data setup time to TCLK rise | 8 | — | ns |
| J10 | TMS, TDI input data hold time after TCLK rise | 1.4 | — | ns |
| J11 | TCLK low to TDO data valid | — | 26.2 | ns |
| J12 | TCLK low to TDO high-Z | — | 26.2 | ns |
| J13 | TRST assert time | 100 | — | ns |
| J14 | TRST setup time (negation) to TCLK high | 8 | — | ns |

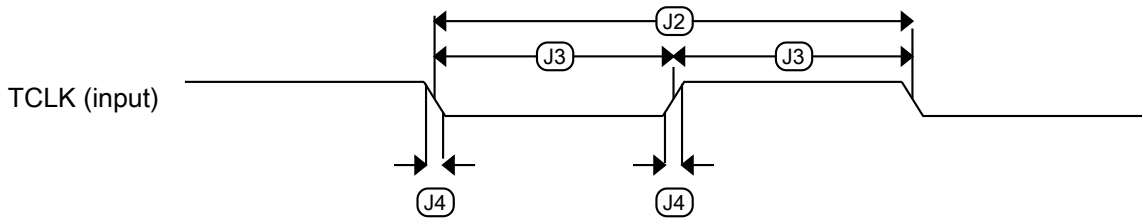


Figure 7. Test clock input timing

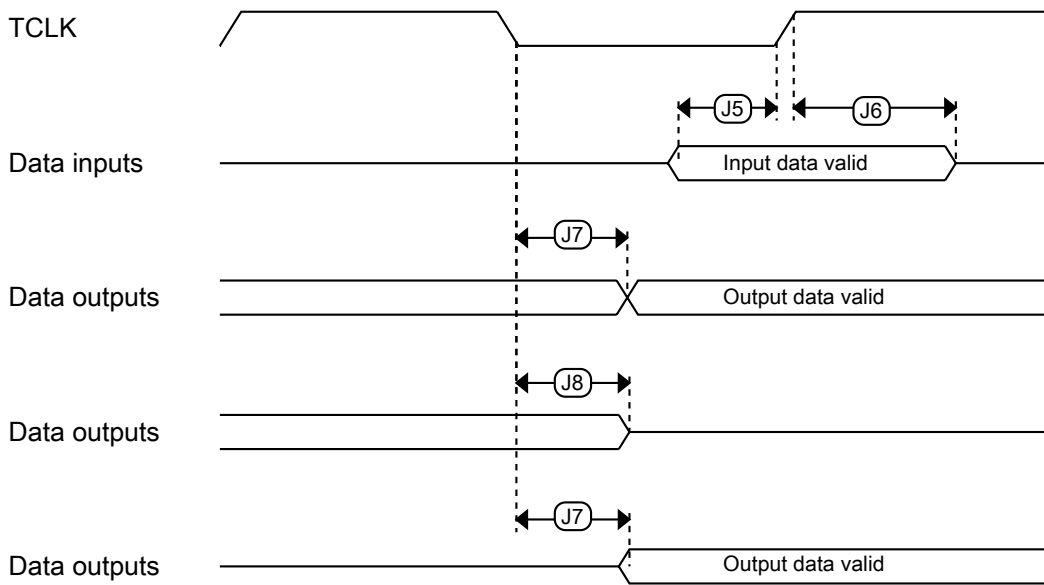


Figure 8. Boundary scan (JTAG) timing

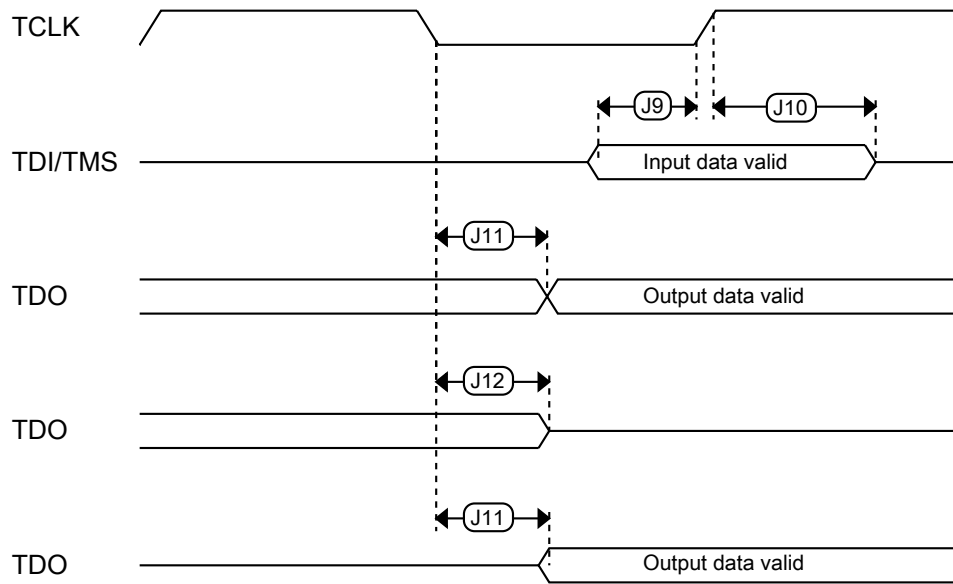
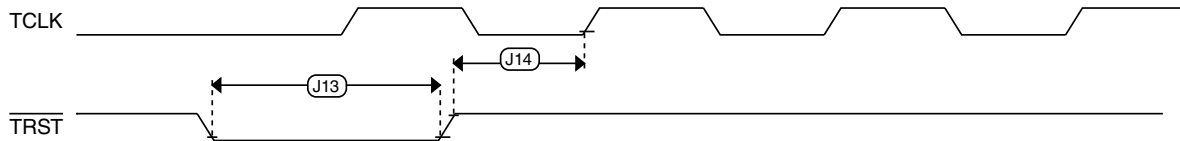


Figure 9. Test Access Port timing

Figure 10. $\overline{\text{TRST}}$ timing

3.2 System modules

There are no specifications necessary for the device's system modules.

3.3 Clock modules

3.3.1 MCG specifications

Table 16. MCG specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes | |
|---------------------------------|--|--|-----------|-----------|-------------------------|-------|------|
| $f_{\text{ints_ft}}$ | Internal reference frequency (slow clock) — factory trimmed at nominal VDD and 25 °C | — | 32.768 | — | kHz | | |
| $\Delta f_{\text{ints_t}}$ | Total deviation of internal reference frequency (slow clock) over voltage and temperature | — | +0.5/-0.7 | ± 2 | % | | |
| $f_{\text{ints_t}}$ | Internal reference frequency (slow clock) — user trimmed | 31.25 | — | 39.0625 | kHz | | |
| $\Delta f_{\text{dco_res_t}}$ | Resolution of trimmed average DCO output frequency at fixed voltage and temperature — using SCTRIM and SCFTRIM | — | ± 0.3 | ± 0.6 | % f_{dco} | 1 | |
| $\Delta f_{\text{dco_t}}$ | Total deviation of trimmed average DCO output frequency over voltage and temperature | — | +0.5/-0.7 | ± 2 | % f_{dco} | 1, 2 | |
| $\Delta f_{\text{dco_t}}$ | Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0–70°C | — | ± 0.3 | ± 1.5 | % f_{dco} | 1 | |
| $f_{\text{intf_ft}}$ | Internal reference frequency (fast clock) — factory trimmed at nominal VDD and 25°C | — | 4 | — | MHz | | |
| $\Delta f_{\text{intf_ft}}$ | Frequency deviation of internal reference clock (fast clock) over temperature and voltage — factory trimmed at nominal VDD and 25 °C | — | +1/-2 | ± 5 | % $f_{\text{intf_ft}}$ | | |
| $f_{\text{intf_t}}$ | Internal reference frequency (fast clock) — user trimmed at nominal VDD and 25 °C | 3 | — | 5 | MHz | | |
| $f_{\text{loc_low}}$ | Loss of external clock minimum frequency — RANGE = 00 | $(3/5) \times f_{\text{ints_t}}$ | — | — | kHz | | |
| $f_{\text{loc_high}}$ | Loss of external clock minimum frequency — RANGE = 01, 10, or 11 | $(16/5) \times f_{\text{ints_t}}$ | — | — | kHz | | |
| FLL | | | | | | | |
| $f_{\text{fll_ref}}$ | FLL reference frequency range | 31.25 | — | 39.0625 | kHz | | |
| f_{dco} | DCO output frequency range | Low range (DRS=00) $640 \times f_{\text{fll_ref}}$ | 20 | 20.97 | 25 | MHz | 3, 4 |
| | | Mid range (DRS=01) $1280 \times f_{\text{fll_ref}}$ | 40 | 41.94 | 50 | MHz | |
| | | Mid-high range (DRS=10) $1920 \times f_{\text{fll_ref}}$ | 60 | 62.91 | 75 | MHz | |
| | | High range (DRS=11) $2560 \times f_{\text{fll_ref}}$ | 80 | 83.89 | 100 | MHz | |
| $f_{\text{dco_t_DMX3}}_2$ | DCO output frequency | Low range (DRS=00) $732 \times f_{\text{fll_ref}}$ | — | 23.99 | — | MHz | 5, 6 |
| | | Mid range (DRS=01) $1464 \times f_{\text{fll_ref}}$ | — | 47.97 | — | MHz | |
| | | Mid-high range (DRS=10) | — | 71.99 | — | MHz | |

Table continues on the next page...

Table 16. MCG specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---------------------|--|------|------|------|------|-------|
| | | | | | | |
| | | | | | | |
| | | | | | | |
| | | | | | | |
| J_{cyc_fill} | FLL period jitter <ul style="list-style-type: none"> $f_{VCO} = 48$ MHz $f_{VCO} = 98$ MHz | — | — | — | ps | |
| $t_{fill_acquire}$ | FLL target frequency acquisition time | — | — | 1 | ms | 7 |

1. This parameter is measured with the internal reference (slow clock) being used as a reference to the FLL (FEI clock mode).
2. $2.0\text{ V} \leq VDD \leq 3.6\text{ V}$.
3. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=0.
4. The resulting system clock frequencies should not exceed their maximum specified values. The DCO frequency deviation (Δf_{dco_t}) over voltage and temperature should be considered.
5. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32=1.
6. The resulting clock frequency must not exceed the maximum specified clock frequency of the device.
7. This specification applies to any time the FLL reference source or reference divider is changed, trim value is changed, DMX32 bit is changed, DRS bits are changed, or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

3.3.2 IRC48M specifications

Table 17. IRC48M specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------------|---|------|-----------|-----------|----------------|-------|
| V_{DD} | Supply voltage | 1.71 | — | 3.6 | V | |
| I_{DD48M} | Supply current | — | 400 | 500 | μA | |
| f_{irc48m} | Internal reference frequency | — | 48 | — | MHz | |
| $\Delta f_{irc48m_ol_hv}$ | Open loop total deviation of IRC48M frequency at high voltage ($VDD=1.89\text{V}-3.6\text{V}$) over 0°C to 70°C Regulator enable ($USB_CLK_RECOVER_IRC_EN[REG_EN]=1$) | — | ± 0.2 | ± 0.5 | $\%f_{irc48m}$ | 1 |
| $\Delta f_{irc48m_ol_hv}$ | Open loop total deviation of IRC48M frequency at high voltage ($VDD=1.89\text{V}-3.6\text{V}$) over full temperature Regulator enable ($USB_CLK_RECOVER_IRC_EN[REG_EN]=1$) | — | ± 0.4 | ± 1.0 | $\%f_{irc48m}$ | 1 |
| $\Delta f_{irc48m_ol_lv}$ | Open loop total deviation of IRC48M frequency at low voltage ($VDD=1.71\text{V}-1.89\text{V}$) over full temperature Regulator disable ($USB_CLK_RECOVER_IRC_EN[REG_EN]=0$) Regulator enable ($USB_CLK_RECOVER_IRC_EN[REG_EN]=1$) | — | ± 0.4 | ± 1.0 | $\%f_{irc48m}$ | 1 |

Table continues on the next page...

Table 17. IRC48M specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-------------------------|--|------|------|-----------|--------------|-------|
| Δf_{irc48m_cl} | Closed loop total deviation of IRC48M frequency over voltage and temperature | — | — | ± 0.1 | % f_{host} | 2 |
| J_{cyc_irc48m} | Period Jitter (RMS) | — | 35 | 150 | ps | |
| $t_{irc48mst}$ | Startup time | — | 2 | 3 | μs | 3 |

1. The maximum value represents characterized results equivalent to the mean plus or minus three times the standard deviation (mean \pm 3 sigma).
2. Closed loop operation of the IRC48M is only feasible for USB device operation; it is not usable for USB host operation. It is enabled by configuring for USB Device, selecting IRC48M as USB clock source, and enabling the clock recover function (USB_CLK_RECOVER_IRC_CTRL[CLOCK_RECOVER_EN]=1, USB_CLK_RECOVER_IRC_EN[IRC_EN]=1).
3. IRC48M startup time is defined as the time between clock enablement and clock availability for system use. Enable the clock by one of the following settings:
 - USB_CLK_RECOVER_IRC_EN[IRC_EN]=1 or
 - MCG operating in an external clocking mode and MCG_C7[OSCSEL]=10 or MCG_C5[PLLCLKEN0]=1, or
 - SIM_SOPT2[PLLFLLSEL]=11

3.3.3 Oscillator electrical specifications

3.3.3.1 Oscillator DC electrical specifications

Table 18. Oscillator DC electrical specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-------------|---|------|------|------|---------|-------|
| V_{DD} | Supply voltage | 1.71 | — | 3.6 | V | |
| I_{DDOSC} | Supply current — low-power mode (HGO=0) <ul style="list-style-type: none"> • 32 kHz • 4 MHz • 8 MHz (RANGE=01) • 16 MHz • 24 MHz • 32 MHz | — | 500 | — | nA | 1 |
| I_{DDOSC} | Supply current — high-gain mode (HGO=1) <ul style="list-style-type: none"> • 32 kHz • 4 MHz • 8 MHz (RANGE=01) • 16 MHz • 24 MHz • 32 MHz | — | 25 | — | μA | 1 |
| C_x | EXTAL load capacitance | — | — | — | | 2, 3 |

Table continues on the next page...

Table 18. Oscillator DC electrical specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------|--|------|----------|------|------------|-------|
| C_y | XTAL load capacitance | — | — | — | | 2, 3 |
| R_F | Feedback resistor — low-frequency, low-power mode (HGO=0) | — | — | — | M Ω | 2, 4 |
| | Feedback resistor — low-frequency, high-gain mode (HGO=1) | — | 10 | — | M Ω | |
| | Feedback resistor — high-frequency, low-power mode (HGO=0) | — | — | — | M Ω | |
| | Feedback resistor — high-frequency, high-gain mode (HGO=1) | — | 1 | — | M Ω | |
| R_S | Series resistor — low-frequency, low-power mode (HGO=0) | — | — | — | k Ω | |
| | Series resistor — low-frequency, high-gain mode (HGO=1) | — | 200 | — | k Ω | |
| | Series resistor — high-frequency, low-power mode (HGO=0) | — | — | — | k Ω | |
| | Series resistor — high-frequency, high-gain mode (HGO=1) | — | 0 | — | k Ω | |
| V_{pp} ⁵ | Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0) | — | 0.6 | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1) | — | V_{DD} | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0) | — | 0.6 | — | V | |
| | Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1) | — | V_{DD} | — | V | |

1. V_{DD} =3.3 V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3. C_x and C_y can be provided by using either integrated capacitors or external components.
4. When low-power mode is selected, R_F is integrated and must not be attached externally.
5. The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other device.

3.3.3.2 Oscillator frequency specifications

Table 19. Oscillator frequency specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---------------|---|------|------|------|------|-------|
| f_{osc_lo} | Oscillator crystal or resonator frequency — low-frequency mode (MCG_C2[RANGE]=00) | 32 | — | 40 | kHz | |

Table continues on the next page...

Table 19. Oscillator frequency specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|------------------|---|------|------|------|------|-------|
| $f_{osc_hi_1}$ | Oscillator crystal or resonator frequency — high-frequency mode (low range) (MCG_C2[RANGE]=01) | 3 | — | 8 | MHz | |
| $f_{osc_hi_2}$ | Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x) | 8 | — | 32 | MHz | |
| f_{ec_extal} | Input clock frequency (external clock mode) | — | — | 50 | MHz | 1, 2 |
| t_{dc_extal} | Input clock duty cycle (external clock mode) | 40 | 50 | 60 | % | |
| t_{cst} | Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0) | — | 750 | — | ms | 3, 4 |
| | Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1) | — | 250 | — | ms | |
| | Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0) | — | 0.6 | — | ms | |
| | Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1) | — | 1 | — | ms | |

1. Other frequency limits may apply when external clock is being used as a reference for the FLL
2. When transitioning from FEI or FBI to FBE mode, restrict the frequency of the input clock so that, when it is divided by FRDIV, it remains within the limits of the DCO input clock frequency.
3. Proper PC board layout procedures must be followed to achieve specifications.
4. Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

3.3.4 32 kHz oscillator electrical characteristics

3.3.4.1 32 kHz oscillator DC electrical specifications

Table 20. 32kHz oscillator DC electrical specifications

| Symbol | Description | Min. | Typ. | Max. | Unit |
|------------|---|------|------|------|------------|
| V_{BAT} | Supply voltage | 1.71 | — | 3.6 | V |
| R_F | Internal feedback resistor | — | 100 | — | M Ω |
| C_{para} | Parasitical capacitance of EXTAL32 and XTAL32 | — | 5 | 7 | pF |
| V_{pp}^1 | Peak-to-peak amplitude of oscillation | — | 0.6 | — | V |

1. When a crystal is being used with the 32 kHz oscillator, the EXTAL32 and XTAL32 pins should only be connected to required oscillator components and must not be connected to any other devices.

3.3.4.2 32 kHz oscillator frequency specifications

Table 21. 32 kHz oscillator frequency specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-------------------------|---|------|--------|------------------|------|-------|
| f _{osc_lo} | Oscillator crystal | — | 32.768 | — | kHz | |
| t _{start} | Crystal start-up time | — | 1000 | — | ms | 1 |
| f _{ec_extal32} | Externally provided input clock frequency | — | 32.768 | — | kHz | 2 |
| V _{ec_extal32} | Externally provided input clock amplitude | 700 | — | V _{BAT} | mV | 2, 3 |

1. Proper PC board layout procedures must be followed to achieve specifications.
2. This specification is for an externally supplied clock driven to EXTAL32 and does not apply to any other clock input. The oscillator remains enabled and XTAL32 must be left unconnected.
3. The parameter specified is a peak-to-peak value and V_{IH} and V_{IL} specifications do not apply. The voltage of the applied clock must be within the range of V_{SS} to V_{BAT}.

3.4 Memories and memory interfaces

3.4.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

3.4.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

Table 22. NVM program/erase timing specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|--------------------------------|------------------------------------|------|------|------|------|-------|
| t _{hvp_{gm4}} | Longword Program high-voltage time | — | 7.5 | 18 | μs | — |
| t _{hversscr} | Sector Erase high-voltage time | — | 13 | 113 | ms | 1 |
| t _{hversall} | Erase All high-voltage time | — | 104 | 904 | ms | 1 |

1. Maximum time based on expectations at cycling end-of-life.

3.4.1.2 Flash timing specifications — commands

Table 23. Flash command timing specifications

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-----------------------|---|------|------|------|------|-------|
| t _{rd1sec2k} | Read 1s Section execution time (flash sector) | — | — | 60 | μs | 1 |
| t _{pgmchk} | Program Check execution time | — | — | 45 | μs | 1 |

Table continues on the next page...

Table 23. Flash command timing specifications (continued)

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|---------------|---|------|------|------|---------|-------|
| t_{rdsrc} | Read Resource execution time | — | — | 30 | μ s | 1 |
| t_{pgm4} | Program Longword execution time | — | 65 | 145 | μ s | — |
| t_{ersscr} | Erase Flash Sector execution time | — | 14 | 114 | ms | 2 |
| t_{rd1all} | Read 1s All Blocks execution time | — | — | 0.9 | ms | 1 |
| t_{rdonce} | Read Once execution time | — | — | 30 | μ s | 1 |
| $t_{pgmonce}$ | Program Once execution time | — | 100 | — | μ s | — |
| t_{ersall} | Erase All Blocks execution time | — | 140 | 1150 | ms | 2 |
| t_{vfykey} | Verify Backdoor Access Key execution time | — | — | 30 | μ s | 1 |

1. Assumes 25 MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.

3.4.1.3 Flash high voltage current behaviors

Table 24. Flash high voltage current behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit |
|---------------|---|------|------|------|------|
| I_{DD_PGM} | Average current adder during high voltage flash programming operation | — | 2.5 | 6.0 | mA |
| I_{DD_ERS} | Average current adder during high voltage flash erase operation | — | 1.5 | 4.0 | mA |

3.4.1.4 Reliability specifications

Table 25. NVM reliability specifications

| Symbol | Description | Min. | Typ. ¹ | Max. | Unit | Notes |
|------------------|--|------|-------------------|------|--------|-------|
| Program Flash | | | | | | |
| $t_{nvmretp10k}$ | Data retention after up to 10 K cycles | 5 | 50 | — | years | — |
| $t_{nvmretp1k}$ | Data retention after up to 1 K cycles | 20 | 100 | — | years | — |
| $n_{nvmcycp}$ | Cycling endurance | 10 K | 50 K | — | cycles | 2 |

1. Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25 °C use profile. Engineering Bulletin EB618 does not apply to this technology. Typical endurance defined in Engineering Bulletin EB619.
2. Cycling endurance represents number of program/erase cycles at $-40\text{ °C} \leq T_j \leq 125\text{ °C}$.

3.4.2 EzPort switching specifications

Table 26. EzPort switching specifications

| Num | Description | Min. | Max. | Unit |
|------|--|------------------------|-------------|------|
| | Operating voltage | 1.71 | 3.6 | V |
| EP1 | EZP_CK frequency of operation (all commands except READ) | — | $f_{SYS}/2$ | MHz |
| EP1a | EZP_CK frequency of operation (READ command) | — | $f_{SYS}/8$ | MHz |
| EP2 | $\overline{EZP_CS}$ negation to next $\overline{EZP_CS}$ assertion | $2 \times t_{EZP_CK}$ | — | ns |
| EP3 | $\overline{EZP_CS}$ input valid to EZP_CK high (setup) | 5 | — | ns |
| EP4 | EZP_CK high to $\overline{EZP_CS}$ input invalid (hold) | 5 | — | ns |
| EP5 | EZP_D input valid to EZP_CK high (setup) | 2 | — | ns |
| EP6 | EZP_CK high to EZP_D input invalid (hold) | 5 | — | ns |
| EP7 | EZP_CK low to EZP_Q output valid | — | 25 | ns |
| EP8 | EZP_CK low to EZP_Q output invalid (hold) | 0 | — | ns |
| EP9 | $\overline{EZP_CS}$ negation to EZP_Q tri-state | — | 12 | ns |

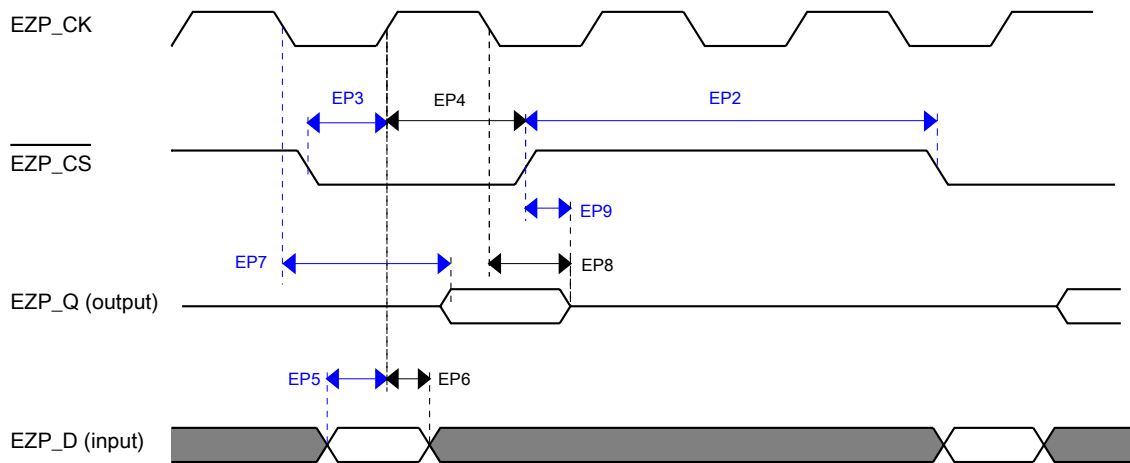


Figure 11. EzPort Timing Diagram

3.5 Security and integrity modules

There are no specifications necessary for the device's security and integrity modules.

3.6 Analog

3.6.1 ADC electrical specifications

The 16-bit accuracy specifications listed in [Table 27](#) and [Table 28](#) are achievable on the differential pins ADCx_DPx, ADCx_DMx.

All other ADC channels meet the 13-bit differential/12-bit single-ended accuracy specifications.

3.6.1.1 16-bit ADC operating conditions

Table 27. 16-bit ADC operating conditions

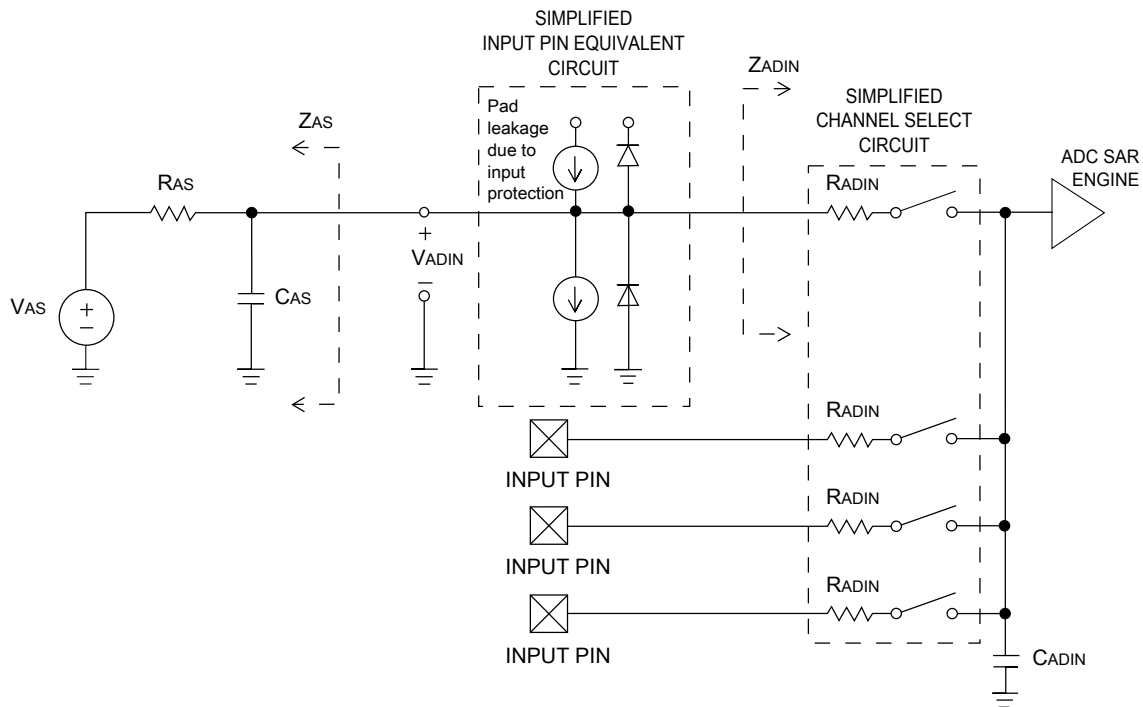
| Symbol | Description | Conditions | Min. | Typ. ¹ | Max. | Unit | Notes |
|-------------------|-------------------------------------|---|------------------|-------------------|---------------------------|------|-------------------|
| V _{DDA} | Supply voltage | Absolute | 1.71 | — | 3.6 | V | |
| ΔV _{DDA} | Supply voltage | Delta to V _{DD} (V _{DD} – V _{DDA}) | -100 | 0 | +100 | mV | 2 |
| ΔV _{SSA} | Ground voltage | Delta to V _{SS} (V _{SS} – V _{SSA}) | -100 | 0 | +100 | mV | 2 |
| V _{REFH} | ADC reference voltage high | | 1.13 | V _{DDA} | V _{DDA} | V | |
| V _{REFL} | ADC reference voltage low | | V _{SSA} | V _{SSA} | V _{SSA} | V | |
| V _{ADIN} | Input voltage | <ul style="list-style-type: none"> 16-bit differential mode All other modes | VREFL VREFL | — — | 31/32 * VREFH VREFH | V | |
| C _{ADIN} | Input capacitance | <ul style="list-style-type: none"> 16-bit mode 8-bit / 10-bit / 12-bit modes | — — | 8 4 | 10 5 | pF | |
| R _{ADIN} | Input series resistance | | — | 2 | 5 | kΩ | |
| R _{AS} | Analog source resistance (external) | 13-bit / 12-bit modes f _{ADCK} < 4 MHz | — | — | 5 | kΩ | 3 |
| f _{ADCK} | ADC conversion clock frequency | ≤ 13-bit mode | 1.0 | — | 24.0 | MHz | 4 |
| f _{ADCK} | ADC conversion clock frequency | 16-bit mode | 2.0 | — | 12.0 | MHz | 4 |
| C _{rate} | ADC conversion rate | ≤ 13-bit modes No ADC hardware averaging Continuous conversions enabled, subsequent conversion time | 20 | — | 1200 | Ksps | 5 |

Table continues on the next page...

Table 27. 16-bit ADC operating conditions (continued)

| Symbol | Description | Conditions | Min. | Typ. ¹ | Max. | Unit | Notes |
|------------|---------------------|--|------|-------------------|------|------|-------|
| C_{rate} | ADC conversion rate | 16-bit mode No ADC hardware averaging Continuous conversions enabled, subsequent conversion time | 37 | — | 461 | Ksps | 5 |

1. Typical values assume $V_{DDA} = 3.0\text{ V}$, $Temp = 25\text{ }^{\circ}\text{C}$, $f_{ADCK} = 1.0\text{ MHz}$, unless otherwise stated. Typical values are for reference only, and are not tested in production.
2. DC potential difference.
3. This resistance is external to MCU. To achieve the best results, the analog source resistance must be kept as low as possible. The results in this data sheet were derived from a system that had $< 8\ \Omega$ analog source resistance. The R_{AS}/C_{AS} time constant should be kept to $< 1\text{ ns}$.
4. To use the maximum ADC conversion clock frequency, $CFG2[ADHSC]$ must be set and $CFG1[ADLPC]$ must be clear.
5. For guidelines and examples of conversion rate calculation, download the [ADC calculator tool](#).

**Figure 12. ADC input impedance equivalency diagram**

3.6.1.2 16-bit ADC electrical characteristics

Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$)

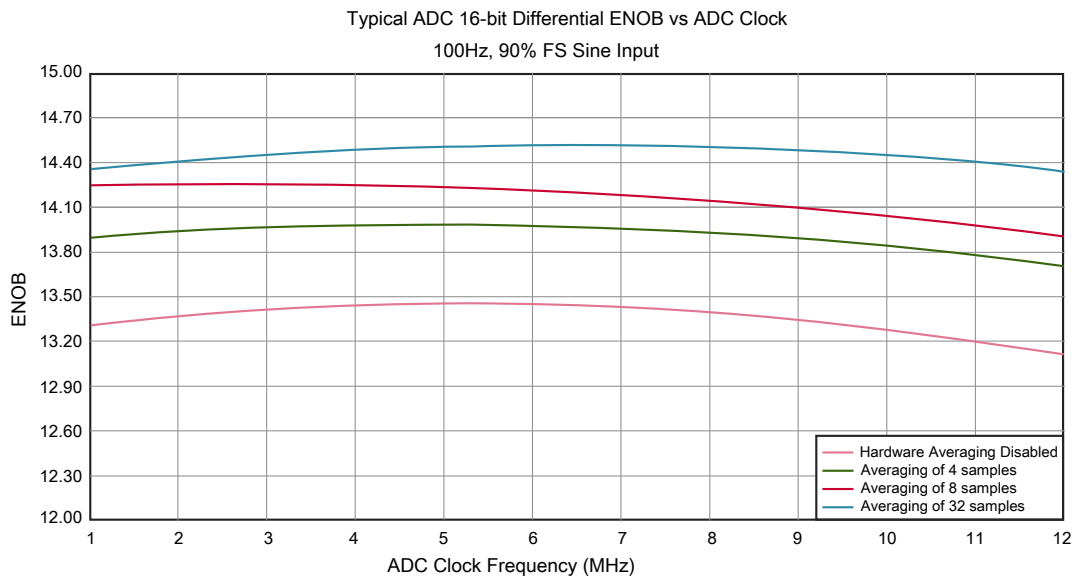
| Symbol | Description | Conditions ¹ | Min. | Typ. ² | Max. | Unit | Notes |
|----------------|---------------------------------|---|----------------------------------|----------------------|------------------------|------------------|-----------------------------------|
| I_{DDA_ADC} | Supply current | | 0.215 | — | 1.7 | mA | 3 |
| f_{ADACK} | ADC asynchronous clock source | • ADLPC = 1, ADHSC = 0 | 1.2 | 2.4 | 3.9 | MHz | $t_{ADACK} = 1/f_{ADACK}$ |
| | | • ADLPC = 1, ADHSC = 1 | 2.4 | 4.0 | 6.1 | MHz | |
| | | • ADLPC = 0, ADHSC = 0 | 3.0 | 5.2 | 7.3 | MHz | |
| | | • ADLPC = 0, ADHSC = 1 | 4.4 | 6.2 | 9.5 | MHz | |
| | Sample Time | See Reference Manual chapter for sample times | | | | | |
| TUE | Total unadjusted error | • 12-bit modes • <12-bit modes | — — | ± 4 ± 1.4 | ± 6.8 ± 2.1 | LSB ⁴ | 5 |
| DNL | Differential non-linearity | • 12-bit modes | — | ± 0.7 | -1.1 to +1.9 | LSB ⁴ | 5 |
| | | • <12-bit modes | — | ± 0.2 | -0.3 to 0.5 | | |
| INL | Integral non-linearity | • 12-bit modes | — | ± 1.0 | -2.7 to +1.9 | LSB ⁴ | 5 |
| | | • <12-bit modes | — | ± 0.5 | -0.7 to +0.5 | | |
| E_{FS} | Full-scale error | • 12-bit modes | — | -4 | -5.4 | LSB ⁴ | $V_{ADIN} = V_{DDA}$ ⁵ |
| | | • <12-bit modes | — | -1.4 | -1.8 | | |
| E_Q | Quantization error | • 16-bit modes | — | -1 to 0 | — | LSB ⁴ | |
| | | • ≤ 13 -bit modes | — | — | ± 0.5 | | |
| ENOB | Effective number of bits | 16-bit differential mode | | | | | 6 |
| | | • Avg = 32 | 12.8 | 14.5 | — | bits | |
| | | • Avg = 4 | 11.9 | 13.8 | — | bits | |
| | | 16-bit single-ended mode | | | | | |
| • Avg = 32 | 12.2 | 13.9 | — | bits | | | |
| • Avg = 4 | 11.4 | 13.1 | — | bits | | | |
| SINAD | Signal-to-noise plus distortion | See ENOB | $6.02 \times \text{ENOB} + 1.76$ | | | dB | |
| THD | Total harmonic distortion | 16-bit differential mode | | | | dB | 7 |
| | | • Avg = 32 | — | -94 | — | dB | |
| | | 16-bit single-ended mode | | | | | |
| • Avg = 32 | — | -85 | — | | | | |
| SFDR | Spurious free dynamic range | 16-bit differential mode | | | | dB | 7 |
| | | • Avg = 32 | 82 | 95 | — | dB | |
| | | | | | | | |

Table continues on the next page...

Table 28. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$) (continued)

| Symbol | Description | Conditions ¹ | Min. | Typ. ² | Max. | Unit | Notes |
|--------------|---------------------|---|------------------------|-------------------|------|-------|--|
| | | 16-bit single-ended mode • Avg = 32 | 78 | 90 | | | |
| E_{IL} | Input leakage error | | $I_{in} \times R_{AS}$ | | | mV | I_{in} = leakage current (refer to the MCU's voltage and current operating ratings) |
| | Temp sensor slope | Across the full temperature range of the device | 1.55 | 1.62 | 1.69 | mV/°C | 8 |
| V_{TEMP25} | Temp sensor voltage | 25 °C | 706 | 716 | 726 | mV | 8 |

- All accuracy numbers assume the ADC is calibrated with $V_{REFH} = V_{DDA}$
- Typical values assume $V_{DDA} = 3.0$ V, Temp = 25 °C, $f_{ADCK} = 2.0$ MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
- The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.
- 1 LSB = $(V_{REFH} - V_{REFL})/2^N$
- ADC conversion clock < 16 MHz, Max hardware averaging (AVGE = %1, AVGS = %11)
- Input data is 100 Hz sine wave. ADC conversion clock < 12 MHz.
- Input data is 1 kHz sine wave. ADC conversion clock < 12 MHz.
- ADC conversion clock < 3 MHz

**Figure 13. Typical ENOB vs. ADC_CLK for 16-bit differential mode**

Peripheral operating requirements and behaviors

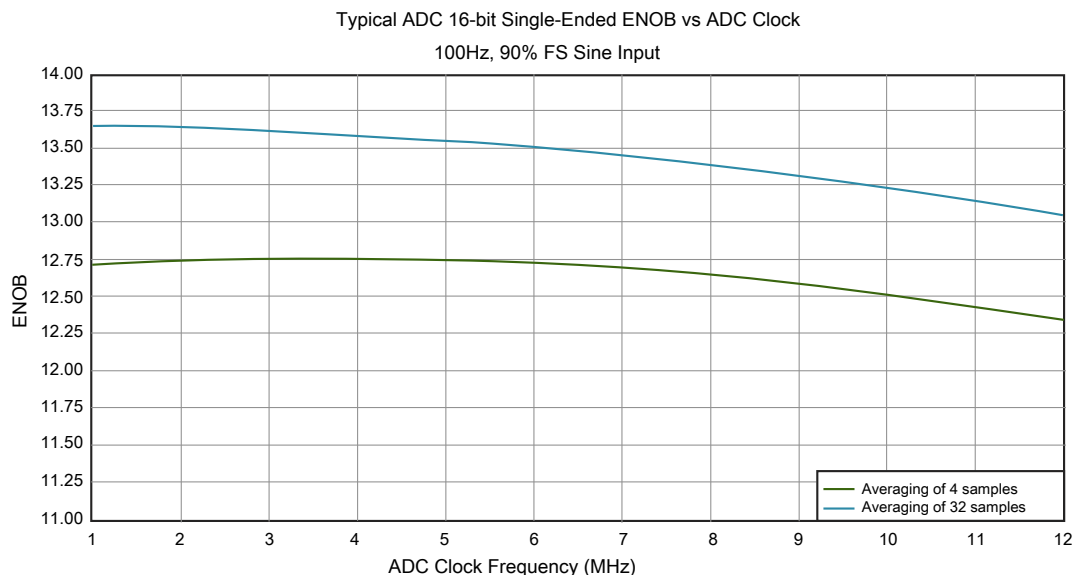


Figure 14. Typical ENOB vs. ADC_CLK for 16-bit single-ended mode

3.6.2 CMP and 6-bit DAC electrical specifications

Table 29. Comparator and 6-bit DAC electrical specifications

| Symbol | Description | Min. | Typ. | Max. | Unit |
|-------------|--|----------------|---------------------|----------|------------------|
| V_{DD} | Supply voltage | 1.71 | — | 3.6 | V |
| I_{DDHS} | Supply current, High-speed mode (EN=1, PMODE=1) | — | — | 200 | μ A |
| $I_{DDL S}$ | Supply current, low-speed mode (EN=1, PMODE=0) | — | — | 20 | μ A |
| V_{AIN} | Analog input voltage | $V_{SS} - 0.3$ | — | V_{DD} | V |
| V_{AIO} | Analog input offset voltage | — | — | 20 | mV |
| V_H | Analog comparator hysteresis ¹ <ul style="list-style-type: none"> • CR0[HYSTCTR] = 00 • CR0[HYSTCTR] = 01 • CR0[HYSTCTR] = 10 • CR0[HYSTCTR] = 11 | — | 5 10 20 30 | — | mV |
| V_{CMPOh} | Output high | $V_{DD} - 0.5$ | — | — | V |
| V_{CMPOl} | Output low | — | — | 0.5 | V |
| t_{DHS} | Propagation delay, high-speed mode (EN=1, PMODE=1) | 20 | 50 | 200 | ns |
| t_{DLS} | Propagation delay, low-speed mode (EN=1, PMODE=0) | 80 | 250 | 600 | ns |
| | Analog comparator initialization delay ² | — | — | 40 | μ s |
| I_{DAC6b} | 6-bit DAC current adder (enabled) | — | 7 | — | μ A |
| INL | 6-bit DAC integral non-linearity | -0.5 | — | 0.5 | LSB ³ |
| DNL | 6-bit DAC differential non-linearity | -0.3 | — | 0.3 | LSB |

1. Typical hysteresis is measured with input voltage range limited to 0.6 to $V_{DD}-0.6$ V.
2. Comparator initialization delay is defined as the time between software writes to change control inputs (Writes to CMP_DACCR[DACEN], CMP_DACCR[VRSEL], CMP_DACCR[VOSEL], CMP_MUXCR[PSEL], and CMP_MUXCR[MSEL]) and the comparator output settling to a stable level.
3. $1 \text{ LSB} = V_{\text{reference}}/64$

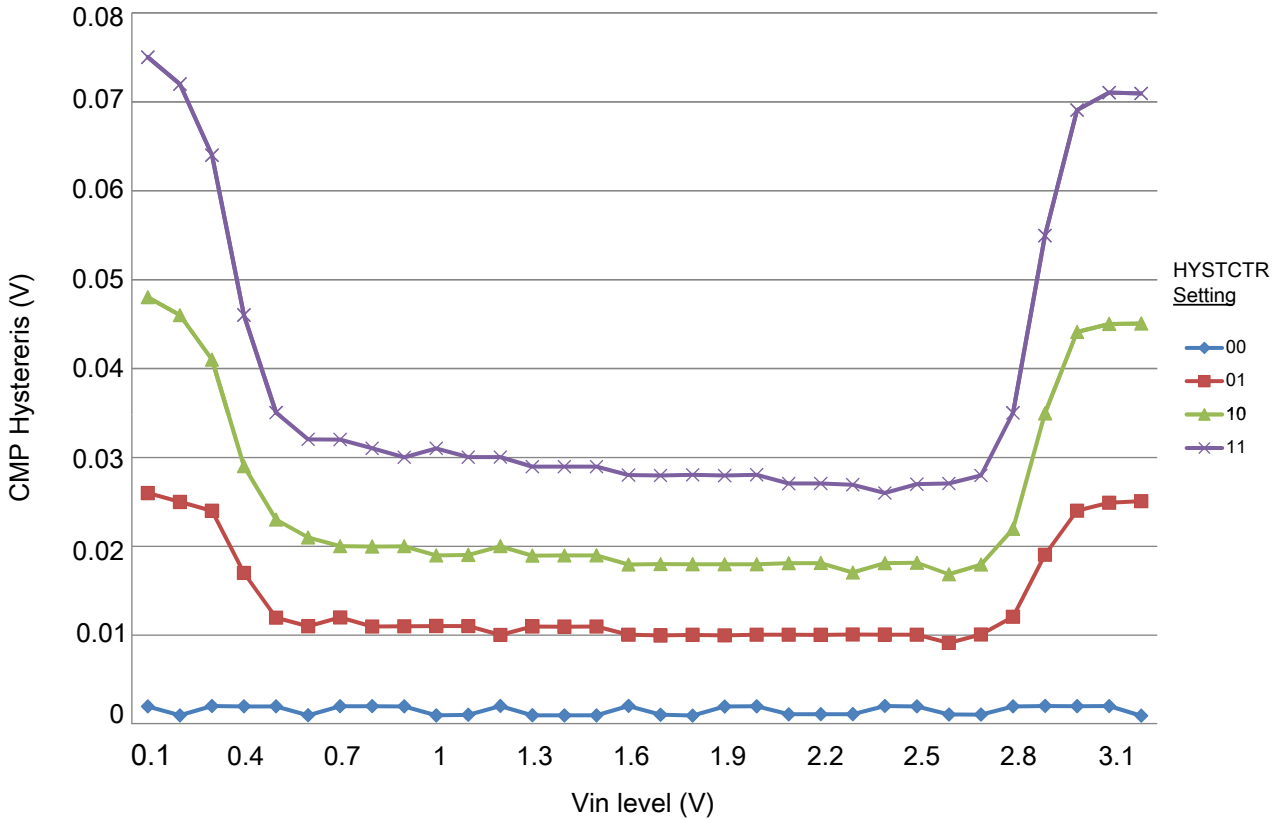


Figure 15. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 0)

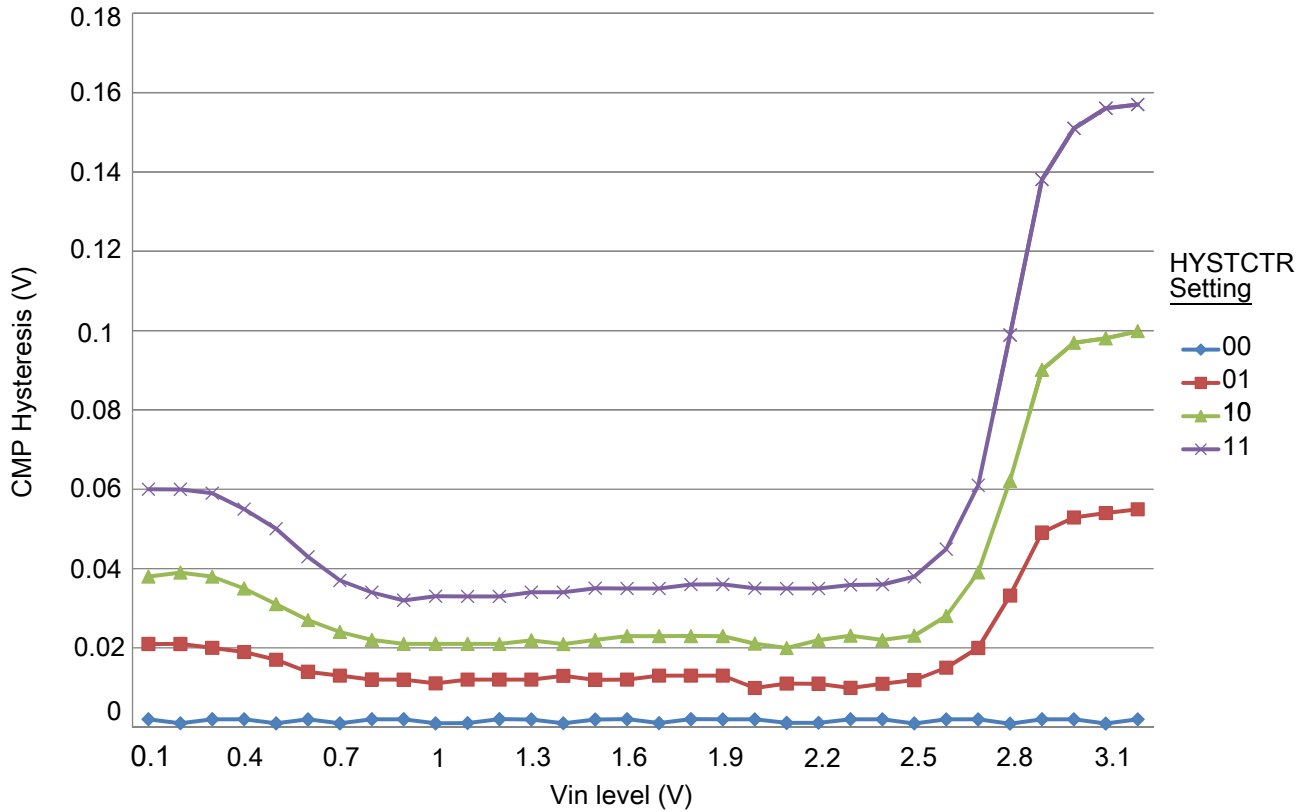


Figure 16. Typical hysteresis vs. Vin level (VDD = 3.3 V, PMODE = 1)

3.6.3 12-bit DAC electrical characteristics

3.6.3.1 12-bit DAC operating requirements

Table 30. 12-bit DAC operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|------------|-------------------------|------|------|------|-------|
| V_{DDA} | Supply voltage | 1.71 | 3.6 | V | |
| V_{DACR} | Reference voltage | 1.13 | 3.6 | V | 1 |
| C_L | Output load capacitance | — | 100 | pF | 2 |
| I_L | Output load current | — | 1 | mA | |

1. The DAC reference can be selected to be V_{DDA} or V_{REFH} .
2. A small load capacitance (47 pF) can improve the bandwidth performance of the DAC.

3.6.3.2 12-bit DAC operating behaviors

Table 31. 12-bit DAC operating behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|------------------|---|------------------|-------------|------------|------------------------|-------|
| I_{DDA_DACLP} | Supply current — low-power mode | — | — | 330 | μA | |
| I_{DDA_DACHP} | Supply current — high-speed mode | — | — | 1200 | μA | |
| t_{DACLP} | Full-scale settling time (0x080 to 0xF7F) — low-power mode | — | 100 | 200 | μs | 1 |
| t_{DACHP} | Full-scale settling time (0x080 to 0xF7F) — high-power mode | — | 15 | 30 | μs | 1 |
| $t_{CCDACLP}$ | Code-to-code settling time (0xBF8 to 0xC08) — low-power mode and high-speed mode | — | 0.7 | 1 | μs | 1 |
| $V_{dacoutl}$ | DAC output voltage range low — high-speed mode, no load, DAC set to 0x000 | — | — | 100 | mV | |
| $V_{dacouth}$ | DAC output voltage range high — high-speed mode, no load, DAC set to 0xFFFF | $V_{DACR} - 100$ | — | V_{DACR} | mV | |
| INL | Integral non-linearity error — high speed mode | — | — | ± 8 | LSB | 2 |
| DNL | Differential non-linearity error — $V_{DACR} > 2\text{ V}$ | — | — | ± 1 | LSB | 3 |
| DNL | Differential non-linearity error — $V_{DACR} = V_{REF_OUT}$ | — | — | ± 1 | LSB | 4 |
| V_{OFFSET} | Offset error | — | ± 0.4 | ± 0.8 | %FSR | 5 |
| E_G | Gain error | — | ± 0.1 | ± 0.6 | %FSR | 5 |
| PSRR | Power supply rejection ratio, $V_{DDA} \geq 2.4\text{ V}$ | 60 | — | 90 | dB | |
| T_{CO} | Temperature coefficient offset voltage | — | 3.7 | — | $\mu\text{V}/\text{C}$ | 6 |
| T_{GE} | Temperature coefficient gain error | — | 0.000421 | — | %FSR/C | |
| R_{op} | Output resistance (load = 3 k Ω) | — | — | 250 | Ω | |
| SR | Slew rate -80h→ F7Fh→ 80h <ul style="list-style-type: none"> High power (SP_{HP}) Low power (SP_{LP}) | 1.2 0.05 | 1.7 0.12 | — — | $\text{V}/\mu\text{s}$ | |
| BW | 3dB bandwidth <ul style="list-style-type: none"> High power (SP_{HP}) Low power (SP_{LP}) | 550 40 | — — | — — | kHz | |

- Settling within ± 1 LSB
- The INL is measured for 0 + 100 mV to $V_{DACR} - 100$ mV
- The DNL is measured for 0 + 100 mV to $V_{DACR} - 100$ mV
- The DNL is measured for 0 + 100 mV to $V_{DACR} - 100$ mV with $V_{DDA} > 2.4\text{ V}$
- Calculated by a best fit curve from $V_{SS} + 100$ mV to $V_{DACR} - 100$ mV
- $V_{DDA} = 3.0\text{ V}$, reference select set for V_{DDA} ($\text{DACx_CO:DACRFS} = 1$), high power mode ($\text{DACx_CO:LPEN} = 0$), DAC set to 0x800, temperature range is across the full range of the device

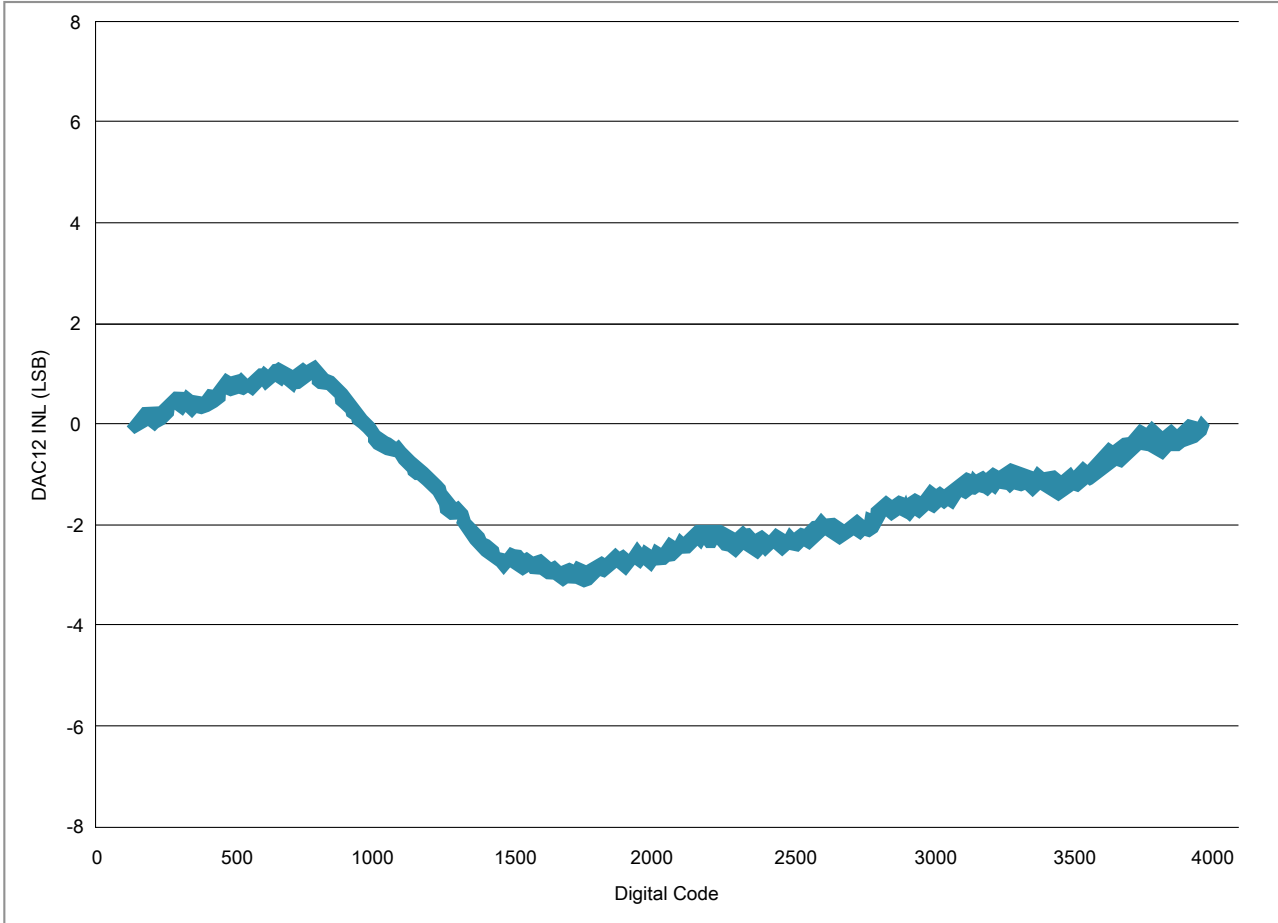


Figure 17. Typical INL error vs. digital code

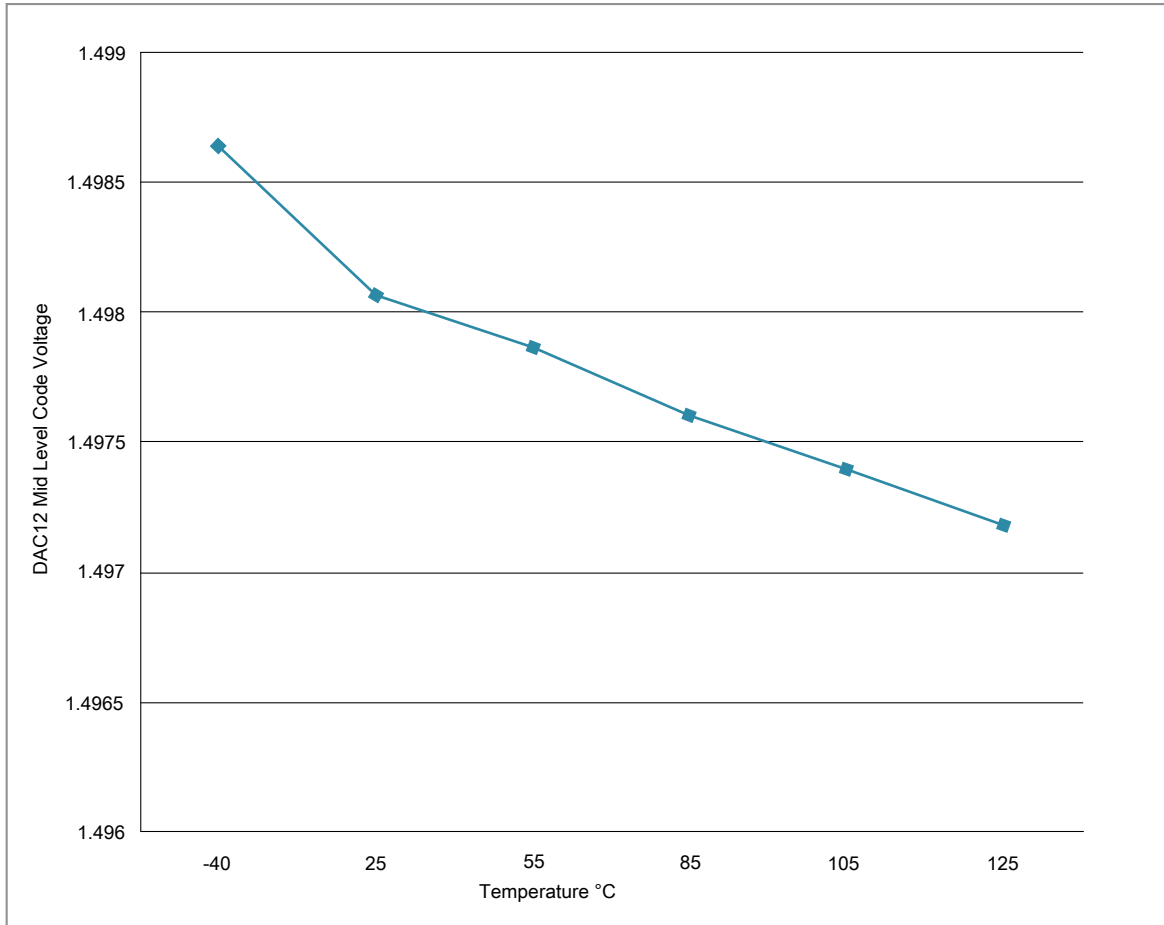


Figure 18. Offset at half scale vs. temperature

3.6.4 Voltage reference electrical specifications

Table 32. VREF full-range operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|-----------|-------------------------|---|------|------|-------|
| V_{DDA} | Supply voltage | 1.71 | 3.6 | V | |
| T_A | Temperature | Operating temperature range of the device | | °C | |
| C_L | Output load capacitance | 100 | | nF | 1, 2 |

1. C_L must be connected to VREF_OUT if the VREF_OUT functionality is being used for either an internal or external reference.
2. The load capacitance should not exceed +/-25% of the nominal specified C_L value over the operating temperature range of the device.

Table 33. VREF full-range operating behaviors

| Symbol | Description | Min. | Typ. | Max. | Unit | Notes |
|-------------------------|--|--------|--------|--------|---------|-------|
| V_{out} | Voltage reference output with factory trim at nominal V_{DDA} and temperature=25°C | 1.1920 | 1.1950 | 1.1980 | V | 1 |
| V_{out} | Voltage reference output with user trim at nominal V_{DDA} and temperature=25°C | 1.1945 | 1.1950 | 1.1955 | V | 1 |
| V_{step} | Voltage reference trim step | — | 0.5 | — | mV | 1 |
| V_{tdrift} | Temperature drift ($V_{max} - V_{min}$ across the full temperature range) | — | — | 15 | mV | 1 |
| I_{bg} | Bandgap only current | — | — | 80 | μ A | |
| I_{lp} | Low-power buffer current | — | — | 360 | μ A | 1 |
| I_{hp} | High-power buffer current | — | — | 1 | mA | 1 |
| ΔV_{LOAD} | Load regulation • current = ± 1.0 mA | — | 200 | — | μ V | 1, 2 |
| T_{stup} | Buffer startup time | — | — | 100 | μ s | |
| $T_{chop_osc_st\ up}$ | Internal bandgap start-up delay with chop oscillator enabled | — | — | 35 | ms | |
| V_{vdrift} | Voltage drift ($V_{max} - V_{min}$ across the full voltage range) | — | 2 | — | mV | 1 |

1. See the chip's Reference Manual for the appropriate settings of the VREF Status and Control register.
2. Load regulation voltage is the difference between the VREF_OUT voltage with no load vs. voltage with defined load

Table 34. VREF limited-range operating requirements

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------|-------------|------|------|------|-------|
| T_A | Temperature | 0 | 70 | °C | |

Table 35. VREF limited-range operating behaviors

| Symbol | Description | Min. | Max. | Unit | Notes |
|--------------|---|------|------|------|-------|
| V_{tdrift} | Temperature drift ($V_{max} - V_{min}$ across the limited temperature range) | — | 10 | mV | |

3.7 Timers

See [General switching specifications](#).

3.8 Communication interfaces

3.8.1 USB electrical specifications

The USB electricals for the USB On-the-Go module conform to the standards documented by the Universal Serial Bus Implementers Forum. For the most up-to-date standards, visit usb.org.

NOTE

The MCGFLLCLK does not meet the USB jitter or signaling rate specifications for certification.

The IRC48M meets the USB jitter and signaling rate specifications for certification in Device mode when the USB clock recovery mode is enabled. It does not meet the USB signaling rate specifications for certification in Host mode operation.

3.8.2 DSPI switching specifications (limited voltage range)

The Deserial Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provide DSPI timing characteristics for classic SPI timing modes. Refer to the SPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

Table 36. Master mode DSPI timing (limited voltage range)

| Num | Description | Min. | Max. | Unit | Notes |
|-----|--|---------------------------------|--------------------------|------|-------|
| | Operating voltage | 2.7 | 3.6 | V | |
| | Frequency of operation | — | 25 | MHz | |
| DS1 | DSPI_SCK output cycle time | $2 \times t_{\text{BUS}}$ | — | ns | |
| DS2 | DSPI_SCK output high/low time | $(t_{\text{SCK}}/2) - 2$ | $(t_{\text{SCK}}/2) + 2$ | ns | |
| DS3 | DSPI_PCS n valid to DSPI_SCK delay | $(t_{\text{BUS}} \times 2) - 2$ | — | ns | 1 |
| DS4 | DSPI_SCK to DSPI_PCS n invalid delay | $(t_{\text{BUS}} \times 2) - 2$ | — | ns | 2 |
| DS5 | DSPI_SCK to DSPI_SOUT valid | — | 8.5 | ns | |
| DS6 | DSPI_SCK to DSPI_SOUT invalid | -2 | — | ns | |
| DS7 | DSPI_SIN to DSPI_SCK input setup | 16.2 | — | ns | |
| DS8 | DSPI_SCK to DSPI_SIN input hold | 0 | — | ns | |

1. The delay is programmable in SPI x _CTAR n [PSSCK] and SPI x _CTAR n [CSSCK].

Peripheral operating requirements and behaviors

2. The delay is programmable in SPIx_CTARn[PASC] and SPIx_CTARn[ASC].

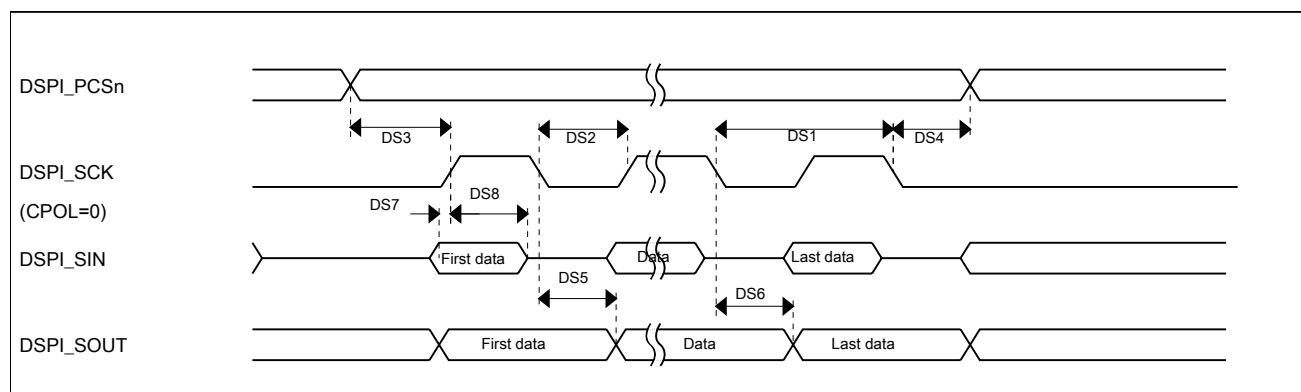


Figure 19. DSPI classic SPI timing — master mode

Table 37. Slave mode DSPI timing (limited voltage range)

| Num | Description | Min. | Max. | Unit | Notes |
|------|--|--------------------|-------------------|------|-------|
| | Operating voltage | 2.7 | 3.6 | V | |
| | Frequency of operation | — | 12.5 | MHz | 1 |
| DS9 | DSPI_SCK input cycle time | $4 \times t_{BUS}$ | — | ns | |
| DS10 | DSPI_SCK input high/low time | $(t_{SCK}/2) - 2$ | $(t_{SCK}/2) + 2$ | ns | |
| DS11 | DSPI_SCK to DSPI_SOUT valid | — | 21.4 | ns | |
| DS12 | DSPI_SCK to DSPI_SOUT invalid | 0 | — | ns | |
| DS13 | DSPI_SIN to DSPI_SCK input setup | 2.6 | — | ns | |
| DS14 | DSPI_SCK to DSPI_SIN input hold | 7 | — | ns | |
| DS15 | $\overline{DSPI_SS}$ active to DSPI_SOUT driven | — | 17 | ns | |
| DS16 | $\overline{DSPI_SS}$ inactive to DSPI_SOUT not driven | — | 17 | ns | |

1. The maximum operating frequency is measured with noncontinuous CS and SCK. When DSPI is configured with continuous CS and SCK, the SPI clock must not be greater than 1/6 of the bus clock. For example, when the bus clock is 60 MHz, the SPI clock must not be greater than 10 MHz.

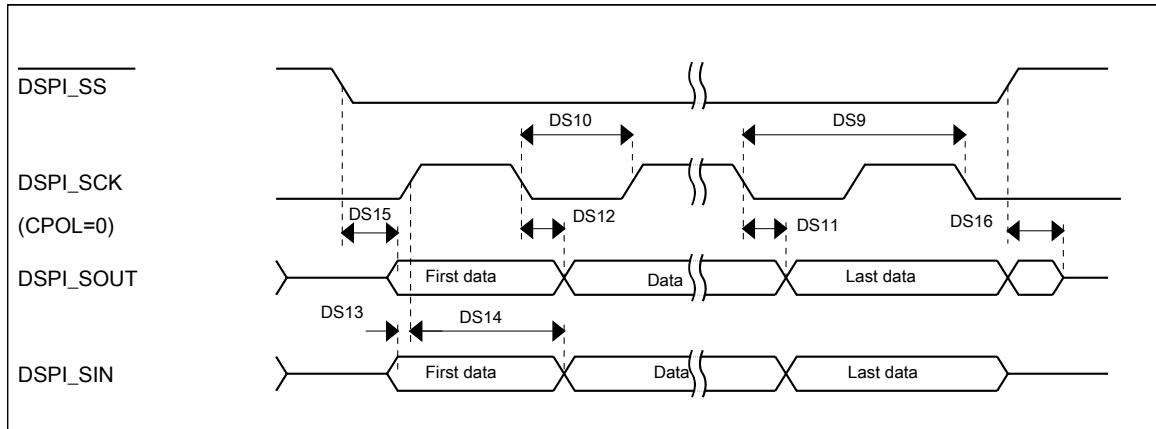


Figure 20. DSPI classic SPI timing — slave mode

3.8.3 DSPI switching specifications (full voltage range)

The Deserial Serial Peripheral Interface (DSPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The tables below provides DSPI timing characteristics for classic SPI timing modes. Refer to the SPI chapter of the Reference Manual for information on the modified transfer formats used for communicating with slower peripheral devices.

Table 38. Master mode DSPI timing (full voltage range)

| Num | Description | Min. | Max. | Unit | Notes |
|-----|--|---------------------------------|--------------------------|------|-------|
| | Operating voltage | 1.71 | 3.6 | V | 1 |
| | Frequency of operation | — | 12.5 | MHz | |
| DS1 | DSPI_SCK output cycle time | $4 \times t_{\text{BUS}}$ | — | ns | |
| DS2 | DSPI_SCK output high/low time | $(t_{\text{SCK}/2}) - 4$ | $(t_{\text{SCK}/2}) + 4$ | ns | |
| DS3 | DSPI_PCS n valid to DSPI_SCK delay | $(t_{\text{BUS}} \times 2) - 4$ | — | ns | 2 |
| DS4 | DSPI_SCK to DSPI_PCS n invalid delay | $(t_{\text{BUS}} \times 2) - 4$ | — | ns | 3 |
| DS5 | DSPI_SCK to DSPI_SOUT valid | — | 10 | ns | |
| DS6 | DSPI_SCK to DSPI_SOUT invalid | -4.5 | — | ns | |
| DS7 | DSPI_SIN to DSPI_SCK input setup | 24.6 | — | ns | |
| DS8 | DSPI_SCK to DSPI_SIN input hold | 0 | — | ns | |

1. The DSPI module can operate across the entire operating voltage for the processor, but to run across the full voltage range the maximum frequency of operation is reduced.
2. The delay is programmable in SPI x _CTAR n [PSSCK] and SPI x _CTAR n [CSSCK].
3. The delay is programmable in SPI x _CTAR n [PASC] and SPI x _CTAR n [ASC].

Peripheral operating requirements and behaviors

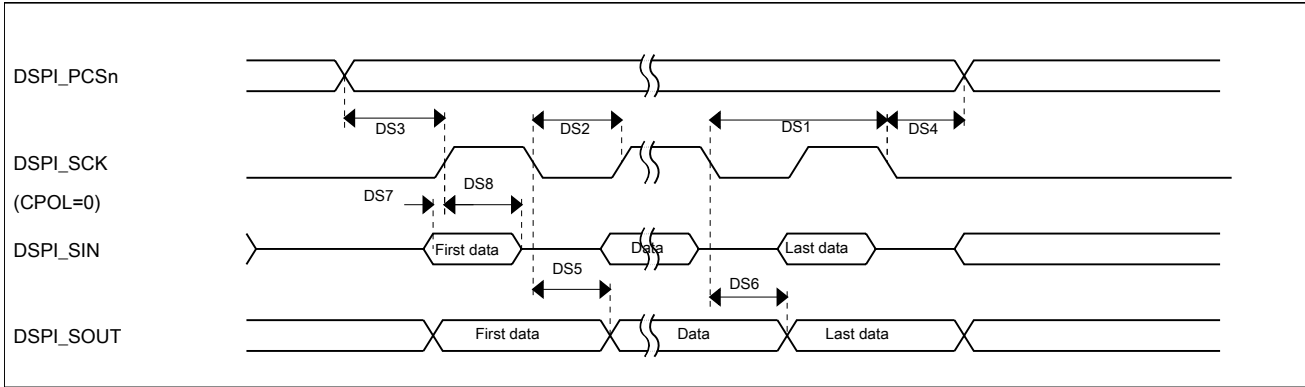


Figure 21. DSPI classic SPI timing — master mode

Table 39. Slave mode DSPI timing (full voltage range)

| Num | Description | Min. | Max. | Unit |
|------|--|--------------------|-------------------|------|
| | Operating voltage | 1.71 | 3.6 | V |
| | Frequency of operation | — | 6.25 | MHz |
| DS9 | DSPI_SCK input cycle time | $8 \times t_{BUS}$ | — | ns |
| DS10 | DSPI_SCK input high/low time | $(t_{SCK}/2) - 4$ | $(t_{SCK}/2) + 4$ | ns |
| DS11 | DSPI_SCK to DSPI_SOUT valid | — | 29.5 | ns |
| DS12 | DSPI_SCK to DSPI_SOUT invalid | 0 | — | ns |
| DS13 | DSPI_SIN to DSPI_SCK input setup | 3.2 | — | ns |
| DS14 | DSPI_SCK to DSPI_SIN input hold | 7 | — | ns |
| DS15 | DSPI_SS active to DSPI_SOUT driven | — | 25 | ns |
| DS16 | DSPI_SS inactive to DSPI_SOUT not driven | — | 25 | ns |

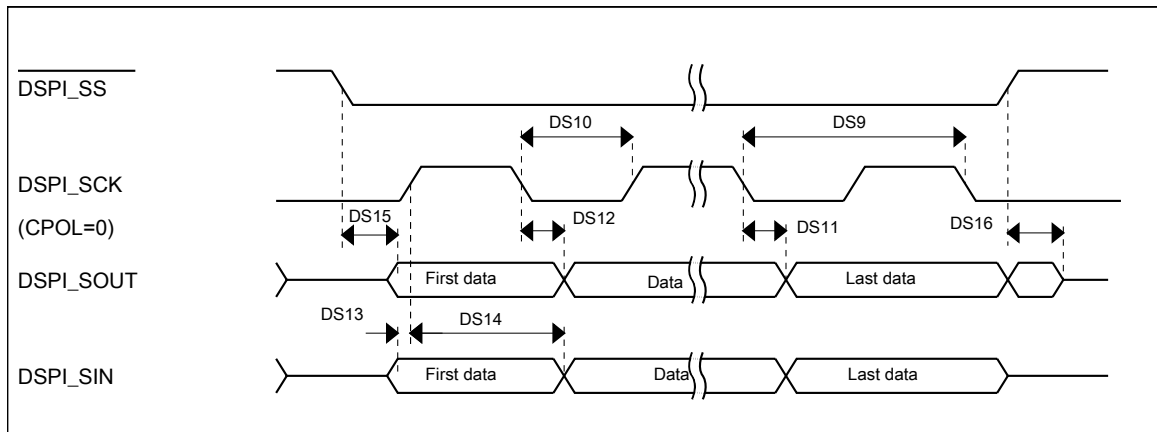


Figure 22. DSPI classic SPI timing — slave mode

3.8.4 Inter-Integrated Circuit Interface (I²C) timing

Table 40. I²C timing

| Characteristic | Symbol | Standard Mode | | Fast Mode | | Unit |
|--|-----------------------|------------------|-------------------|-------------------------------------|------------------|------|
| | | Minimum | Maximum | Minimum | Maximum | |
| SCL Clock Frequency | f _{SCL} | 0 | 100 | 0 | 400 ¹ | kHz |
| Hold time (repeated) START condition. After this period, the first clock pulse is generated. | t _{HD} ; STA | 4 | — | 0.6 | — | μs |
| LOW period of the SCL clock | t _{LOW} | 4.7 | — | 1.25 | — | μs |
| HIGH period of the SCL clock | t _{HIGH} | 4 | — | 0.6 | — | μs |
| Set-up time for a repeated START condition | t _{SU} ; STA | 4.7 | — | 0.6 | — | μs |
| Data hold time for I ² C bus devices | t _{HD} ; DAT | 0 ² | 3.45 ³ | 0 ⁴ | 0.9 ² | μs |
| Data set-up time | t _{SU} ; DAT | 250 ⁵ | — | 100 ^{3, 6} | — | ns |
| Rise time of SDA and SCL signals | t _r | — | 1000 | 20 + 0.1C _b ⁷ | 300 | ns |
| Fall time of SDA and SCL signals | t _f | — | 300 | 20 + 0.1C _b ⁶ | 300 | ns |
| Set-up time for STOP condition | t _{SU} ; STO | 4 | — | 0.6 | — | μs |
| Bus free time between STOP and START condition | t _{BUF} | 4.7 | — | 1.3 | — | μs |
| Pulse width of spikes that must be suppressed by the input filter | t _{SP} | N/A | N/A | 0 | 50 | ns |

1. The maximum SCL Clock Frequency in Fast mode with maximum bus loading can only be achieved when using the High drive pins across the full voltage range and when using the Normal drive pins and VDD ≥ 2.7 V.
2. The master mode I²C deasserts ACK of an address byte simultaneously with the falling edge of SCL. If no slaves acknowledge this address byte, then a negative hold time can result, depending on the edge rates of the SDA and SCL lines.
3. The maximum t_{HD}; DAT must be met only if the device does not stretch the LOW period (t_{LOW}) of the SCL signal.
4. Input signal Slew = 10 ns and Output Load = 50 pF
5. Set-up time in slave-transmitter mode is 1 IPBus clock period, if the TX FIFO is empty.
6. A Fast mode I²C bus device can be used in a Standard mode I²C bus system, but the requirement t_{SU}; DAT ≥ 250 ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, then it must output the next data bit to the SDA line t_{rmax} + t_{SU}; DAT = 1000 + 250 = 1250 ns (according to the Standard mode I²C bus specification) before the SCL line is released.
7. C_b = total capacitance of the one bus line in pF.

Table 41. I²C 1 Mbps timing

| Characteristic | Symbol | Minimum | Maximum | Unit |
|--|-----------------------|---------|----------------|------|
| SCL Clock Frequency | f _{SCL} | 0 | 1 ¹ | MHz |
| Hold time (repeated) START condition. After this period, the first clock pulse is generated. | t _{HD} ; STA | 0.26 | — | μs |
| LOW period of the SCL clock | t _{LOW} | 0.5 | — | μs |
| HIGH period of the SCL clock | t _{HIGH} | 0.26 | — | μs |
| Set-up time for a repeated START condition | t _{SU} ; STA | 0.26 | — | μs |
| Data hold time for I ² C bus devices | t _{HD} ; DAT | 0 | — | μs |

Table continues on the next page...

Table 41. I²C 1 Mbps timing (continued)

| Characteristic | Symbol | Minimum | Maximum | Unit |
|---|---------------|-----------------------|---------|---------|
| Data set-up time | $t_{SU; DAT}$ | 50 | — | ns |
| Rise time of SDA and SCL signals | t_r | $20 + 0.1C_b \cdot 2$ | 120 | ns |
| Fall time of SDA and SCL signals | t_f | $20 + 0.1C_b \cdot 2$ | 120 | ns |
| Set-up time for STOP condition | $t_{SU; STO}$ | 0.26 | — | μ s |
| Bus free time between STOP and START condition | t_{BUF} | 0.5 | — | μ s |
| Pulse width of spikes that must be suppressed by the input filter | t_{SP} | 0 | 50 | ns |

1. The maximum SCL clock frequency of 1 Mbps can support maximum bus loading when using the High drive pins across the full voltage range.
2. C_b = total capacitance of the one bus line in pF.

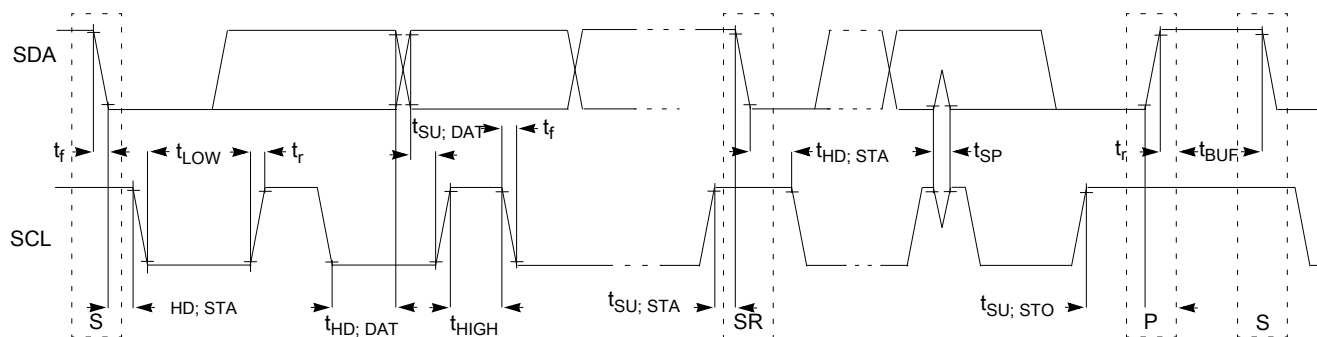


Figure 23. Timing definition for devices on the I²C bus

3.8.5 UART switching specifications

See [General switching specifications](#).

3.8.6 I2S/SAI switching specifications

This section provides the AC timing for the I2S/SAI module in master mode (clocks are driven) and slave mode (clocks are input). All timing is given for noninverted serial clock polarity (TCR2[BCP] is 0, RCR2[BCP] is 0) and a noninverted frame sync (TCR4[FSP] is 0, RCR4[FSP] is 0). If the polarity of the clock and/or the frame sync have been inverted, all the timing remains valid by inverting the bit clock signal (BCLK) and/or the frame sync (FS) signal shown in the following figures.

3.8.6.1 Normal Run, Wait and Stop mode performance over a limited operating voltage range

This section provides the operating performance over a limited operating voltage for the device in Normal Run, Wait and Stop modes.

Table 42. I2S/SAI master mode timing in Normal Run, Wait and Stop modes (limited voltage range)

| Num. | Characteristic | Min. | Max. | Unit |
|------|---|------|------|-------------|
| | Operating voltage | 2.7 | 3.6 | V |
| S1 | I2S_MCLK cycle time | 40 | — | ns |
| S2 | I2S_MCLK pulse width high/low | 45% | 55% | MCLK period |
| S3 | I2S_TX_BCLK/I2S_RX_BCLK cycle time (output) | 80 | — | ns |
| S4 | I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low | 45% | 55% | BCLK period |
| S5 | I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output valid | — | 15 | ns |
| S6 | I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output invalid | 0 | — | ns |
| S7 | I2S_TX_BCLK to I2S_TXD valid | — | 15 | ns |
| S8 | I2S_TX_BCLK to I2S_TXD invalid | 0 | — | ns |
| S9 | I2S_RXD/I2S_RX_FS input setup before I2S_RX_BCLK | 18 | — | ns |
| S10 | I2S_RXD/I2S_RX_FS input hold after I2S_RX_BCLK | 0 | — | ns |

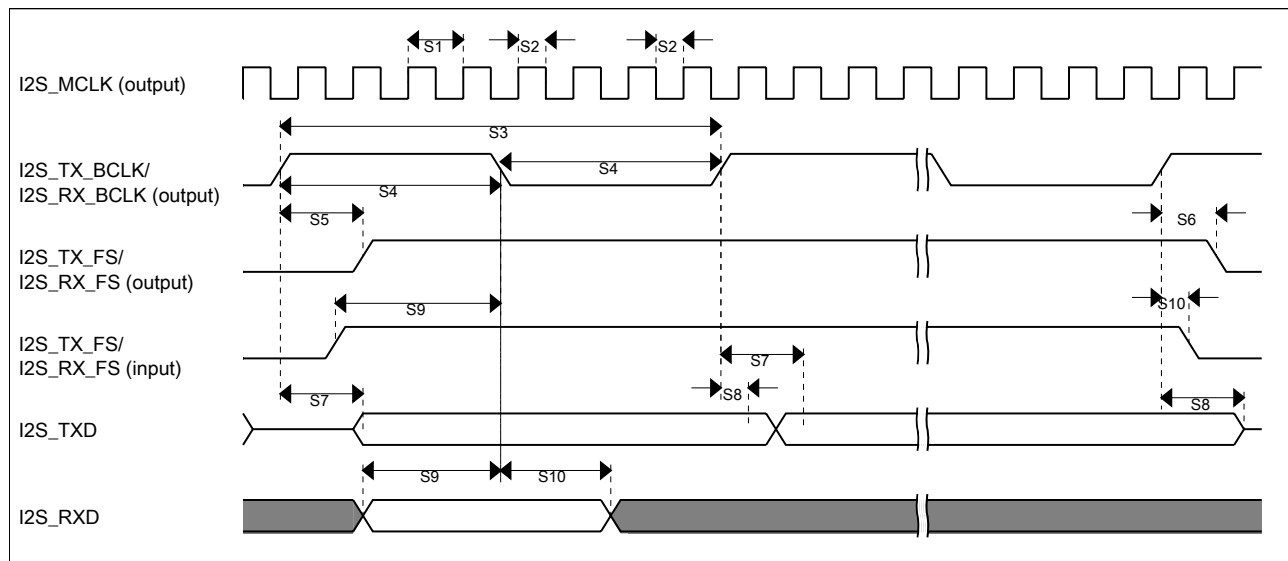


Figure 24. I2S/SAI timing — master modes

Table 43. I2S/SAI slave mode timing in Normal Run, Wait and Stop modes (limited voltage range)

| Num. | Characteristic | Min. | Max. | Unit |
|------|--|------|------|-------------|
| | Operating voltage | 2.7 | 3.6 | V |
| S11 | I2S_TX_BCLK/I2S_RX_BCLK cycle time (input) | 80 | — | ns |
| S12 | I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low (input) | 45% | 55% | MCLK period |
| S13 | I2S_TX_FS/I2S_RX_FS input setup before I2S_TX_BCLK/I2S_RX_BCLK | 4.5 | — | ns |
| S14 | I2S_TX_FS/I2S_RX_FS input hold after I2S_TX_BCLK/I2S_RX_BCLK | 2 | — | ns |
| S15 | I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output valid | — | 20 | ns |
| S16 | I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output invalid | 0 | — | ns |
| S17 | I2S_RXD setup before I2S_RX_BCLK | 4.5 | — | ns |
| S18 | I2S_RXD hold after I2S_RX_BCLK | 2 | — | ns |
| S19 | I2S_TX_FS input assertion to I2S_TXD output valid ¹ | — | 25 | ns |

1. Applies to first bit in each frame and only if the TCR4[FSE] bit is clear

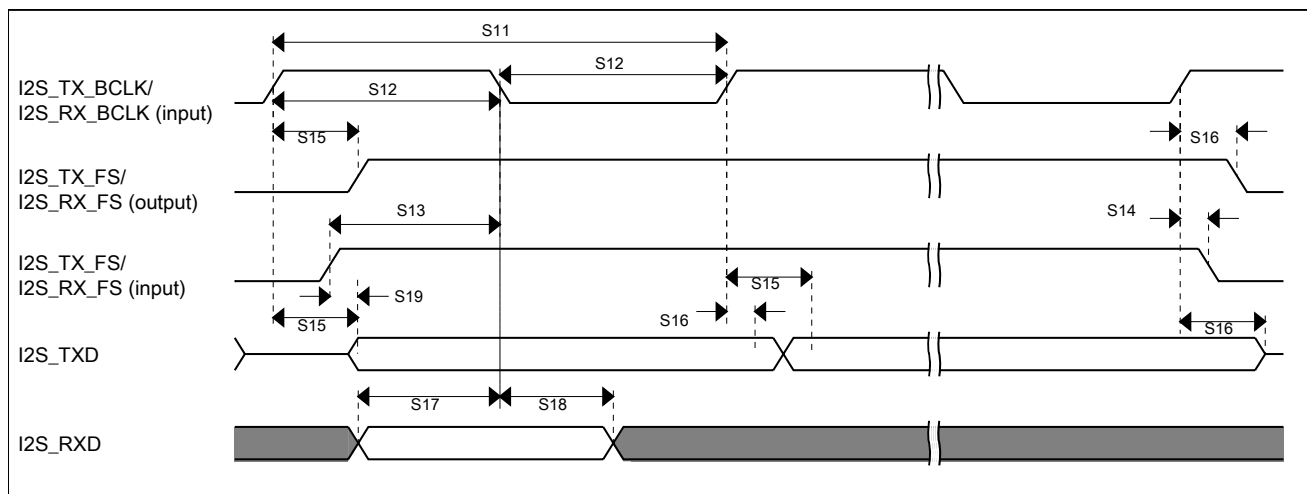


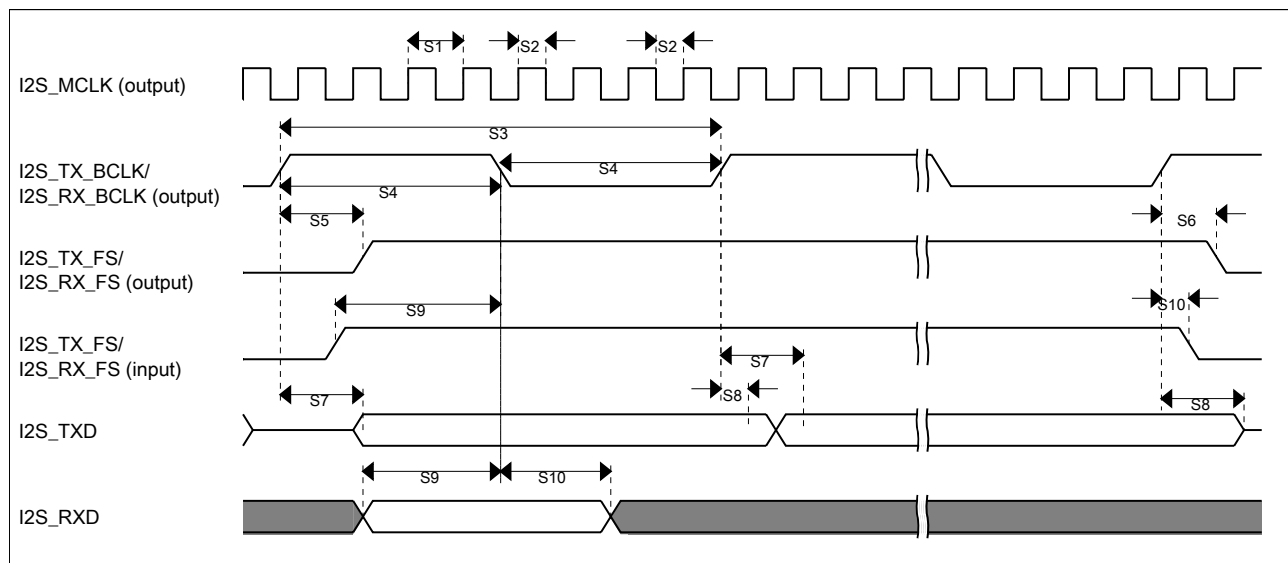
Figure 25. I2S/SAI timing — slave modes

3.8.6.2 Normal Run, Wait and Stop mode performance over the full operating voltage range

This section provides the operating performance over the full operating voltage for the device in Normal Run, Wait and Stop modes.

Table 44. I2S/SAI master mode timing in Normal Run, Wait and Stop modes (full voltage range)

| Num. | Characteristic | Min. | Max. | Unit |
|------|---|------|------|-------------|
| | Operating voltage | 1.71 | 3.6 | V |
| S1 | I2S_MCLK cycle time | 40 | — | ns |
| S2 | I2S_MCLK pulse width high/low | 45% | 55% | MCLK period |
| S3 | I2S_TX_BCLK/I2S_RX_BCLK cycle time (output) | 80 | — | ns |
| S4 | I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low | 45% | 55% | BCLK period |
| S5 | I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output valid | — | 15 | ns |
| S6 | I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output invalid | -1.0 | — | ns |
| S7 | I2S_TX_BCLK to I2S_TXD valid | — | 15 | ns |
| S8 | I2S_TX_BCLK to I2S_TXD invalid | 0 | — | ns |
| S9 | I2S_RXD/I2S_RX_FS input setup before I2S_RX_BCLK | 27 | — | ns |
| S10 | I2S_RXD/I2S_RX_FS input hold after I2S_RX_BCLK | 0 | — | ns |

**Figure 26. I2S/SAI timing — master modes****Table 45. I2S/SAI slave mode timing in Normal Run, Wait and Stop modes (full voltage range)**

| Num. | Characteristic | Min. | Max. | Unit |
|------|--|------|------|------|
| | Operating voltage | 1.71 | 3.6 | V |
| S11 | I2S_TX_BCLK/I2S_RX_BCLK cycle time (input) | 80 | — | ns |

Table continues on the next page...

Table 45. I2S/SAI slave mode timing in Normal Run, Wait and Stop modes (full voltage range) (continued)

| Num. | Characteristic | Min. | Max. | Unit |
|------|--|------|------|-------------|
| S12 | I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low (input) | 45% | 55% | MCLK period |
| S13 | I2S_TX_FS/I2S_RX_FS input setup before I2S_TX_BCLK/I2S_RX_BCLK | 5.8 | — | ns |
| S14 | I2S_TX_FS/I2S_RX_FS input hold after I2S_TX_BCLK/I2S_RX_BCLK | 2 | — | ns |
| S15 | I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output valid | — | 28.5 | ns |
| S16 | I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output invalid | 0 | — | ns |
| S17 | I2S_RXD setup before I2S_RX_BCLK | 5.8 | — | ns |
| S18 | I2S_RXD hold after I2S_RX_BCLK | 2 | — | ns |
| S19 | I2S_TX_FS input assertion to I2S_TXD output valid ¹ | — | 26.3 | ns |

1. Applies to first bit in each frame and only if the TCR4[FSE] bit is clear

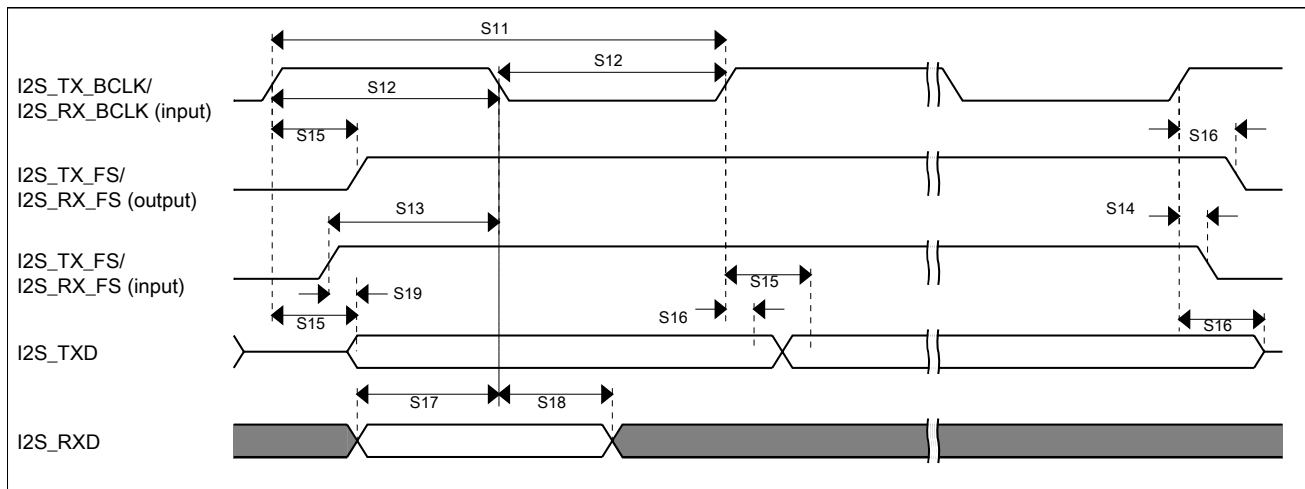


Figure 27. I2S/SAI timing — slave modes

3.8.6.3 VLPR, VLPW, and VLPS mode performance over the full operating voltage range

This section provides the operating performance over the full operating voltage for the device in VLPR, VLPW, and VLPS modes.

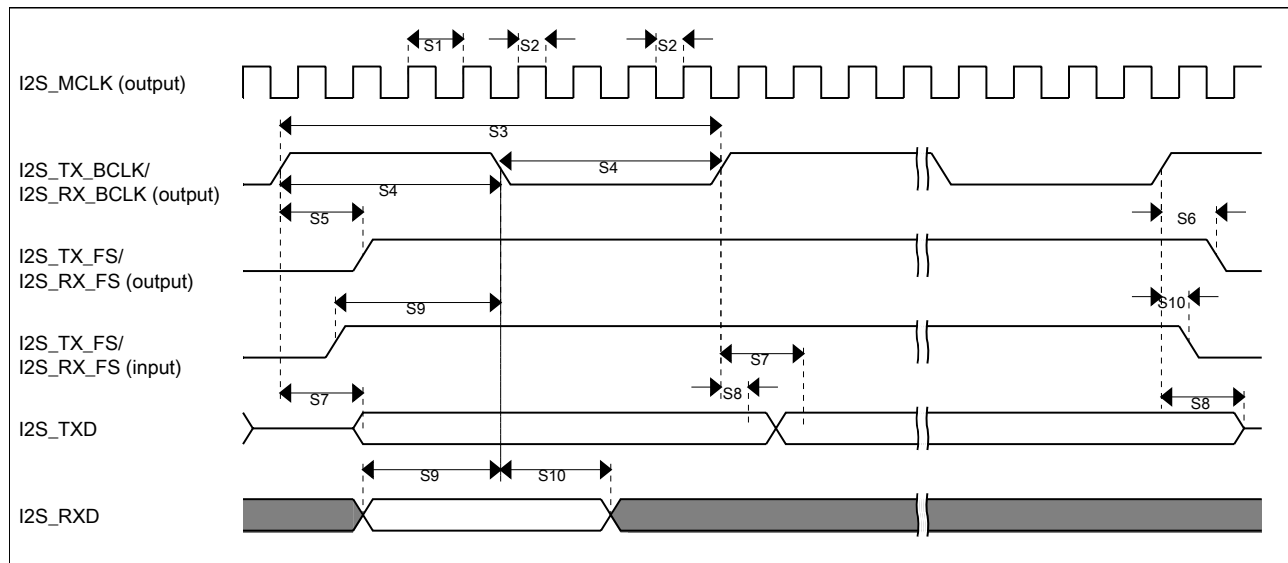
Table 46. I2S/SAI master mode timing in VLPR, VLPW, and VLPS modes (full voltage range)

| Num. | Characteristic | Min. | Max. | Unit |
|------|-------------------|------|------|------|
| | Operating voltage | 1.71 | 3.6 | V |

Table continues on the next page...

Table 46. I2S/SAI master mode timing in VLPR, VLPW, and VLPS modes (full voltage range) (continued)

| Num. | Characteristic | Min. | Max. | Unit |
|------|---|------|------|-------------|
| S1 | I2S_MCLK cycle time | 62.5 | — | ns |
| S2 | I2S_MCLK pulse width high/low | 45% | 55% | MCLK period |
| S3 | I2S_TX_BCLK/I2S_RX_BCLK cycle time (output) | 250 | — | ns |
| S4 | I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low | 45% | 55% | BCLK period |
| S5 | I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output valid | — | 45 | ns |
| S6 | I2S_TX_BCLK/I2S_RX_BCLK to I2S_TX_FS/ I2S_RX_FS output invalid | -1 | — | ns |
| S7 | I2S_TX_BCLK to I2S_TXD valid | — | 45 | ns |
| S8 | I2S_TX_BCLK to I2S_TXD invalid | 0 | — | ns |
| S9 | I2S_RXD/I2S_RX_FS input setup before I2S_RX_BCLK | 45 | — | ns |
| S10 | I2S_RXD/I2S_RX_FS input hold after I2S_RX_BCLK | 0 | — | ns |

**Figure 28. I2S/SAI timing — master modes****Table 47. I2S/SAI slave mode timing in VLPR, VLPW, and VLPS modes (full voltage range)**

| Num. | Characteristic | Min. | Max. | Unit |
|------|--|------|------|-------------|
| | Operating voltage | 1.71 | 3.6 | V |
| S11 | I2S_TX_BCLK/I2S_RX_BCLK cycle time (input) | 250 | — | ns |
| S12 | I2S_TX_BCLK/I2S_RX_BCLK pulse width high/low (input) | 45% | 55% | MCLK period |

Table continues on the next page...

Table 47. I2S/SAI slave mode timing in VLPR, VLPW, and VLPS modes (full voltage range) (continued)

| Num. | Characteristic | Min. | Max. | Unit |
|------|--|------|------|------|
| S13 | I2S_TX_FS/I2S_RX_FS input setup before I2S_TX_BCLK/I2S_RX_BCLK | 30 | — | ns |
| S14 | I2S_TX_FS/I2S_RX_FS input hold after I2S_TX_BCLK/I2S_RX_BCLK | 7 | — | ns |
| S15 | I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output valid | — | 63 | ns |
| S16 | I2S_TX_BCLK to I2S_TXD/I2S_TX_FS output invalid | 0 | — | ns |
| S17 | I2S_RXD setup before I2S_RX_BCLK | 30 | — | ns |
| S18 | I2S_RXD hold after I2S_RX_BCLK | 4 | — | ns |
| S19 | I2S_TX_FS input assertion to I2S_TXD output valid ¹ | — | 72 | ns |

1. Applies to first bit in each frame and only if the TCR4[FSE] bit is clear

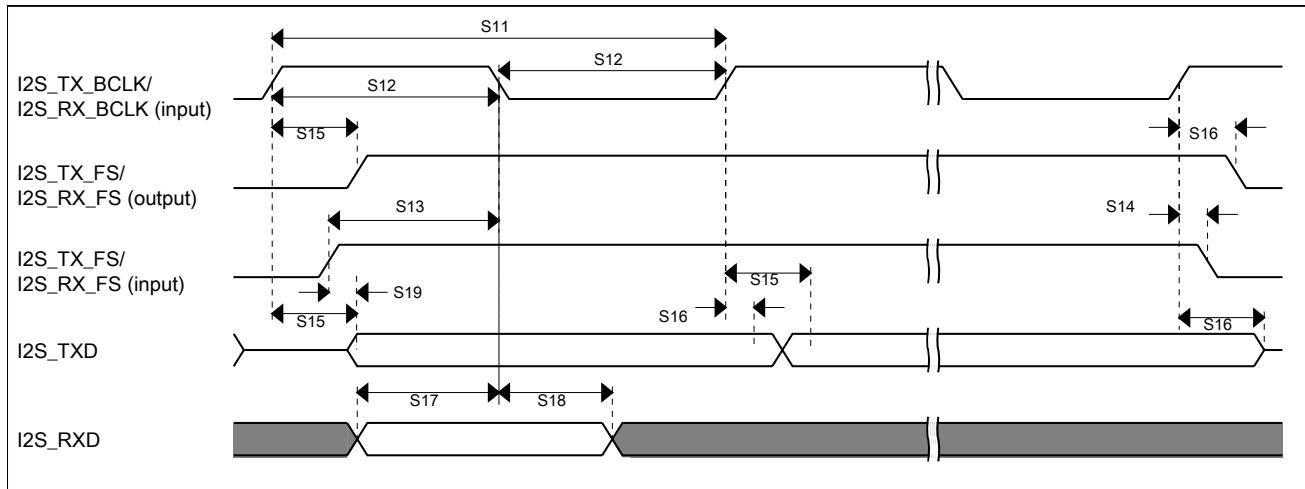


Figure 29. I2S/SAI timing — slave modes

4 Dimensions

4.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to nxp.com and perform a keyword search for the drawing's document number:

| If you want the drawing for this package | Then use this document number |
|--|-------------------------------|
| 64-pin LQFP | 98ASS23234W |
| 64-pin MAPBGA | 98ASA00420D |
| 100-pin LQFP | 98ASS23308W |
| 121-pin XFBGA | 98ASA00595D |

5 Pinout

5.1 K22 Signal Multiplexing and Pin Assignments

The following table shows the signals available on each pin and the locations of these pins on the devices supported by this document. The Port Control Module is responsible for selecting which ALT functionality is available on each pin.

| 121 BGA | 100 LQFP | 64 LQFP | 64 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|---------|----------|---------|------------|------------------------|---------------|---------------|------------------------|---------------|-------------------|---------------|------|----------|-----------------|--------|
| E4 | 1 | 1 | A1 | PTE0/ CLKOUT32 K | ADC1_ SE4a | ADC1_ SE4a | PTE0/ CLKOUT32 K | SPI1_ PCS1 | UART1_TX | | | I2C1_SDA | RTC_ CLKOUT | |
| E3 | 2 | 2 | B1 | PTE1/ LLWU_P0 | ADC1_ SE5a | ADC1_ SE5a | PTE1/ LLWU_P0 | SPI1_ SOUT | UART1_RX | | | I2C1_SCL | SPI1_SIN | |
| E2 | 3 | — | — | PTE2/ LLWU_P1 | ADC1_ SE6a | ADC1_ SE6a | PTE2/ LLWU_P1 | SPI1_SCK | UART1_ CTS_b | | | | | |
| F4 | 4 | — | — | PTE3 | ADC1_ SE7a | ADC1_ SE7a | PTE3 | SPI1_SIN | UART1_ RTS_b | | | | SPI1_ SOUT | |
| H7 | 5 | — | — | PTE4/ LLWU_P2 | DISABLED | | PTE4/ LLWU_P2 | SPI1_ PCS0 | LPUART0_ TX | | | | | |
| G4 | 6 | — | — | PTE5 | DISABLED | | PTE5 | SPI1_ PCS2 | LPUART0_ RX | | | | | |
| F3 | 7 | — | — | PTE6 | DISABLED | | PTE6 | SPI1_ PCS3 | LPUART0_ CTS_b | I2S0_ MCLK | | | USB_SOF_ OUT | |
| E6 | 8 | 3 | C5 | VDD | VDD | VDD | | | | | | | | |
| G7 | 9 | 4 | C4 | VSS | VSS | VSS | | | | | | | | |
| L6 | — | — | — | VSS | VSS | VSS | | | | | | | | |
| F1 | 10 | 5 | E1 | USB0_DP | USB0_DP | USB0_DP | | | | | | | | |
| F2 | 11 | 6 | D1 | USB0_DM | USB0_DM | USB0_DM | | | | | | | | |
| G1 | 12 | 7 | E2 | USBVDD | USBVDD | USBVDD | | | | | | | | |
| G2 | 13 | 8 | D2 | NC | NC | NC | | | | | | | | |
| H1 | 14 | — | — | ADC0_DP1 | ADC0_DP1 | ADC0_DP1 | | | | | | | | |

Pinout

| 121 BGA | 100 LQFP | 64 LQFP | 64 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|---------|----------|---------|------------|--|--|--|-------|------|------|------|----------|-----------|------|--------|
| H2 | 15 | — | — | ADC0_DM1 | ADC0_DM1 | ADC0_DM1 | | | | | | | | |
| J1 | 16 | — | — | ADC1_DP1/ ADC0_DP2 | ADC1_DP1/ ADC0_DP2 | ADC1_DP1/ ADC0_DP2 | | | | | | | | |
| J2 | 17 | — | — | ADC1_DM1/ ADC0_DM2 | ADC1_DM1/ ADC0_DM2 | ADC1_DM1/ ADC0_DM2 | | | | | | | | |
| K1 | 18 | 9 | G1 | ADC0_DP0/ ADC1_DP3 | ADC0_DP0/ ADC1_DP3 | ADC0_DP0/ ADC1_DP3 | | | | | | | | |
| K2 | 19 | 10 | F1 | ADC0_DM0/ ADC1_DM3 | ADC0_DM0/ ADC1_DM3 | ADC0_DM0/ ADC1_DM3 | | | | | | | | |
| L1 | 20 | 11 | G2 | ADC1_DP0/ ADC0_DP3 | ADC1_DP0/ ADC0_DP3 | ADC1_DP0/ ADC0_DP3 | | | | | | | | |
| L2 | 21 | 12 | F2 | ADC1_DM0/ ADC0_DM3 | ADC1_DM0/ ADC0_DM3 | ADC1_DM0/ ADC0_DM3 | | | | | | | | |
| F5 | 22 | 13 | F4 | VDDA | VDDA | VDDA | | | | | | | | |
| G5 | 23 | 14 | G4 | VREFH | VREFH | VREFH | | | | | | | | |
| G6 | 24 | 15 | G3 | VREFL | VREFL | VREFL | | | | | | | | |
| F6 | 25 | 16 | F3 | VSSA | VSSA | VSSA | | | | | | | | |
| L3 | 26 | 17 | H1 | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | | | | | | | | |
| K5 | 27 | 18 | H2 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | | | | | | | | |
| K4 | — | — | — | CMP0_IN4/ ADC1_SE23 | CMP0_IN4/ ADC1_SE23 | CMP0_IN4/ ADC1_SE23 | | | | | | | | |
| L4 | 28 | 19 | H3 | XTAL32 | XTAL32 | XTAL32 | | | | | | | | |
| L5 | 29 | 20 | H4 | EXTAL32 | EXTAL32 | EXTAL32 | | | | | | | | |
| K6 | 30 | 21 | H5 | VBAT | VBAT | VBAT | | | | | | | | |
| H5 | 31 | — | — | PTE24 | ADC0_SE17 | ADC0_SE17 | PTE24 | | | | I2C0_SCL | EWM_OUT_b | | |

| 121 BGA | 100 LQFP | 64 LQFP | 64 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|---------|----------|---------|------------|-------------------------|-----------------------------------|-----------------------|-------------------------|-------------|-------------|------------|----------|--------------|------------------------|----------|
| J5 | 32 | — | — | PTE25 | ADC0_SE18 | ADC0_SE18 | PTE25 | | | | I2C0_SDA | EWM_IN | | |
| H6 | 33 | — | — | PTE26/ CLKOUT32 K | DISABLED | | PTE26/ CLKOUT32 K | | | | | RTC_CLKOUT | USB_CLKIN | |
| J6 | 34 | 22 | D3 | PTA0 | JTAG_TCLK/ SWD_CLK/ EZP_CLK | | PTA0 | UART0_CTS_b | FTM0_CH5 | | | | JTAG_TCLK/ SWD_CLK | EZP_CLK |
| H8 | 35 | 23 | D4 | PTA1 | JTAG_TDI/ EZP_DI | | PTA1 | UART0_RX | FTM0_CH6 | | | | JTAG_TDI | EZP_DI |
| J7 | 36 | 24 | E5 | PTA2 | JTAG_TDO/ TRACE_SWO/ EZP_DO | | PTA2 | UART0_TX | FTM0_CH7 | | | | JTAG_TDO/ TRACE_SWO | EZP_DO |
| H9 | 37 | 25 | D5 | PTA3 | JTAG_TMS/ SWD_DIO | | PTA3 | UART0_RTS_b | FTM0_CH0 | | | | JTAG_TMS/ SWD_DIO | |
| J8 | 38 | 26 | G5 | PTA4/ LLWU_P3 | NMI_b/ EZP_CS_b | | PTA4/ LLWU_P3 | | FTM0_CH1 | | | | NMI_b | EZP_CS_b |
| K7 | 39 | 27 | F5 | PTA5 | DISABLED | | PTA5 | USB_CLKIN | FTM0_CH2 | | | I2S0_TX_BCLK | JTAG_TRST_b | |
| E5 | 40 | — | — | VDD | VDD | VDD | | | | | | | | |
| G3 | 41 | — | — | VSS | VSS | VSS | | | | | | | | |
| K8 | 42 | 28 | H6 | PTA12 | DISABLED | | PTA12 | | FTM1_CH0 | | | I2S0_TXD0 | FTM1_QD_PHA | |
| L8 | 43 | 29 | G6 | PTA13/ LLWU_P4 | DISABLED | | PTA13/ LLWU_P4 | | FTM1_CH1 | | | I2S0_TX_FS | FTM1_QD_PHB | |
| K9 | 44 | — | — | PTA14 | DISABLED | | PTA14 | SPI0_PCS0 | UART0_TX | | | I2S0_RX_BCLK | | |
| L9 | 45 | — | — | PTA15 | DISABLED | | PTA15 | SPI0_SCK | UART0_RX | | | I2S0_RXD0 | | |
| J10 | 46 | — | — | PTA16 | DISABLED | | PTA16 | SPI0_SOUT | UART0_CTS_b | | | I2S0_RX_FS | | |
| H10 | 47 | — | — | PTA17 | ADC1_SE17 | ADC1_SE17 | PTA17 | SPI0_SIN | UART0_RTS_b | | | I2S0_MCLK | | |
| L10 | 48 | 30 | G7 | VDD | VDD | VDD | | | | | | | | |
| K10 | 49 | 31 | H7 | VSS | VSS | VSS | | | | | | | | |
| L11 | 50 | 32 | H8 | PTA18 | EXTAL0 | EXTAL0 | PTA18 | | FTM0_FLT2 | FTM_CLKIN0 | | | | |
| K11 | 51 | 33 | G8 | PTA19 | XTAL0 | XTAL0 | PTA19 | | FTM1_FLT0 | FTM_CLKIN1 | | LPTMR0_ALT1 | | |
| J11 | 52 | 34 | F8 | RESET_b | RESET_b | RESET_b | | | | | | | | |
| G11 | 53 | 35 | F7 | PTB0/ LLWU_P5 | ADC0_SE8/ ADC1_SE8 | ADC0_SE8/ ADC1_SE8 | PTB0/ LLWU_P5 | I2C0_SCL | FTM1_CH0 | | | FTM1_QD_PHA | | |

Pinout

| 121 BGA | 100 LQFP | 64 LQFP | 64 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|---------|----------|---------|------------|--------------|------------------------|------------------------|--------------|-----------|---------------|--------------|--------|--------------|---------------|--------|
| G10 | 54 | 36 | F6 | PTB1 | ADC0_SE9/ ADC1_SE9 | ADC0_SE9/ ADC1_SE9 | PTB1 | I2C0_SDA | FTM1_CH1 | | | FTM1_QD_PHB | | |
| G9 | 55 | 37 | E7 | PTB2 | ADC0_SE12 | ADC0_SE12 | PTB2 | I2C0_SCL | UART0_RTS_b | | | FTM0_FLT3 | | |
| G8 | 56 | 38 | E8 | PTB3 | ADC0_SE13 | ADC0_SE13 | PTB3 | I2C0_SDA | UART0_CTS_b | | | FTM0_FLT0 | | |
| D11 | — | — | — | PTB8 | DISABLED | | PTB8 | | LPUART0_RTS_b | | | | | |
| E10 | 57 | — | — | PTB9 | DISABLED | | PTB9 | SPI1_PCS1 | LPUART0_CTS_b | | | | | |
| D10 | 58 | — | — | PTB10 | ADC1_SE14 | ADC1_SE14 | PTB10 | SPI1_PCS0 | LPUART0_RX | | | FTM0_FLT1 | | |
| C10 | 59 | — | — | PTB11 | ADC1_SE15 | ADC1_SE15 | PTB11 | SPI1_SCK | LPUART0_TX | | | FTM0_FLT2 | | |
| — | 60 | — | — | VSS | VSS | VSS | | | | | | | | |
| — | 61 | — | — | VDD | VDD | VDD | | | | | | | | |
| B10 | 62 | 39 | E6 | PTB16 | DISABLED | | PTB16 | SPI1_SOUT | UART0_RX | FTM_CLKIN0 | | EWM_IN | | |
| E9 | 63 | 40 | D7 | PTB17 | DISABLED | | PTB17 | SPI1_SIN | UART0_TX | FTM_CLKIN1 | | EWM_OUT_b | | |
| D9 | 64 | 41 | D6 | PTB18 | DISABLED | | PTB18 | | FTM2_CH0 | I2S0_TX_BCLK | | FTM2_QD_PHA | | |
| C9 | 65 | 42 | C7 | PTB19 | DISABLED | | PTB19 | | FTM2_CH1 | I2S0_TX_FS | | FTM2_QD_PHB | | |
| F10 | 66 | — | — | PTB20 | DISABLED | | PTB20 | | | | | CMP0_OUT | | |
| F9 | 67 | — | — | PTB21 | DISABLED | | PTB21 | | | | | CMP1_OUT | | |
| F8 | 68 | — | — | PTB22 | DISABLED | | PTB22 | | | | | | | |
| E8 | 69 | — | — | PTB23 | DISABLED | | PTB23 | | SPI0_PCS5 | | | | | |
| B9 | 70 | 43 | D8 | PTC0 | ADC0_SE14 | ADC0_SE14 | PTC0 | SPI0_PCS4 | PDB0_EXTRG | USB_SOF_OUT | | | | |
| D8 | 71 | 44 | C6 | PTC1/LLWU_P6 | ADC0_SE15 | ADC0_SE15 | PTC1/LLWU_P6 | SPI0_PCS3 | UART1_RTS_b | FTM0_CH0 | | I2S0_TXD0 | LPUART0_RTS_b | |
| C8 | 72 | 45 | B7 | PTC2 | ADC0_SE4b/ CMP1_IN0 | ADC0_SE4b/ CMP1_IN0 | PTC2 | SPI0_PCS2 | UART1_CTS_b | FTM0_CH1 | | I2S0_TX_FS | LPUART0_CTS_b | |
| B8 | 73 | 46 | C8 | PTC3/LLWU_P7 | CMP1_IN1 | CMP1_IN1 | PTC3/LLWU_P7 | SPI0_PCS1 | UART1_RX | FTM0_CH2 | CLKOUT | I2S0_TX_BCLK | LPUART0_RX | |
| — | 74 | 47 | E3 | VSS | VSS | VSS | | | | | | | | |
| — | 75 | 48 | E4 | VDD | VDD | VDD | | | | | | | | |
| A8 | 76 | 49 | B8 | PTC4/LLWU_P8 | DISABLED | | PTC4/LLWU_P8 | SPI0_PCS0 | UART1_TX | FTM0_CH3 | | CMP1_OUT | LPUART0_TX | |

| 121 BGA | 100 LQFP | 64 LQFP | 64 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|---------|----------|---------|------------|--------------------|----------------------------|----------------------------|--------------------|---------------|-------------------|------------------|------|-------------------|---------------|--------|
| D7 | 77 | 50 | A8 | PTC5/ LLWU_P9 | DISABLED | | PTC5/ LLWU_P9 | SPI0_SCK | LPTMR0_ ALT2 | I2S0_RXD0 | | CMP0_ OUT | FTM0_CH2 | |
| C7 | 78 | 51 | A7 | PTC6/ LLWU_P10 | CMP0_IN0 | CMP0_IN0 | PTC6/ LLWU_P10 | SPI0_ SOUT | PDB0_ EXTRG | I2S0_RX_ BCLK | | I2S0_ MCLK | | |
| B7 | 79 | 52 | B6 | PTC7 | CMP0_IN1 | CMP0_IN1 | PTC7 | SPI0_SIN | USB_SOF_ OUT | I2S0_RX_ FS | | | | |
| A7 | 80 | 53 | A6 | PTC8 | ADC1_ SE4b/ CMP0_IN2 | ADC1_ SE4b/ CMP0_IN2 | PTC8 | | | I2S0_ MCLK | | | | |
| D6 | 81 | 54 | B5 | PTC9 | ADC1_ SE5b/ CMP0_IN3 | ADC1_ SE5b/ CMP0_IN3 | PTC9 | | | I2S0_RX_ BCLK | | FTM2_ FLT0 | | |
| C6 | 82 | 55 | B4 | PTC10 | ADC1_ SE6b | ADC1_ SE6b | PTC10 | I2C1_SCL | | I2S0_RX_ FS | | | | |
| C5 | 83 | 56 | A5 | PTC11/ LLWU_P11 | ADC1_ SE7b | ADC1_ SE7b | PTC11/ LLWU_P11 | I2C1_SDA | | | | | | |
| B6 | 84 | — | — | PTC12 | DISABLED | | PTC12 | | | | | | | |
| A6 | 85 | — | — | PTC13 | DISABLED | | PTC13 | | | | | | | |
| A5 | 86 | — | — | PTC14 | DISABLED | | PTC14 | | | | | | | |
| B5 | 87 | — | — | PTC15 | DISABLED | | PTC15 | | | | | | | |
| F7 | 88 | — | — | VSS | VSS | VSS | | | | | | | | |
| E7 | 89 | — | — | VDD | VDD | VDD | | | | | | | | |
| D5 | 90 | — | — | PTC16 | DISABLED | | PTC16 | | LPUART0_ RX | | | | | |
| C4 | 91 | — | — | PTC17 | DISABLED | | PTC17 | | LPUART0_ TX | | | | | |
| B4 | 92 | — | — | PTC18 | DISABLED | | PTC18 | | LPUART0_ RTS_b | | | | | |
| D4 | 93 | 57 | C3 | PTD0/ LLWU_P12 | DISABLED | | PTD0/ LLWU_P12 | SPI0_ PCS0 | UART2_ RTS_b | | | LPUART0_ RTS_b | | |
| D3 | 94 | 58 | A4 | PTD1 | ADC0_ SE5b | ADC0_ SE5b | PTD1 | SPI0_SCK | UART2_ CTS_b | | | LPUART0_ CTS_b | | |
| C3 | 95 | 59 | C2 | PTD2/ LLWU_P13 | DISABLED | | PTD2/ LLWU_P13 | SPI0_ SOUT | UART2_RX | | | LPUART0_ RX | I2C0_SCL | |
| B3 | 96 | 60 | B3 | PTD3 | DISABLED | | PTD3 | SPI0_SIN | UART2_TX | | | LPUART0_ TX | I2C0_SDA | |
| A3 | 97 | 61 | A3 | PTD4/ LLWU_P14 | DISABLED | | PTD4/ LLWU_P14 | SPI0_ PCS1 | UART0_ RTS_b | FTM0_CH4 | | EWM_IN | SPI1_ PCS0 | |
| A2 | 98 | 62 | C1 | PTD5 | ADC0_ SE6b | ADC0_ SE6b | PTD5 | SPI0_ PCS2 | UART0_ CTS_b | FTM0_CH5 | | EWM_ OUT_b | SPI1_SCK | |
| B2 | 99 | 63 | B2 | PTD6/ LLWU_P15 | ADC0_ SE7b | ADC0_ SE7b | PTD6/ LLWU_P15 | SPI0_ PCS3 | UART0_RX | FTM0_CH6 | | FTM0_ FLT0 | SPI1_ SOUT | |
| A1 | 100 | 64 | A2 | PTD7 | DISABLED | | PTD7 | | UART0_TX | FTM0_CH7 | | FTM0_ FLT1 | SPI1_SIN | |
| A11 | — | — | — | NC | NC | NC | | | | | | | | |

Pinout

| 121 BGA | 100 LQFP | 64 LQFP | 64 MAP BGA | Pin Name | Default | ALT0 | ALT1 | ALT2 | ALT3 | ALT4 | ALT5 | ALT6 | ALT7 | EzPort |
|---------|----------|---------|------------|----------|---------|------|------|------|------|------|------|------|------|--------|
| K3 | — | — | — | NC | NC | NC | | | | | | | | |
| H4 | — | — | — | NC | NC | NC | | | | | | | | |
| B11 | — | — | — | NC | NC | NC | | | | | | | | |
| C11 | — | — | — | NC | NC | NC | | | | | | | | |
| H11 | — | — | — | NC | NC | NC | | | | | | | | |
| C1 | — | — | — | NC | NC | NC | | | | | | | | |
| D2 | — | — | — | NC | NC | NC | | | | | | | | |
| D1 | — | — | — | NC | NC | NC | | | | | | | | |
| E1 | — | — | — | NC | NC | NC | | | | | | | | |
| J3 | — | — | — | NC | NC | NC | | | | | | | | |
| H3 | — | — | — | NC | NC | NC | | | | | | | | |
| J9 | — | — | — | NC | NC | NC | | | | | | | | |
| J4 | — | — | — | NC | NC | NC | | | | | | | | |
| A10 | — | — | — | NC | NC | NC | | | | | | | | |
| A9 | — | — | — | NC | NC | NC | | | | | | | | |
| B1 | — | — | — | NC | NC | NC | | | | | | | | |
| C2 | — | — | — | NC | NC | NC | | | | | | | | |
| L7 | — | — | — | NC | NC | NC | | | | | | | | |
| F11 | — | — | — | NC | NC | NC | | | | | | | | |
| E11 | — | — | — | NC | NC | NC | | | | | | | | |
| A4 | — | — | — | NC | NC | NC | | | | | | | | |

5.2 Recommended connection for unused analog and digital pins

The following table shows the recommended connections for analog interface pins if those analog interfaces are not used in the customer's application.

Table 48. Recommended connection for unused analog interfaces

| Pin Type | | Short recommendation | Detailed recommendation |
|-----------------|--------------|----------------------|-------------------------|
| Analog/non GPIO | PGAx/ADCx | Float | Analog input - Float |
| Analog/non GPIO | ADCx/CMPx | Float | Analog input - Float |
| Analog/non GPIO | VREF_OUT | Float | Analog output - Float |
| Analog/non GPIO | DACx_OUT | Float | Analog output - Float |
| Analog/non GPIO | RTC_WAKEUP_B | Float | Analog output - Float |
| Analog/non GPIO | XTAL32 | Float | Analog output - Float |
| Analog/non GPIO | EXTAL32 | Float | Analog input - Float |

Table continues on the next page...

Table 48. Recommended connection for unused analog interfaces (continued)

| Pin Type | | Short recommendation | Detailed recommendation |
|--------------|----------------|--|--|
| GPIO/Analog | PTA18/EXTAL0 | Float | Analog input - Float |
| GPIO/Analog | PTA19/XTAL0 | Float | Analog output - Float |
| GPIO/Analog | PTx/ADCx | Float | Float (default is analog input) |
| GPIO/Analog | PTx/CMPx | Float | Float (default is analog input) |
| GPIO/Digital | PTA0/JTAG_TCLK | Float | Float (default is JTAG with pulldown) |
| GPIO/Digital | PTA1/JTAG_TDI | Float | Float (default is JTAG with pullup) |
| GPIO/Digital | PTA2/JTAG_TDO | Float | Float (default is JTAG with pullup) |
| GPIO/Digital | PTA3/JTAG_TMS | Float | Float (default is JTAG with pullup) |
| GPIO/Digital | PTA4/NMI_b | 10k Ω pullup or disable and float | Pull high or disable in PCR & FOPT and float |
| GPIO/Digital | PTx | Float | Float (default is disabled) |
| USB | USB0_DP | Float | Float |
| USB | USB0_DM | Float | Float |
| USB | USBVDD | Tie to ground through 10k Ω | Tie to ground through 10k Ω |
| VBAT | VBAT | Float | Float |
| VDDA | VDDA | Always connect to VDD potential | Always connect to VDD potential |
| VREFH | VREFH | Always connect to VDD potential | Always connect to VDD potential |
| VREFL | VREFL | Always connect to VSS potential | Always connect to VSS potential |
| VSSA | VSSA | Always connect to VSS potential | Always connect to VSS potential |

5.3 K22 Pinouts

This figure shows the pinout diagram for the devices supported by this document. Many signals may be multiplexed onto a single pin. To determine what signals can be used on which pin, see the previous section.

Pinout

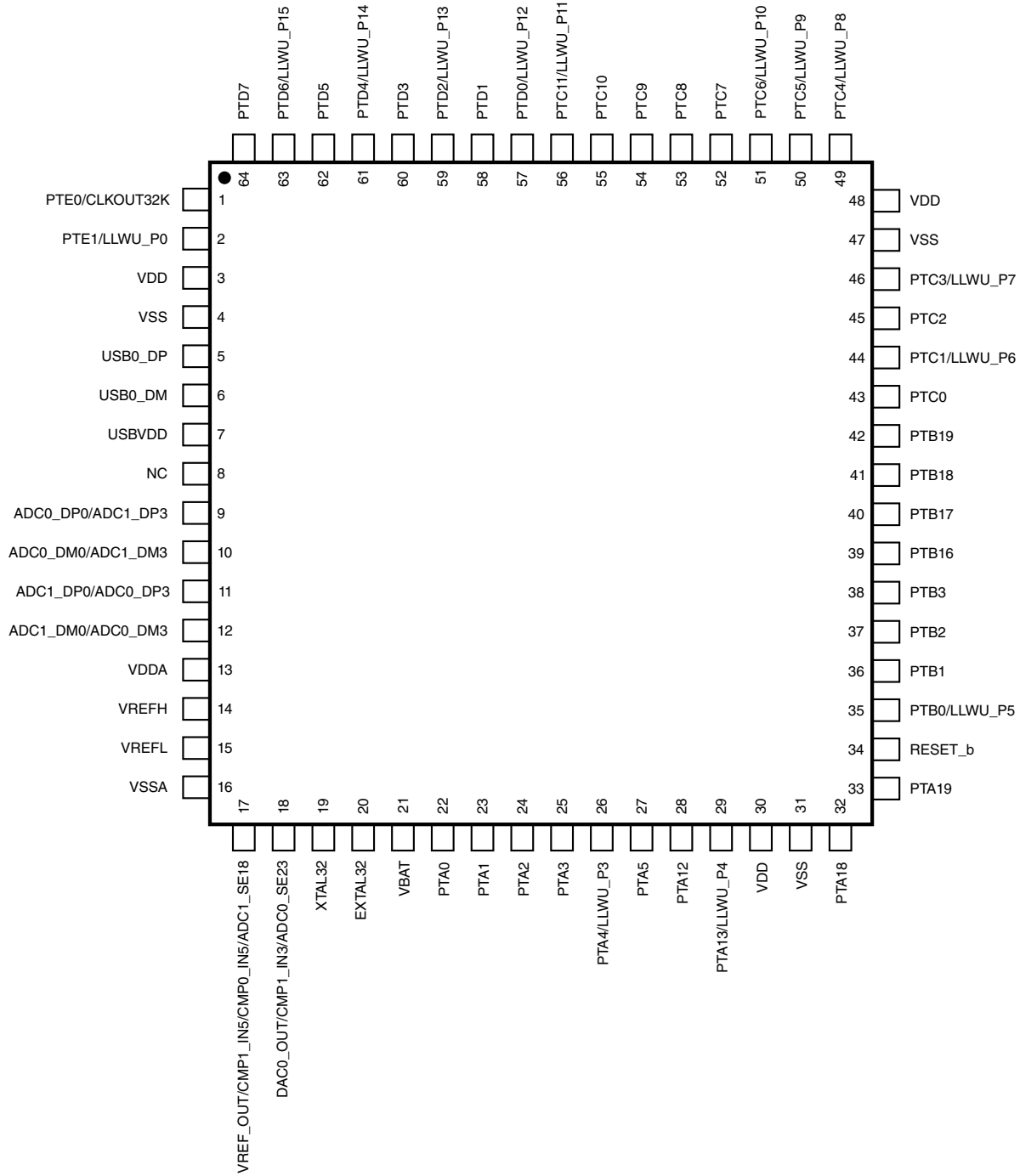


Figure 30. K22 64 LQFP Pinout Diagram (top view)

| | | | | | | | | | |
|---|--|-------------------------------------|-------------------|---------|--------------------|-------------------|-------------------|------------------|---|
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | |
| A | PTE0/ CLKOUT32K | PTD7 | PTD4/ LLWU_P14 | PTD1 | PTC11/ LLWU_P11 | PTC8 | PTC6/ LLWU_P10 | PTC5/ LLWU_P9 | A |
| B | PTE1/ LLWU_P0 | PTD6/ LLWU_P15 | PTD3 | PTC10 | PTC9 | PTC7 | PTC2 | PTC4/ LLWU_P8 | B |
| C | PTD5 | PTD2/ LLWU_P13 | PTD0/ LLWU_P12 | VSS | VDD | PTC1/ LLWU_P6 | PTB19 | PTC3/ LLWU_P7 | C |
| D | USB0_DM | NC | PTA0 | PTA1 | PTA3 | PTB18 | PTB17 | PTC0 | D |
| E | USB0_DP | USBVDD | VSS | VDD | PTA2 | PTB16 | PTB2 | PTB3 | E |
| F | ADC0_DM0/ ADC1_DM3 | ADC1_DM0/ ADC0_DM3 | VSSA | VDDA | PTA5 | PTB1 | PTB0/ LLWU_P5 | RESET_b | F |
| G | ADC0_DP0/ ADC1_DP3 | ADC1_DP0/ ADC0_DP3 | VREFL | VREFH | PTA4/ LLWU_P3 | PTA13/ LLWU_P4 | VDD | PTA19 | G |
| H | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | XTAL32 | EXTAL32 | VBAT | PTA12 | VSS | PTA18 | H |
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | |

Figure 31. K22 64 MAPBGA Pinout Diagram (transparent top view)

Pinout

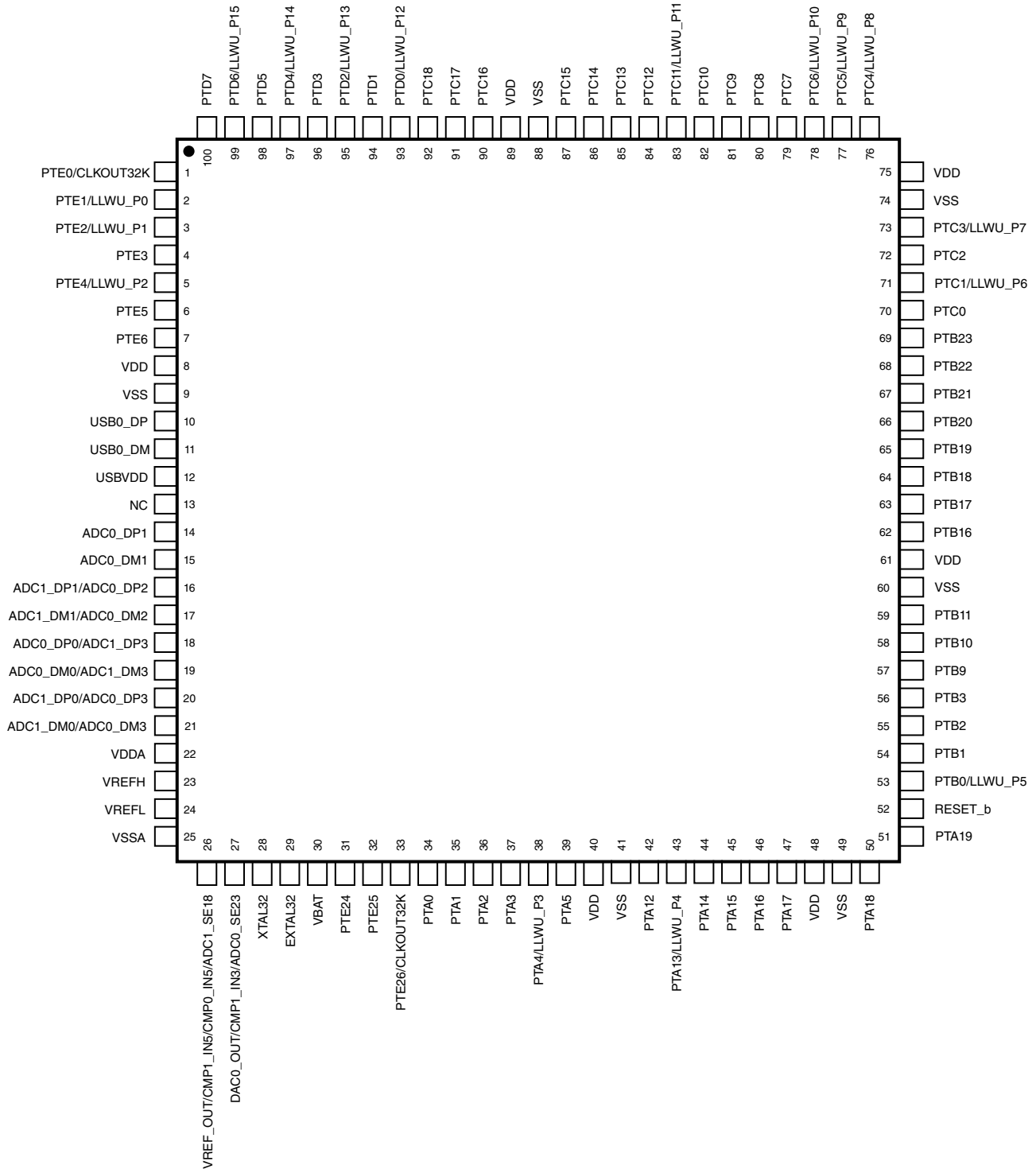


Figure 32. K22 100 LQFP Pinout Diagram (top view)

| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | |
|---|-----------------------|-----------------------|--|------------------------|-------------------------------------|---------------------|-------------------|-------------------|-------|-------|------------------|---|
| A | PTD7 | PTD5 | PTD4/ LLWU_P14 | NC | PTC14 | PTC13 | PTC8 | PTC4/ LLWU_P8 | NC | NC | NC | A |
| B | NC | PTD6/ LLWU_P15 | PTD3 | PTC18 | PTC15 | PTC12 | PTC7 | PTC3/ LLWU_P7 | PTC0 | PTB16 | NC | B |
| C | NC | NC | PTD2/ LLWU_P13 | PTC17 | PTC11/ LLWU_P11 | PTC10 | PTC6/ LLWU_P10 | PTC2 | PTB19 | PTB11 | NC | C |
| D | NC | NC | PTD1 | PTD0/ LLWU_P12 | PTC16 | PTC9 | PTC5/ LLWU_P9 | PTC1/ LLWU_P6 | PTB18 | PTB10 | PTB8 | D |
| E | NC | PTE2/ LLWU_P1 | PTE1/ LLWU_P0 | PTE0/ CLKOUT32K | VDD | VDD | VDD | PTB23 | PTB17 | PTB9 | NC | E |
| F | USB0_DP | USB0_DM | PTE6 | PTE3 | VDDA | VSSA | VSS | PTB22 | PTB21 | PTB20 | NC | F |
| G | USBVDD | NC | VSS | PTE5 | VREFH | VREFL | VSS | PTB3 | PTB2 | PTB1 | PTB0/ LLWU_P5 | G |
| H | ADC0_DP1 | ADC0_DM1 | NC | NC | PTE24 | PTE26/ CLKOUT32K | PTE4/ LLWU_P2 | PTA1 | PTA3 | PTA17 | NC | H |
| J | ADC1_DP1/ ADC0_DP2 | ADC1_DM1/ ADC0_DM2 | NC | NC | PTE25 | PTA0 | PTA2 | PTA4/ LLWU_P3 | NC | PTA16 | RESET_b | J |
| K | ADC0_DP0/ ADC1_DP3 | ADC0_DM0/ ADC1_DM3 | NC | CMP0_IN4/ ADC1_SE23 | DAC0_OUT/ CMP1_IN3/ ADC0_SE23 | VBAT | PTA5 | PTA12 | PTA14 | VSS | PTA19 | K |
| L | ADC1_DP0/ ADC0_DP3 | ADC1_DM0/ ADC0_DM3 | VREF_OUT/ CMP1_IN5/ CMP0_IN5/ ADC1_SE18 | XTAL32 | EXTAL32 | VSS | NC | PTA13/ LLWU_P4 | PTA15 | VDD | PTA18 | L |
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | |

Figure 33. K22 121 XFBGA Pinout Diagram (top view)

6 Part identification

6.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

6.2 Format

Part numbers for this device have the following format:

Q K## A M FFF R T PP CC N

6.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

| Field | Description | Values |
|-------|-----------------------------|--|
| Q | Qualification status | <ul style="list-style-type: none"> M = Fully qualified, general market flow, full reel P = Prequalification K = Fully qualified, general market flow, 100 piece reel |
| K## | Kinetis family | <ul style="list-style-type: none"> K22 |
| A | Key attribute | <ul style="list-style-type: none"> D = Cortex-M4 w/ DSP F = Cortex-M4 w/ DSP and FPU |
| M | Flash memory type | <ul style="list-style-type: none"> N = Program flash only X = Program flash and FlexMemory |
| FFF | Program flash memory size | <ul style="list-style-type: none"> 128 = 128 KB 256 = 256 KB 512 = 512 KB |
| R | Silicon revision | <ul style="list-style-type: none"> Z = Initial (Blank) = Main A = Revision after main |
| T | Temperature range (°C) | <ul style="list-style-type: none"> V = -40 to 105 C = -40 to 85 |
| PP | Package identifier | <ul style="list-style-type: none"> LH = 64 LQFP (10 mm x 10 mm) MP = 64 MAPBGA (5 mm x 5 mm) LL = 100 LQFP (14 mm x 14 mm) MC = 121 XFBGA (8 mm x 8 mm) DC = 121 XFBGA (8 mm x 8 mm x 0.5 mm) |
| CC | Maximum CPU frequency (MHz) | <ul style="list-style-type: none"> 5 = 50 MHz 7 = 72 MHz 10 = 100 MHz 12 = 120 MHz 15 = 150 MHz |
| N | Packaging type | <ul style="list-style-type: none"> R = Tape and reel |

6.4 Example

This is an example part number:

MK22FN128VDC10

6.5 121-pin XFBGA part marking

The 121-pin XFBGA package parts follow the part-marking scheme in the following table.

Table 49. 121-pin XFBGA part marking

| MK Partnumber | MK Part Marking |
|----------------|-----------------|
| MK22FN128VDC10 | M22J7VDC |

6.6 64-pin MAPBGA part marking

The 64-pin MAPBGA package parts follow the part-marking scheme in the following table.

Table 50. 64-pin MAPBGA part marking

| MK Partnumber | MK Part Marking |
|----------------|-----------------|
| MK22FN128VMP10 | M22J7V |

7 Terminology and guidelines

7.1 Definitions

Key terms are defined in the following table:

| Term | Definition |
|--------|--|
| Rating | <p>A minimum or maximum value of a technical characteristic that, if exceeded, may cause permanent chip failure:</p> <ul style="list-style-type: none"> • <i>Operating ratings</i> apply during operation of the chip. • <i>Handling ratings</i> apply when the chip is not powered. |

Table continues on the next page...

Terminology and guidelines

| Term | Definition |
|-----------------------|--|
| | NOTE: The likelihood of permanent chip failure increases rapidly as soon as a characteristic begins to exceed one of its operating ratings. |
| Operating requirement | A specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip |
| Operating behavior | A specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions |
| Typical value | <p>A specified value for a technical characteristic that:</p> <ul style="list-style-type: none"> Lies within the range of values specified by the operating behavior Is representative of that characteristic during operation when you meet the typical-value conditions or other specified conditions <p>NOTE: Typical values are provided as design guidelines and are neither tested nor guaranteed.</p> |

7.2 Examples

Operating rating:

| Symbol | Description | Min. | Max. | Unit |
|-----------------|---------------------------|------|------|------|
| V _{DD} | 1.0 V core supply voltage | -0.3 | 1.2 | V |

Operating requirement:

| Symbol | Description | Min. | Max. | Unit |
|-----------------|---------------------------|------|------|------|
| V _{DD} | 1.0 V core supply voltage | 0.9 | 1.1 | V |

Operating behavior that includes a typical value:

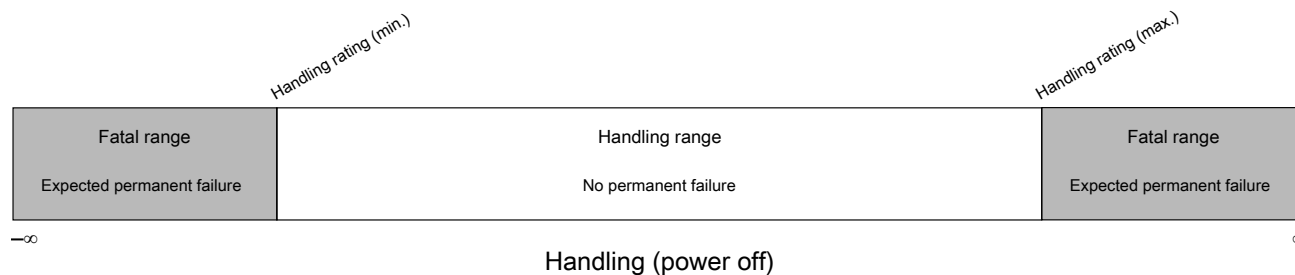
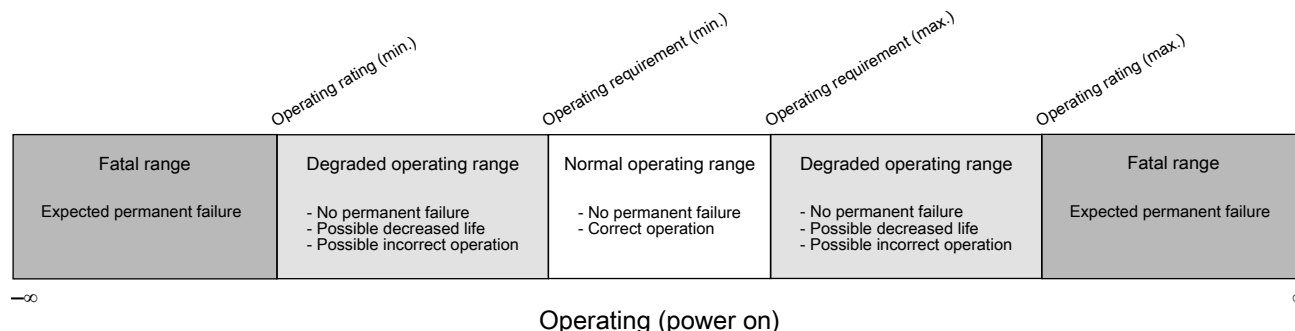
| Symbol | Description | Min. | Typ. | Max. | Unit |
|-----------------|--|------|------|------|------|
| I _{WP} | Digital I/O weak pullup/pulldown current | 10 | 70 | 130 | μA |

7.3 Typical-value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

| Symbol | Description | Value | Unit |
|-----------------|---------------------|-------|------|
| T _A | Ambient temperature | 25 | °C |
| V _{DD} | Supply voltage | 3.3 | V |

7.4 Relationship between ratings and operating requirements



7.5 Guidelines for ratings and operating requirements

Follow these guidelines for ratings and operating requirements:

- Never exceed any of the chip's ratings.
- During normal operation, don't exceed any of the chip's operating requirements.
- If you must exceed an operating requirement at times other than during normal operation (for example, during power sequencing), limit the duration as much as possible.

8 Revision History

The following table provides a revision history for this document.

Table 51. Revision History

| Rev. No. | Date | Substantial Changes |
|----------|---------|--|
| 7 | 08/2016 | <ul style="list-style-type: none"> Added Terminology and Guidelines section Updated the front matter section Added Device Revision Number Table Updated Chip Errata naming convention in Related Resource table |
| 6 | 10/2015 | <ul style="list-style-type: none"> In "Power consumption operating behaviors" section, added "Low power mode peripheral adders—typical value" table In "Thermal operating requirements" table, in footnote, corrected "$T_J = T_A + \Theta_{JA}$" to "$T_J = T_A + R_{\Theta JA}$" Updated "IRC48M specifications" table Updated "NVM program/erase timing specifications" table; updated values for $t_{hversall}$ (Erase All high-voltage time) In "Slave mode DSPI timing (limited voltage range)" table, added footnote regarding maximum frequency of operation Added new section, "Recommended connections for unused analog and digital pins" |
| 5 | 4/2015 | <ul style="list-style-type: none"> On page 1: <ul style="list-style-type: none"> In first bullet of introduction, updated power consumption data to align with the data in the "Power consumption operating behaviors" table In second bullet of introduction, added "USB FS device crystal-less functionality" Under "Communication interfaces," updated I²C bullet to indicate support for up to 1 Mbps operation Under "Operating characteristics," specified that voltage range includes flash writes In "Voltage and current operating requirements" table: <ul style="list-style-type: none"> Removed content related to positive injection Updated footnote 1 to say that all analog and I/O pins are internally clamped to V_{SS} only (not V_{SS} and V_{DD}) through ESD protection diodes. In "Power consumption operating behaviors" table: <ul style="list-style-type: none"> Added additional temperature data in power consumption table Added Max IDD values based on characterization results equivalent to mean + 3 sigma Updated "EMC radiated emissions operating behaviors" table In "Thermal operating requirements" table, added the following footnote for ambient temperature: "Maximum T_A can be exceeded only if the user ensures that T_J does not exceed maximum T_J. The simplest method to determine T_J is: $T_J = T_A + \Theta_{JA} \times$ chip power dissipation" Updated "IRC48M Specifications": <ul style="list-style-type: none"> Updated maximum values for $\Delta_{firc48m_ol_lv}$ and $\Delta_{firc48m_ol_hv}$ (full temperature) Added specifications for $\Delta_{firc48m_ol_hv}$ (-40°C to 85°C) Updated notes in "USB electrical specifications" section In "I²C timing" table, <ul style="list-style-type: none"> Added the following footnote on maximum Fast mode value for SCL Clock Frequency: "The maximum SCL Clock Frequency in Fast mode with maximum bus loading can only be achieved when using the High drive pins across the full voltage range and when using the Normal drive pins and $V_{DD} \geq 2.7$ V." Updated minimum Fast mode value for LOW period of the SCL clock to 1.25 μ Added "I²C 1 Mbps timing" table Specified that the figure, "K22F 64 LQFP Pinout Diagram" is a top view Specified that the figure, "K22F 64 MAPBGA Pinout Diagram" is a transparent top view Specified that the figure, "K22F 100 LQFP Pinout Diagram" is a top view |

Table continues on the next page...

Table 51. Revision History (continued)

| Rev. No. | Date | Substantial Changes |
|----------|--------|--|
| | | <ul style="list-style-type: none"> Removed Section 6, "Ordering parts." Corrected part marking shown in "64-pin MAPBGA part marking" table |
| 4 | 7/2014 | <p>In "Power consumption operating behaviors table":</p> <ul style="list-style-type: none"> Updated existing typical power measurements Added new typical power measurements for the following: <ul style="list-style-type: none"> IDD_HSRUN (High Speed Run mode current executing CoreMark code) IDD_RUNCO (Run mode current in Compute operation, executing CoreMark code) IDD_RUN (Run mode current in Compute operation, executing while(1) loop) IDD_VLPR (Very Low Power mode current executing CoreMark code) IDD_VLPR (Very Low Power Run mode current in Compute operation, executing while(1) loop) |
| 3 | 5/2014 | <ul style="list-style-type: none"> In "Voltage and current operating ratings" table, updated maximum digital supply current Updated "Voltage and current operating behaviors" table Updated "Power mode transition operating behaviors" table Updated "Power consumption operating behaviors" table Updated "EMC radiated emissions operating behaviors for 64 LQFP package" table Updated "Thermal attributes" table Updated "MCG specifications" table Updated "IRC48M specifications" table Updated "16-bit ADC operating conditions" table Updated "Voltage reference electrical specifications" section Added "121-pin XFBGA part marking" table Added "64-pin MAPBGA part marking" table |
| 2 | 4/2014 | <ul style="list-style-type: none"> In "Voltage and current operating requirements" table, added row for USBV_{DD} Updated "Voltage and current operating behaviors" table Updated "Thermal attributes" table Updated "IRC48M specifications" table |
| 1 | 3/2014 | Initial public release |

How to Reach Us:

Home Page:

nxp.com

Web Support:

nxp.com/support

Information in this document is provided solely to enable system and software implementers to use NXP products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits based on the information in this document. NXP reserves the right to make changes without further notice to any products herein.

NXP makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does NXP assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in NXP data sheets and/or specifications can and do vary in different applications, and actual performance may vary over time. All operating parameters, including "typicals," must be validated for each customer application by customer's technical experts. NXP does not convey any license under its patent rights nor the rights of others. NXP sells products pursuant to standard terms and conditions of sale, which can be found at the following address: nxp.com/SalesTermsandConditions.

NXP, the NXP logo, NXP SECURE CONNECTIONS FOR A SMARTER WORLD, Freescale, the Freescale logo, and Kinetis are trademarks of NXP B.V. All other product or service names are the property of their respective owners. ARM, the ARM Powered logo, and Cortex are registered trademarks of ARM Limited (or its subsidiaries) in the EU and/or elsewhere. All rights reserved.

© 2014–2016 NXP B.V.

Document Number K22P121M100SF9
Revision 7, 08/2016



Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



Телефон: 8 (812) 309-75-97 (многоканальный)

Факс: 8 (812) 320-03-32

Электронная почта: ocean@oceanchips.ru

Web: <http://oceanchips.ru/>

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, д. 2, корп. 4, лит. А